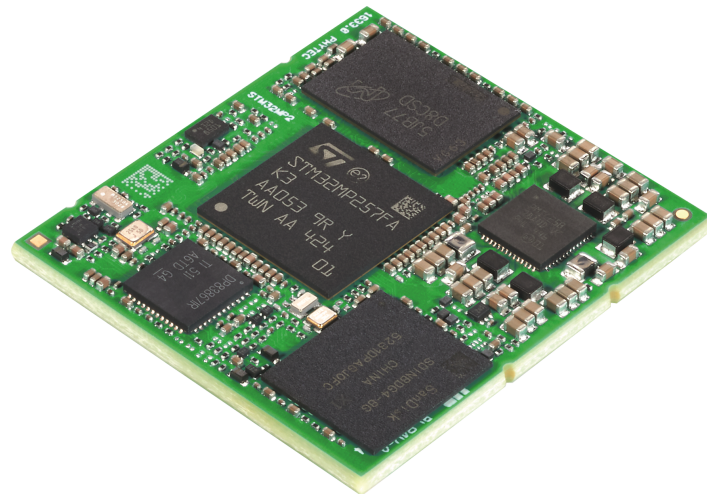




phyFLEX-STM32MP2x FPSC & Libra Development Board



A product of PHYTEC Technology Holding Company

Hardware Manual - phyFLEX-STM32MP2x FPSC/Libra Development Board (1633.0 and 1633.1/1618.2) (L-1087e.A1)	
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1 Information on this Manual

This hardware manual describes the PFL-G-04 (FPSC) System on Module, referred to as phyFLEX-STM32MP2x, and the PBA-BG-41e PBA-BG-41, referred to as Libra Development Board. This manual also specifies the phyFLEX-STM32MP2x and Libra Development Board's design and function. Precise specifications for the STMicroelectronics® STM32MP2x microcontrollers can be found in the *STM32MP2x Microcontroller Data Sheet/Reference Manual*.

There will be several changes and additions to this manual. New versions will be released in the future with no notice. Please make sure that you are using the latest version of this manual when working with your product.

1.1 Future Proof Solder Core

The PFL-G-04 System on Module, referred to as phyFLEX®-STM32MP2x FPSC, is designed according to [FPSC Gamma Feature Set Specifications \(LAN-118e.A6\)](#).

1.2 Design Considerations

The schematics shown in this hardware manual are believed to be correct. However, correctness can not be guaranteed. The schematics have been pulled from PHYTEC's designs that have been built, tested, and are known to work. The schematics have been re-formatted to fit better in this hardware manual.

Many hardware examples and suggestions are given in the following pages. Designing the phyFLEX System on Module onto a Carrier Board is generally straightforward. However, before committing to a particular active component selection when designing a carrier board, it is wise to check out the software driver support for those components. A particular device may be supported in, for example, Linux but not in Windows Embedded Compact 7. Your overall project may go smoother if you pick components that are already supported in your target OS. The premade selections for our reference designs, for example, our Single Board Computers, are typically focused on using components that are well supported under Linux.

Specific details may need to be considered when designing a customer-specific carrier board. For design information on carrier board components, please check the ***Design Considerations*** in each component section of [phyFLEX-STM32MP2x FPSC on the Libra Development Board](#). Be aware that not all components need to be considered when designing your own carrier board.

2 Preface

As a member of PHYTEC's product family, the phyFLEX® SoM can be populated with different controllers, various types of memory (RAM, NAND flash, eMMC), and many other features. This, in turn, offers increased types of functions and configurations. PHYTEC supports a variety of 8/16/32/64-bit controllers in two ways:

1. As the basis for Rapid Development Kits which serve as a reference and evaluation platform
2. As insert-ready, fully functional phyFLEX® OEM modules, which can be embedded directly into the user's peripheral hardware design.

Implementation of an OEM-able SOM subassembly as the "core" of your embedded design allows for increased focus on hardware peripherals and firmware without expending resources to "reinvent" microcontroller circuitry. Furthermore, much of the value of the phyFLEX® module lies in its layout and test.

Production-ready Board Support Packages (BSPs) and Design Services for our hardware will further reduce development time and risk and allows for increased focus on product expertise. Take advantage of PHYTEC products to shorten time-to-market, reduce development costs, and avoid substantial design issues and risks. With this new innovative, full-system solution, new ideas can be brought to market in the most timely and cost-efficient manner.

For more information go to:

<http://www.phytec.de/leistungen/entwicklungsunterstuetzung.html>

or

<http://www.phytec.eu/europe/oem-integration/evaluation-start-up.html>

Note

Assembly Options include a choice of Controller, RAM (Size/Type), Size of NAND Flash, interfaces available, vanishing, temperature range, and other features. Please contact our sales team to get more information on the ordering options available.

2.1 Declaration of Electro Magnetic Conformity of the PHYTEC phyFLEX®



PHYTEC System on Modules are designed for installation in electrical appliances or as dedicated Evaluation Boards (i.e.: for use as a test and prototype platform for hardware/software development) in laboratory environments.

Warning

PHYTEC products lacking protective enclosures are subject to damage by ESD and, therefore, must be unpacked, handled, or operated in environments in which sufficient precautionary measures have been taken with respect to ESD dangers. Only appropriately trained personnel such as qualified electricians, technicians, and engineers should handle and/or operate these products. Moreover, PHYTEC products should not be operated without protection circuitry if connections to the product's pin header rows are longer than 3 m.

PHYTEC products fulfill the norms of the European Union's Directive for Electro Magnetic Conformity in accordance with the descriptions and rules of usage indicated in this hardware manual (particularly in respect to the pin header row connectors, power connector, and serial interface to a host-PC).



Tip

Implementation of PHYTEC products into target devices, as well as user modifications and extensions of PHYTEC products, is subject to renewed establishment of conformity to and certification of Electro Magnetic Directives. Users should ensure conformity following any modifications to a product as well as the implementation of a product into target systems.

2.2 Product Change Management and Information Regarding Parts Populated on the SoM

With the purchase of a PHYTEC SoM / SBC, you will, in addition to our hardware and software possibilities, receive free obsolescence maintenance service for the hardware we provide. Our Product Change Management (PCM) team of developers is continuously processing all incoming Product Change Notifications (PCNs) from vendors and distributors concerning parts that are used in our products. Possible impacts on the functionality of our products due to changes in functionality or obsolescence of certain parts are constantly being evaluated in order to take the right measures either in purchasing decisions or within our hardware/software design.

Our general philosophy here is: **We will never discontinue a product as long as there is a demand for it.**

To fulfill this, we have established a set of methods to fulfill our philosophy:

Avoidance strategies:

- Avoid changes by evaluating the longevity of parts during the design-in phase.
- Ensure the availability of equivalent second source parts.
- Stay in close contact with part vendors to keep up with roadmap strategies.

Change management in the rare event of an obsolete and non-replaceable part:

- Ensure long-term availability by stocking parts through last-time buy management according to product forecasts.
- Offer long-term frame contracts to customers.

Change management in cases of functional changes:

- Avoid impacts on product functionality by choosing equivalent replacement parts.
- Avoid impacts on product functionality by compensating for changes through hardware redesign or backward-compatible software maintenance.
- Provide early change notifications concerning functional, relevant changes to our products.

We refrain from providing detailed part-specific information within this manual, which can be subject to continuous changes, due to part maintenance for our products.

In order to receive reliable, up-to-date, and detailed information concerning parts used for our product, please contact our support team through the contact information given within this manual.

2.3 PHYTEC Documentation

PHYTEC will provide a variety of hardware and software documentation for all of our products. This includes any or all of the following:

- **Quickstart Guide:** A short guide on how to set up and boot a phyFLEX board along with brief information on building a Board Support Package (BSP), the device tree, and accessing peripherals.
- **Hardware Manual:** A detailed description of the System on Module (SoM) and accompanying carrier board.

- **Yocto Guide:** A comprehensive guide for the Yocto version the phyFLEX uses. This guide contains an overview of Yocto; introducing, installing, and customizing the PHYTEC BSP; how to work with programs like Poky and Bitbake; and much more.
- **BSP Manual:** A manual specific to the BSP version of the phyFLEX. Information such as how to build the BSP, booting, updating software, device tree, and accessing peripherals can be found here.
- **Development Environment Guide:** This guide shows how to work with the Virtual Machine (VM) Host PHYTEC has developed and prepared to run various Development Environments. There are detailed step-by-step instructions for Eclipse and Qt Creator, which are included in the VM. There are instructions for running demo projects for these programs on a phyFLEX product as well. Information on how to build a Linux host PC yourself is also a part of this guide.
- **Pin Muxing Table:** phyFLEX SoMs have an accompanying pin table (in Excel format). This table will show the complete default signal path, from processor to carrier board. The default device tree muxing option will also be included. This gives a developer all the information needed in one location to make muxing changes and design options when developing a specialized carrier board or adapting a PHYTEC phyFLEX SOM to an application.

On top of these standard manuals and guides, PHYTEC will also provide Product Change Notifications, Application Notes, and Technical Notes. These will be done on a case-by-case basis. Most of the documentation can be found on the applicable download page of our products.



Tip

After finishing the Quickstart Guide, we recommend working through the Development Environment Guide. This will give you a comprehensive overview of the features and functions of both the SoM and carrier board.

These manuals and more can be found in the download section of the [phyFLEX-STM32MP2x Product page](#).

3 Conversions, Abbreviations, and Acronyms

✓ Tip

Due to part maintenance for our products (which are subject to continuous changes), we refrain from providing detailed, part-specific information within this manual. Please read the section [Product Change Management and Information Regarding Parts Populated on the SOM / SBC](#) within the [Preface](#) for more information.

✓ Tip

The BSP delivered with the phyFLEX-STM32MP2x usually includes drivers and/or software for controlling all components, such as interfaces, memory, etc. Programming close to hardware at the register level is not necessary in most cases. For this reason, this manual does not contain detailed descriptions of the controller's registers or information relevant to software development. Please refer to the STM32MP2x Reference Manual, if any information not found in this manual is needed to connect customer-designed applications.

3.1 Conventions

The conventions used in this manual are as follows:

- Signals that are preceded by an "n", "/", or "#" character (e.g., nRD, /RD, or #RD), or that have a dash on top of the signal name (e.g., RD), are designated as active low signals. That is, their active state is when they are driven low or are driving low.
- A "0" indicates a logic zero or low-level signal, while a "1" represents a logic one or high-level signal.
- The hex numbers given for addresses of I2C devices always represent the 7 MSB of the address byte. The correct value of the LSB, which depends on the desired command (read (1) or write (0)), must be added to get the complete address byte. For example, if the given address in this manual is 0x41 =>, the complete address byte = 0x83 to read from the device and 0x82 to write to the device
- Tables that describe all settings show the default position in **bold, blue text**.

3.2 Types of Signals

Different types of signals are brought out at the phyFLEX-Connector. The following table lists the abbreviations used to specify the type of signal.

TABLE 1: Signal Types

Signal Type	Description	Abbreviation
Power In	Supply voltage input	PWR_I
Power Out	Supply voltage output	PWR_O
Ref-Voltage	Reference voltage output	REF_O
Input	Digital input	I

Signal Type	Description	Abbreviation
Output	Digital output	O
IO	Bidirectional input/push-pull output	I/O
Input/OD-Output	Input / open-drain output requires an external pull-up	I/OD
OC-Bidir PU	Open collector input/output with pull-up	OC-BI-PU
OC-Output	Open collector output without a pull-up requires an external pull-up	OC
OD-Bidir PU	Open-drain input/output with pull-up	OD-BI-PU
OD-Output	Open-drain output without a pull-up requires an external pull-up	OD
5 V Input PD	5 V tolerant input with pull-down	5V-PD
Analog input	Analog input	A
USB IO	Differential line pairs 90 Ω USB level bidirectional input/output	USB_I/O
ETHERNET Input	Differential line pairs 100 Ω Ethernet level input	ETH_I
ETHERNET Output	Differential line pairs 100 Ω Ethernet level output	ETH_O
ETHERNET IO	Differential line pairs 100 Ω Ethernet level bidirectional input/output	ETH_I/O
PCIe Input	Differential line pairs 100 Ω PCIe level input	PCIe_I
PCIe Output	Differential line pairs 100 Ω PCIe level output	PCIe_O
PCIe IO	Differential line pairs 100 Ω PCIe level input or output	PCIe_I/O
HDMI Input	Differential line pairs 100 Ω HDMI level input	HDMI_I
HDMI Output	Differential line pairs 100 Ω HDMI level output	HDMI_O
MIPI CSI-2 Input	Differential line pairs 100 Ω MIPI CSI-2 level input	CSI2_I
MIPI DSI-2 Output	Differential line pairs 100 Ω MIPI DSI-2 level output	DSI2_O
CAN FD IO	Differential line pairs 120 Ω CAN FD level bidirectional input/output	CAN_I/O

3.3 Abbreviations and Acronyms

Many acronyms and abbreviations are used throughout this manual. Use the following table to navigate unfamiliar terms used in this document.

TABLE 2: Abbreviations and Acronyms Used in this Manual

Abbreviation	Definition
BGA	Ball Grid Array
BSP	Board Support Package (software delivered with the Development Kit, including an operating system (Windows or Linux) preinstalled on the module and development tools)
CB	Carrier board; used in reference to the phyFLEX development kit carrier board
EMI	Electromagnetic Interference
GPI	General-purpose input
GPIO	General-purpose input and output
GPO	General-purpose output
FPSC	Future Proofed Soldering Core
IRAM	Internal RAM: the internal static RAM on the TI® Semiconductor STM32MP2x microcontroller
J	Solder jumpers; these types of jumpers require solder equipment to remove and place
JP	Solderless jumpers; these types of jumpers can be removed and placed by hand with no special tools
OEM	Original Equipment Manufacturers
PCB	Printed circuit board
PCM	Product Change Management
PCN	Product Change Notification
PMIC	Power management IC

Abbreviation	Definition
RTC	Real-time clock
SBC	Single Board Computer
SMT	Surface mount technology
SOM	System on Module; used in reference to the PFL-G-04 /phyFLEX [®] -STM32MP2x module
Sx	User button Sx (e.g., S1, S2, etc.) used in reference to the available user buttons, or DIP-Switches on the carrier board
Sx_y	Switch y of DIP-Switch Sx; used in reference to the DIP-Switch on the carrier board
VM	Virtual Machine

4 phyFLEX-STM32MP2x FPSC Introduction

The phyFLEX-STM32MP2x belongs to PHYTEC's phyFLEX System on Module family. The phyFLEX SOMs represent the continuous development of the PHYTEC System on Module technology. Like its mini-, micro-, and nanoMODUL predecessors, phyFLEX boards integrate all core elements of a microcontroller system on a subminiature board and are designed in a manner that ensures their easy expansion and embedding in peripheral hardware developments.

Independent research indicates approximately 70 % of all EMI (Electromagnetic interference) problems are caused by insufficient supply voltage grounding of electronic components in high-frequency environments. The phyFLEX board design features an increased pin package, which allows for the dedication of approximately 20 % of all connector pins on the phyFLEX boards to Ground. This improves EMI and EMC characteristics and makes it easier to design complex applications meeting EMI and EMC guidelines using phyFLEX boards, even in high-noise environments.

phyFLEX boards achieve their small size through modern SMT and multi-layer design. Due to the complexity of our modules, 0201-packaged SMT components and laser-drilled microvias are used on the boards, providing phyFLEX users with access to this cutting-edge miniaturization technology for integration into their own design.

The phyFLEX-STM32MP2x is a subminiature (37 mm x 40 mm) insert-ready System on Module populated with the STMicroelectronics® STM32MP2x microcontroller. Its universal design enables it to be inserted into a wide range of embedded applications. All controller signals and ports extend from the controller to surface mount technology (**FPSC FTGA 1.27 mm grid**) connectors, aligning four sides of the board, allowing it to be soldered into any target application like a "big chip".

The descriptions in this manual are based on the STMicroelectronics® STM32MP2x. Descriptions of compatible microcontroller derivative functions are not included, as such functions are not relevant for the basic functioning of the phyFLEX-STM32MP2x.

4.1 phyFLEX-STM32MP2x FPSC Features

The phyFLEX-STM32MP2x FPSC offers the following features:

- Insert-ready, sub-miniature (37 mm x 40 mm) System on Module (SOM) subassembly in low EMI design, achieved through advanced SMD technology
- Mounted using FTGA Direct Solder Connector (FPSC FTGA)
- Populated with the STMicroelectronics® STM32MP257F microcontroller (VFBGA424 14x14, packaging)
- 1.5 GHz (A35), 400 MHz (M33), 200 MHz (M0+)
- Boot from different memory devices (eMMC Flash standard)
- Single supply voltage of +5 V with on-board power management
- IO voltage between **1.8 V (FPSC standard)** and 3.3 V (factory assembly option)
- All controller-required supplies are generated on-board using sophisticated on-board Power Management
- Improved interference safety achieved through multi-layer PCB technology and dedicated ground pins
- up to 4 GB LPDDR4 RAM (32-bit) ^[1]
- up to 256 GB ^[1] on-board eMMC
- up to 32 kB ^[1] I²C-EEPROM
- 1x USB 2.0/3.0 DRD SuperSpeed up to 5 Gbit/s
- 1x USB 2.0 Host
- 1x PCI Express 1x1 interface (5 Gbit, shared with USB3.0 SuperSpeed)
- 3x 1Gbit Ethernet interfaces (TSN, IEEE 1588v2, either one of them with Ethernet PHY on the phyFLEX-STM32MP2x; the other two as RGMII Signals)
- 1x integrated TSN Ethernet Switch.
- 4x I²C interfaces (up to 8x I2C)
- 3x SPI interfaces (up to 8x SPI)

- 1x QSPI interface (up to 2x OSPI)
- 3x UART interfaces (up to 9x U(S)ART)
- 3x CAN-FD interfaces (1x TTCAN)
- 1x MIPI DSI-2 display interface (with internal 3D-GPU)
- 2x LVDS display interface (with internal 3D-GPU)
- 1x MIPI-CSI camera interface
- 1x 4-bit SDIO interface (with 1.8 V and 3.3 V IO switch and supply switch for μ SD Cards)
- 1x 4-bit SDIO interface
- 1x stereo audio interface SAI (up to 4x SAI/I2S/PDM/SPDIF)
- 4x PWM outputs (up to x)
- 4x analog inputs to 3x 12-bit ADCs 5 MSPS (up to 21 input channels)
- CPU internal secure RTC and Temperature sensor
- 1x external RTC module with extremely low power consumption
- 1x temperature sensor to monitor the board's temperature profile
- Available for different temperature grades (see [Product Temperature Grades](#))

Info

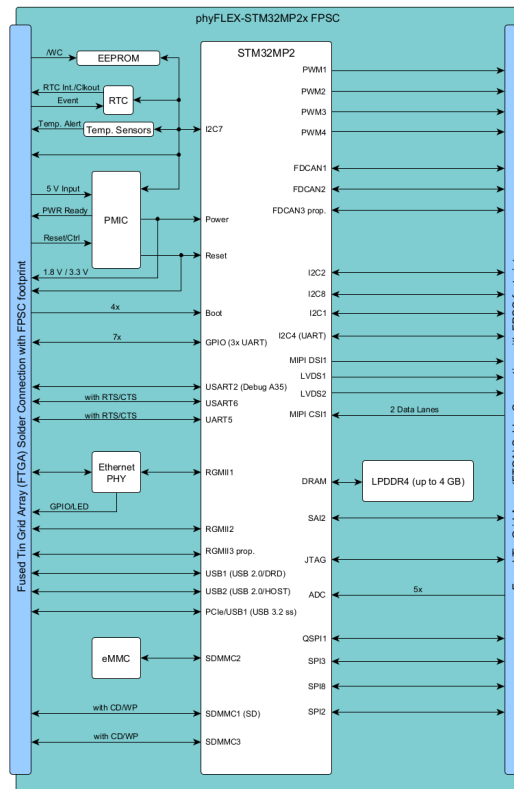
[1] The maximum memory size is listed as of the printing of this manual.

Please contact PHYTEC for more information about additional or new module configurations available.

Due to multiplexing, not all interfaces may be fully available.

4.2 phyFLEX-STM32MP2x FPSC Block Diagram

FIGURE 1: phyFLEX-STM32MP2x Block Diagram



4.3 phyFLEX-STM32MP2x FPSC Component Placement

FIGURE 2: phyFLEX-STM32MP2x Component Placement (1633.0 Top View)

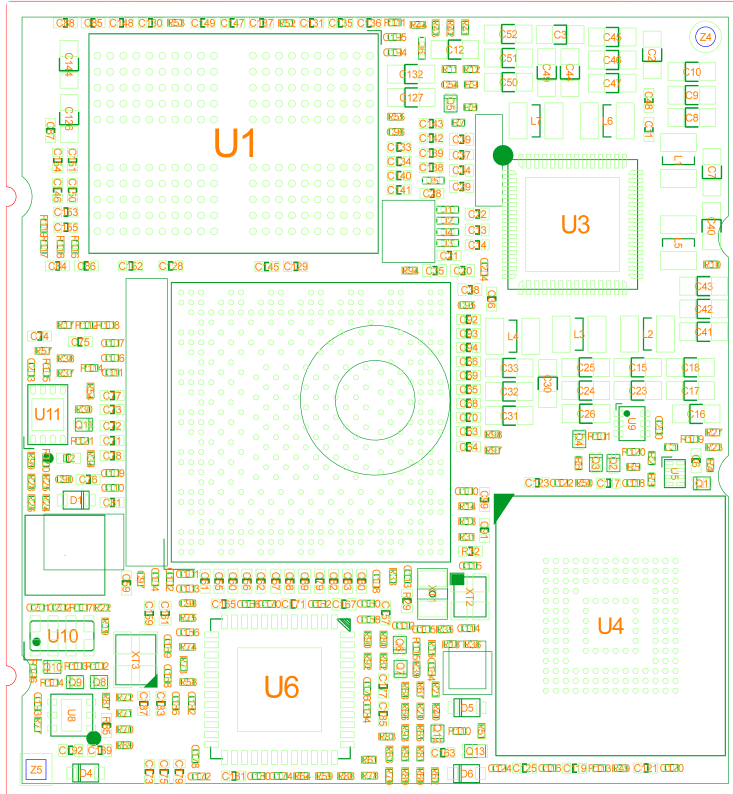
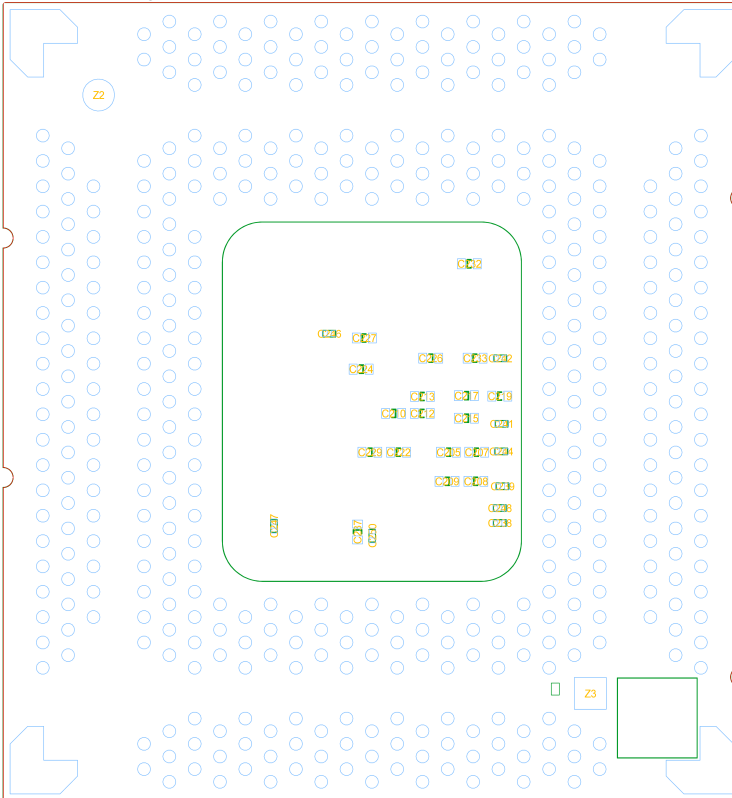


FIGURE 3: phyFLEX-STM32MP2x Component Placement (1633.0 Bottom View)



⚠ The capacitors shown on the bottom layer may be removed after the evaluation phase. Contact [your PHYTEC representative](#) for more information.

4.4 phyFLEX-STM32MP2x FPSC Minimum Operating Requirements

⊗ Warning

We recommend connecting all available VCC_IN (+5.0 V) input contacts to the power supply system on a custom carrier board housing the phyFLEX-STM32MP2x FPSC. In addition, proper implementation of the phyFLEX-STM32MP2x FPSC module into a target application also requires connecting all GND contacts. Refer to [Power](#) for more information.

Before the phyFLEX-STM32MP2x FPSC can be used, please make sure the host system meets the minimum operating requirements. These include:

- The stable and clean input power supply of 5.0 V with low ESR bulk capacitors (e.g. 2x 47 μ F/16 V MLCC) paired with some HF blocking capacitors (e.g. 100 nF MLCC) connected to the input pins as near as possible ([phyFLEX-STM32MP2x FPSC Power Consumption](#))
- Supply voltage for externally connected peripherals should be controlled by signal X_nPWRREADY to avoid reverse currents ([External Logic IO Supply Voltage](#))
- If external peripherals need a longer reset delay, hold the reset signal X_nRESET_IN as long low as needed ([Reset](#))

- Desired boot configuration - "Boot from on-board eMMC" must be set by connecting configuration resistors to the BOOT_MODE[4:1] configuration signals on the baseboard ([System Boot Configuration](#))
- To back up the on-board I2C-RTC, connect a buffer voltage source to input pin X_RTC_VBACKUP ([Backup Power \(X_RTC_VBACKUP\), RTC](#))

5 Pin Description

⊗ Warning

Module connections **must** not exceed their expressed maximum voltage or current. Maximum signal input values are indicated in the corresponding controller manuals/datasheets. As damage from improper connections varies according to use and application, the user must take appropriate safety measures to ensure that the module connections are protected from overloading through connected peripherals.

All controller signals extend to the FPSC footprint. These contacts line four sides of the module (referred to as the FPSC footprint). This enables phyFLEX-STM32MP2x to be plugged into any target application like a "big chip".

PHYTEC provides a complete pinout table for the phyFLEX-STM32MP2x Connector (X1). This table contains a complete signal path for the phyFLEX-STM32MP2x and the Libra Development Board, including signal names, pin muxing paths, and descriptions specific to each pin. It also provides the appropriate voltage domain, signal type (ST), and a functional grouping of the signals. The signal type also includes information about the signal direction. A table describing the signal types can be found with the [phyFLEX-STM32MP2x Pinout Table](#).

⊗ Warning

- The STMicroelectronics® STM32MP2x is a multi-voltage-operated microcontroller and, as such, special attention should be paid to the interface voltage levels to avoid unintentional damage to the microcontroller and other on-board components. Please refer to the *STMicroelectronics STM32MP2x Reference Manual* for details on the functions and features of controller signals and port pins.
- As some of the signals that are brought out on the phyFLEX-Connector are used to configure the boot mode for specific boot options, please make sure that these signals are not driven by any device on the baseboard during reset. The signals that may affect the boot configuration are shown in [phyFLEX-Connector Boot Configuration Pins](#).
- It is necessary to avoid voltages at the IO pins of the phyFLEX-STM32MP2x FPSC, which are sourced from the supply voltage of peripheral devices attached to the SOM during power-up or power-down. These voltages can cause a current flow into the controller, especially if peripheral devices attached to the interfaces of the STM32MP2x are supposed to be powered while the phyFLEX-STM32MP2x FPSC is in suspend mode or turned off. To avoid this, bus switches have their output enabled to the SOM controlled by the X_nPWRREADY signal (see [Supply Voltage for External Logic](#)).

⊗ Pin Muxing Warning

If pin settings are changed from the PHYTEC standard configuration, make sure that the settings of the pull resistors are adjusted accordingly. Never rely on the SoC-internal pull resistor.

6 Jumpers

The phyFLEX-STM32MP2x FPSC (PFL-G-04) has a few jumpers, which are shown in the picture below:

 **Warning**

Due to the small footprint of the solder jumpers (J), PHYTEC does not recommend manual jumper modifications. This may also render the warranty invalid. Contact our sales team if you need jumper configurations different from the default configuration.

TABLE 3: phyFLEX-STM32MP2x FPSC Jumpers

Jumper	Default	default Function / Description	Alternative	Section
R41	nm	Bootmode 1 CPU int. PD	Bootmode 1 PU	bootmode
R42	nm	Bootmode 1 CPU int. PD	Bootmode 2 PU	bootmode
R43	nm	Bootmode 1 CPU int. PD	Bootmode 3 PU	bootmode
R44	nm	Bootmode 1 CPU int. PD	Bootmode 4 PU	bootmode
R112/R108	0R/nm alternative: nm/0R	X_PZ5 used as (GPIO) X_PCIE_CLKREQN on phyFLEX connector AC16 and PA7 ETH3_TXD1 used as ETH3_TXD1 on phyFLEX connector AJ34 In this configuration, the RGMII (ETH3) complete signal set is available on phyFlexReserved Pins Refer to table FPSC Reserved Target-specific Proprietary Signals	X_PCIE_CLKREQN/ETH3_TXD1/ PA7 used as X_PCIE_CLKREQN on phyFLEX connector AC16	PCIE / FPSC Reserved

Jumper	Default	default Function / Description	Alternative	Section
R116 (relates to R118)	nm	X_SAI2_MCLK_A/PF10 not available on phyFLEX connector AJ32 PF10 is free to use for ADC4 on the phyFLEX connector U14 In this config, a 19.2MHz oscillator on the baseboard must be used to provide the SAI clock to the audio device	if populated X_SAI2_MCLK_A/PF10 available on phyFLEX connector AJ32 ADC4 on the phyFLEX connector U14 can not be used	SAI / ADC(4)
R117 (relates to R119)	OR	X_ADC1_INP16/ SAI2_SCK_B / PF3 available on on phyFLEX connector AG27	X_ADC1_INP16/ SAI2_SCK_B / PF3 not available on phyFLEX connector AG28	SAI / ADC(5)
R118 (relates to R116)	OR	X_ADC3_INP2/PF10 available on on phyFLEX connector U14 (ADC4)	X_ADC3_INP2/PF10 not available on phyFLEX connector U14 (ADC4)	SAI / ADC(4)

Jumper	Default	default Function / Description	Alternative	Section
R119 (relates to R117)	0R	X_ADC1_INP16/PF3 available on on phyFLEX connector V15 (ADC5)	X_ADC1_INP16/PF3 not available on on phyFLEX connector V15 (ADC5)	SAI / ADC(5)
J1	1+2	COMBOPHY_RX1N = X_PCIE_RXN_N	COMBOPHY_RX1N = X_USB1_RX_N	PCIe-1-Lane-Bus / RX 5GBit USB3 super speed
J2	1+2	COMBOPHY_RX1P = X_PCIE_RXN_P	COMBOPHY_RX1P = X_USB1_RX_P	PCIe-1-Lane-Bus / RX 5GBit USB3 super speed
J3	1+2	COMBOPHY_TX1P = X_PCIE_TXN_P	COMBOPHY_TX1P = X_USB1_TX_P	PCIe-1-Lane-Bus / TX 5GBit USB3 super speed
J4	1+2	COMBOPHY_TX1N = X_PCIE_TXN_N	COMBOPHY_TX1N = X_USB1_TX_N	PCIe-1-Lane-Bus / TX 5GBit USB3 super speed
J5	1+2	Supply for LDO56_IN = VDD_3V3 (PMIC BUCK7)	Supply for LDO56_IN = VIN do not change	PMIC
J6	1+2	Supply for VDD1_DDR = VDD1_DDR (PMIC LDO3)	Supply for VDD1_DDR = 1V8 (PMIC BUCK5) do not change	PMIC

Information on jumpers for the Libra Development Board can be found in [Jumpers](#).

7 Power

The phyFLEX-STM32MP2x FPSC operates off a single power supply voltage. The following section discusses the primary power pins on the phyFLEX STM32MP2x FPSC Connector X1 in detail.

7.1 Primary System Power (VIN)

The phyFLEX-STM32MP2x FPSC is powered by a primary voltage supply with a nominal value of +5.0 V. On-board switching regulators generate the voltage supplies required by the STM32MP2x MCU and on-board components from the primary 5.0 V supplied to the SOM.

For proper operation, the phyFLEX-STM32MP2x FPSC must be supplied with a voltage source of 4.75 ... 5.25 V with a maximum power consumption of a 1.5 A load at the VIN pins on the phyFLEX.

TABLE 4: phyFLEX-STM32MP2x FPSC Primary System Power Pinout

FPSC Contact	FPSC Signal	SOM Signal Name	Signal Type	Description
L24, M25, N24, L22, N22, M21, N20, P21	VCC_IN1	VIN	PWR_IN	5 V ± 5% Power supply input of the module.
AB13,AB23,AB59,AB69,AD13,AD23,AD59,AD69,AF13,AF23,AF59,AF69,AH13,AH23,AH27,AH31,AH35,AH39,AH43,AH47,AH51,AH55,AH59,AH69,AM23,AM27,AM31,AM35,AM39,AM43,AM47,AM51,AM55,AM59,H23,H27,H31,H35,H39,H43,H47,H51,H55,H59,M13,M23,M27,M31,M35,M39,M43,M47,M51,M55,M59,M69,P13,P23,P59,P69,T13,T23,T59,T69,V13,V23,V59,V69,Y13,Y23,Y59,Y69,	0V GND	GND	GND	Power and signal ground reference.
1, 2, 3, 4 (Corner GND)	0V GND	GND	GND	Mechanical fixing, power, and signal ground reference.

Please refer to the section [Pin Description](#) for information on additional GND Pins located at the phyFLEX-STM32MP2x Connector X1.

For information on various power consumption scenarios that PHYTEC has run, go to [phyFLEX-STM32MP2x FPSC Power Consumption](#).

Warning

As a general design rule, PHYTEC recommends connecting all GND pins to neighboring signals that are being used in the application circuitry. For maximum EMI performance, all GND pins should be connected to a solid ground plane. Additionally, take care of a solid, low impedance connection of the power supply line to avoid voltage drop. It is recommended to place a couple of bulk capacitors as near as possible to the phyFLEX's system power input (VCC_IN) to compensate for the trace inductance.

7.2 Power Management IC (PMIC) (U1)

The phyFLEX-STM32MP2x FPSC provides an on-board Power Management IC (PMIC) at position U3 and a secondary component U8 to provide different voltages required by the microcontroller and the on-board components. The PMIC supports low-power modes and regulator supervision. It is connected to the STM32MP2x via the on-board I²C bus I2C7 (I2C7_SDA/PD14 and I2C7_SCL/PD15). The I²C address of the PMIC U1 is 0x33.

TABLE 5: I2C Interfaces for PMIC

I2C Interfaces for PMIC (addr. 0x33)
I2C7_SDA/PD14
I2C7_SCL/PD15

7.3 Power Domains

External voltages to supply the board:

- VCC_IN 5.0 V main supply voltage (4.75 .. 5.25 V / max. 1.5A)
- VCC_RTC backup supply voltage for the on-board I2C-Bus RTC U11 (RV-3028-C7) [Preferred](#)

7.4 External Logic IO Supply Voltage

The voltage level of the phyFLEX's logic interface circuitry is **VDD_IO=1.8 V (FPSC standard)** (VDD_IO = 3.3 only with factory assembly option available on request).

To follow the power-up and power-down sequencing mandatory for the STM32MP2x, external devices connected to the phyFLEX interface circuitry have to be supplied by an external power supply, which is controlled by the output signal X_nPWRREADY (OD driver), which is brought out at pin X1-U22. X_nPWRREADY should control the external supply voltage, which is used to supply the external interface circuitry connected to the phyFLEX's interfaces. X_nPWRREADY switches to GND to start the external voltage supply or to switch over a power switch. If the on-board interface voltage switches off, X_nPWRREADY is released to high impedance. To raise the signal, an external pull-up resistor (eg, 4.7 kΩ) is needed. It can be connected to voltage levels up to **12 V**, depending on the external power supply control signal requirement. The use of X_nPWRREADY ensures that external components are only

supplied when the supply voltages of the STM32MP2x are stable and avoids undefined return currents while the system is powered down.

TABLE 6: phyFLEX-STM32MP2xFPSC External Logic IO Supply Voltage Pinout

FPSC Contact	FPSC Signal Mandatory Optional Specialized	SOM Signal Name	SOM Voltage Domain	Signal Level	Signal Type	Description
U22	nPWRREADY_OUT	X_nPWRREADY	-	abs. max 12 V	OD_OUT	Needs an external PU-Resistor (abs. max. 12 V). Use it to control the power sequencing of your baseboard.

 **Warning**

Monitoring the externally generated power supply voltages by a voltage supervisor is strongly recommended.

7.5 Backup Power (X_RTC_VBACKUP)

To back up the on-board I2C-Bus RTC U10 (RV-3028-C7), an external voltage source must be added at Pin X1-AA22 (X_RTC_VBACKUP). The RTC has an extremely low backup current consumption of only 40 nA (@3 V).

TABLE 7: phyFLEX-STM32MP2x FPSC Backup Power Pinout

FPSC Contact	FPSC Signal Mandatory Optional Specialized	SOM Signal Name	SOM Voltage Domain	Signal Level	Signal Type	Description
AA22	VCC_RTC	X_RTC_VBACKUP	-	nom. 3.3 V (max. range 1.1 V to 5.5 V)	PWR_IN	Connect a gold cap or a battery here. If a battery is used, make sure that the RTC trickle charger is deactivated!

7.6 Manual Power Switch (ON/OFF)

The FPSC Signal X_OnOff (Pin X1-R20) is used to manually switch the power of the SOM . It is directly connected to the PMICs STPMIC25 PONKEYn Input. The X_OnOff signal can be left unconnected if not used. It has an internal pull-up resistor against VIN.

The PONKEYn signal is intended to be connected via a push-button to GND at the application level. Please refer to the PMIC STPMIC25B datasheet for more information on the PONKEYn Input Pin.

TABLE 8: phyFLEX-STM32MP2x FPSC Manual Power Switch Pinout

FPSC Contact	FPSC Signal Mandatory Optional Specialized	SOM Signal Name	SOM Voltage Domain	Signal Level	Signal Type	Description
R20	ON/OFF	X_PMIC_PONKEY	VIN	5 V ± 5%	OD_IN	Wake up the Processor. Intended to connect a push-button or an open collector/drain driver.

8 Reset

The X_nRESET_IN signal (Pin X1-Y21) has a 10 kΩ pull-up to VDD_IO and is directly connected to the PMIC and CPUs (nRST) Reset input. The phyFLEX-Connector is designated as a "cold reset" input.

- X_nRESET_IN will perform a power cycle of the PMIC, including the SoC. An expanded low-level time after a recognized falling edge will only hold the SoC and PMIC in reset.

This input can be used for a mechanical reset switch button.

X_nRESET_OUT Signal (Pin X1-R22) is an OD Output driven by X_nRESET_IN (nRST) and is used as a global system reset output

TABLE 9: phyFLEX-STM32MP2x FPSC Reset Pinout

FPSC Contact	FPSC Signal Mandatory Optional Specialized	SOM Signal Name	SOM Voltage Domain	Signal Level	Signal Type	Description
Y21	nRESET_IN	X_nRESET_IN	VDD_IO	1.8 V / 3.3 V	OD_IN	X_nRESET_IN acts as a "cold reset" input. Driving a falling edge on X_nRESET_IN to low (has 10 kΩ pull-up to VDD_IO=1.8V supplied will restart the system, performing a complete power cycle of the SOM. This input can be used for a mechanical reset switch button.
R22	nRESET_OUT	X_nRESET_OUT	VDD_IO	1.8 V / 3.3 V	OD_OUT	Connect it to the reset input of your baseboard peripherals. This OD output pin is driven by CPU/PMIC nRST and X_nRESET_IN pin (nRST and X_nRESET_IN are internally connected)

9 System Boot Configuration

Most features of the STM32MP2x microcontroller are configured and/or programmed during the initialization routine. Other features that impact program execution must be configured prior to initialization via pin termination.

The system start-up configuration includes:

- Boot mode selection
- Boot device selection
- Boot device configuration

The internal ROM code is the first code executed during the initialization process of the STM32MP2x after POR. The ROM code detects the boot mode by using the boot mode pins (BOOT[3:0]), while the boot device is selected and configured by determining the state of input pins (X_BOOT_MODE[4:1]).

9.1 Boot Mode Selection

The boot mode of the STM32MP2x microcontroller is determined by the configuration of four boot mode inputs BOOT_MODE[4:1] during the reset cycle of the operating system. These inputs are brought out at the phyFLEX processor pins BOOT_MODE[4:1] ((X1-P25, X1-R24, X1-T25, X1-U24). [phyFLEX-STM32MP2x Boot Modes](#) shows the possible settings of pins BOOT_MODE[4:1] and the resulting boot configuration of the BOOT_MODE[4:1] ((X1-P25, X1-R2.

TABLE 10: phyFLEX-STM32MP2x FPSC Boot Modes

Bootmode	BOOT_MODE4	BOOT_MODE3	BOOT_MODE2	BOOT_MODE1	Primary Boot Source	Remarks
0	0	0	0	0	UART / USB DFU	
1	0	0	0	1	SD-Card SDMMC1	
2	0	0	1	0	onboard eMMC (SDMMC2)	
3	0	0	1	1	Development	
4	0	1	0	0	Serial NOR	Serial NOR memory not available on the module

The boot configuration settings must be set by connecting configuration resistors to the BOOT_MODE[4:1] configuration signals on the baseboard.

The pull-up/down resistors must be supplied by the right voltage level (default VDD_IO=1.8/3.3 V, see section [External Logic IO Supply Voltage](#)).

The BOOT_MODE is initialized by sampling the BOOT_MODE inputs on the rising edge of the X_nRESET_IN (nRST) signal.

TABLE 11: phyFLEX-STM32MP2x FPSC Boot Configuration Pins

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name	SOM Voltage Domain	Signal Level	Signal Type	Description
P25	BOOT_MODE1	X_BOOT0	VDD_IO	1.8 V / 3.3 V	IN	CPU int. PD
R24	BOOT_MODE2	X_BOOT1	VDD_IO	1.8 V / 3.3 V	IN	CPU int. PD
T25	BOOT_MODE3	X_BOOT2	VDD_IO	1.8 V / 3.3 V	IN	CPU int. PD
U24	BOOT_MODE4	X_BOOT3	VDD_IO	1.8 V / 3.3 V	IN	CPU int. PD

10 System Memory

The phyFLEX-STM32MP2x FPSC provides three types of on-board memory:

TABLE 12: phyFLEX-STM32MP2x FPSC Onboard Memory Types

	Basic-Version	Kit-Version	Maximum Available
DDR4 RAM	512 MB	2 GByte	4 GByte
eMMC	4 GByte	8 GByte	256 GByte
I2C EEPROM*	4 kByte	4 kByte	256kByte

*EEPROM will be shared for user and factory information, which contains module-specific information to identify the module during factory handling and testing. The factory information starts at address 0 and ends at address 1023, and the user section starts at address 1024.

10.1 LPDDR4-RAM (U1)

The RAM memory interface of the phyFLEX-STM32MP2x FPSC supports one 32-bit LPDDR4-RAM chip (U1)

Typically, the DDR4 RAM initialization is performed by a boot loader or operating system following a power-on reset and must not be changed at a later point by any application code. When writing custom code independent of an operating system or boot loader, the RAM must be initialized by accessing the appropriate RAM configuration registers on the STM32MP2x controller. Refer to the *STM32MP2x Reference Manual* to access and configure these registers.

10.2 eMMC Flash Memory (U4)

The main flash memory of the STM32MP2x is eMMC and is populated at U4. The eMMC Flash memory is connected to the SDMMC2 interface of the STM32MP2x.

For more information about the eMMC Flash interface, please refer to the *STMicroelectronics® STM32MP2x Reference Manual*.

The following table shows the ports used for the SDMMC2 Interface connected to the onboard eMMC:

TABLE 13: SDMMC2 Ports

STM32MP2 Port Name	SDMMC2 Interface
PE14	SDMMC2_CK
PE15	SDMMC2_CMD
PE13	SDMMC2_D0

STM32MP2 Port Name	SDMMC2 Interface
PE11	SDMMC2_D1
PE8	SDMMC2_D2
PE12	SDMMC2_D3
PE10	SDMMC2_D4
PE9	SDMMC2_D5
PE6	SDMMC2_D6
PE7	SDMMC2_D7

I²C EEPROM (U11)

The phyFLEX-STM32MP2x FPSC is populated with a non-volatile 4 kB I²C EEPROM at U11. This memory is shared to store factory and user data. This device is accessed through I2C on the STM32MP2x. Please see the *STMicroelectronics® STM32MP2x Reference Manual* for detailed information.

The three lower address bits are fixed to 0x0, which means that the EEPROM can be accessed at I²C address 0x50. The EEPROM has a second address on 0x58, which is called the Identification Page.

The device is not write-protected by default. Write protection can be established by driving the signal X_EEPROM1_WC (X1-J50) to high (1.8 V).

The following table shows the ports used for the I2C Interface for EEPROM Board Devices (RTC, Temp-Sensor) on the same I2C bus:

TABLE 14: EEPROM I2C Information

I2C Interface for EPROM (RTC, Temp-Sensor) pcb PL1633.1	I2C Interface for EPROM (RTC, Temp-Sensor) pcb PL1633.0 (Alpha SOM)
X_I2C8_SDA/PZ3	I2C7_SDA/PD14
X_I2C8_SCL/PZ4	I2C7_SCL/PD15
	I2C7 is exclusively used for PMIC, therefore on PL1633.,0 I2C is not applicable for other devices!

EPROM (RTC, Temp-Sensor) on the same bus has the following address:

TABLE 15: EEPROM RTC & Temperature Sensor

EPROM (RTC, Temp-Sensor) Device	I2C slave address
EEPROM U11	0x50/0x58
RTC U10 (optional)	0x52
Temperature Sensors U9 (optional)	0x48

11 Serial Interfaces

The phyFLEX-STM32MP2x FPSC provides numerous dedicated serial interfaces, some of which are equipped with a transceiver to enable direct connection to external devices:

1. 1x 4-bit SDIO interface (SDMMC1) with controlled IO voltage for μ SD card.
2. 1x 4-bit SDIO interface (SDMMC3)
3. 3x high-speed UARTs
4. 3x CAN-FD interfaces
5. 1x USB 2.0/3.0 DRD SuperSpeed up to 5 Gbit/s
6. 1x USB 2.0 Host
7. 3x 1Gbit Ethernet interfaces (TSN, IEEE 1588v2, either one of them with Ethernet PHY on the phyFLEX-STM32MP2x; the other two as RGMII Signals)
8. 4x I²C interfaces
9. 3x Serial Peripheral Interfaces (SPI)
10. 1x SAI audio interface
11. 1x MIPI DSI
12. 2x LVDS interface (depending on the configuration)

Details for each of these serial interfaces and any applicable jumper configurations are below.

11.1 SDIO Interface

The SDIO interface can be used to connect external SD cards, eMMC, or any other device requiring an SDIO interface (i.e., WiFi, I/O expansion, etc).

On the phyFLEX-STM32MP2x FPSC, the interface signals of SDMMC1 and SDMMC3 extend to the phyFLEX-Connector.

The tables below show the location of the different interface signals on the phyFLEX-Connector.

The interface SDMMC1 supports SD cards with 3.3 V and 1.8 V I/O signals.

11.2 SDCARD SDMMC1 (4-bit)

SDMMC1 is a 4-bit wide interface with controlled I/O voltage to support high-speed modes that require 1.8 V I/O voltage. During runtime, the I/O voltage can be switched from 3.3 V (default) to 1.8 V by the processor, which controls the integrated voltage regulator. VDD_SDCARD will be used exclusively to supply an external SD or MicroSD memory card.

TABLE 16: SDIO Interface Pinout of SD2

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
V57	SDCARD_CD	X_SDMMC1_CD/PD9	VDDIO_SDCARD	1.8 V / 3.3 V Could change dynamically for UHS-I devices	OD-I-PU	MMC1 Card Detect
W60	SDCARD_CLK	X_SDMMC1_CLK/PE3	VDDIO_SDCARD	1.8 V / 3.3 V 1.8 V / 3.3 V Could change dynamically for UHS-I devices	O	MMC1 Clock
W58	SDCARD_CMD	X_SDMMC1_CMD/PE2	VDDIO_SDCARD	1.8 V / 3.3 V Could change dynamically for UHS-I devices	I/O	MMC1 Command

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
W62	SDCARD_DATA0	X_SDMMC1_DATA0/PE4	VDDIO_SDCARD	1.8 V / 3.3 V Could change dynamically for UHS-I devices	I/O	MMC1 Data 0
Y61	SDCARD_DATA1	X_SDMMC1_DATA1/PE5	VDDIO_SDCARD	1.8 V / 3.3 V Could change dynamically for UHS-I devices	I/O	MMC1 Data 1
U60	SDCARD_DATA2	X_SDMMC1_DATA2/PE0	VDDIO_SDCARD	1.8 V / 3.3 V Could change dynamically for UHS-I devices	I/O	MMC1 Data 2

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
V61	SDCARD_DATA3	X_SDMMC1_DATA3/PE1	VDDIO_SDCARD	1.8 V / 3.3 V Could change dynamically for UHS-I devices	I/O	MMC1 Data 3
Y57	SDCARD_VCC_OUT	VDD_SDCARD	LDO7OUT	3.3 V	PWR_O	Controlled MMC1 Supply Voltage
V67	SDCARD_WP	X_PF8	VDD_IO	1.8 V / 3.3 V Could change dynamically for UHS-I devices	OD-I-PU	MMC1 Write Protect

11.3 SDIO SDMMC3 (4-bit)

SDMMC3 is a 4-bit wide interface. The I/O voltage is default 1.8 V (refer to [External Logic IO Supply Voltage](#)).

TABLE 17: SDIO Interface Pinout of SD3

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
J58	SDIO_CD	X_PF4	VDD_IO	1.8 V / 3.3 V	OD-I	MMC2 Card Detect
H57	SDIO_CLK	X_SDMMC3_CLK/PB13	VDD_IO	1.8 V / 3.3 V	O	MMC2 Clock
G56	SDIO_CMD	X_SDMMC3_CMD/PD12	VDD_IO	1.8 V / 3.3 V	I/O	MMC2 Command
G62	SDIO_DATA0	X_SDMMC3_DATA0/ PB14	VDD_IO	1.8 V / 3.3 V	I/O	MMC2 Data 0
H61	SDIO_DATA1	X_SDMMC3_DATA1/ PD13	VDD_IO	1.8 V / 3.3 V	I/O	MMC2 Data 1
G60	SDIO_DATA2	X_SDMMC3_DATA2/ PB12	VDD_IO	1.8 V / 3.3 V	I/O	MMC2 Data 2
G58	SDIO_DATA3	X_SDMMC3_DATA3/PI11	VDD_IO	1.8 V / 3.3 V	I/O	MMC2 Data 3
J56	SDIO_VIO_OUT	VDD_IO	VDD_IO	1.8 V / 3.3 V	PWR_O	Voltage output (max. 20mA) to supply VDD_IO of the connected device

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
G54	SDIO_WP	X_PB11	VDD_IO	1.8 V / 3.3 V	OD-I	MMC2 Write Protect

11.4 Universal Asynchronous Interfaces (UARTs)

The phyFLEX-STM32MP2x FPSC provides three high-speed universal asynchronous interfaces. The following table shows the location of the signals on the phyFLEX-Connector.

TABLE 18: UART Signal Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
L44	UART1 RXD	X_USART6_RX/PF14	VDD_IO	1.8 V / 3.3 V	I	
L42	UART1 TXD	X_USART6_TX/PF13	VDD_IO	1.8 V / 3.3 V	O	
M41	UART1 CTS	X_USART6_CTS/PF15	VDD_IO	1.8 V / 3.3 V	I	
N42	UART1 RTS	X_USART6_RTS/PG5	VDD_IO	1.8 V / 3.3 V	O	
N46	UART2 RXD	X_UART5_RX/PG10	VCC_1V8_SYS	1.8 V	I	
N44	UART2 TXD	X_UART5_TX/PG9	VCC_1V8_SYS	1.8 V	O	
L46	UART2 CTS	X_UART5_CTS/PI5	VCC_1V8_SYS	1.8 V	I	
M45	UART2 RTS	X_UART5_RTS/PG8	VCC_1V8_SYS	1.8 V	O	

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
AE22	UART3 RXD	X_USART2_RX/PA8	VDD_IO	1.8 V / 3.3 V	I	A35 Debug UART (Linux-console)
AE20	UART3 TXD	X_USART2_TX/PA4	VDD_IO	1.8 V / 3.3 V	O	A35 Debug UART (Linux-console)

11.5 CAN Interfaces

The CAN-FD interfaces of the phyFLEX-STM32MP2x FPSC conform with CAN protocol 2.0 A & B and ISO 11898-1. It supports a flexible message payload, ranging from 0 to 8, 12, 16, 20, 24, 32, 48, and 64 bytes. It also supports standard and extended message frames and programmable bits up to 8 Mb/s.

The following table shows the position of the signals on the phyFLEX-Connector.

TABLE 19: CAN Interface Signal Location

FPSC Contact	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Muxing / Description
N38	CAN1_RX	FDCAN1_RX/PG12	VDD_IO	1.8 V / 3.3 V	I	
N36	CAN1_TX	FDCAN1_TX/PG11	VDD_IO	1.8 V / 3.3 V	O	
L38	CAN2_RX	FDCAN2_RX/PI10	VDD_IO	1.8 V / 3.3 V	I	
M37	CAN2_TX	FDCAN2_TX/PI9	VDD_IO	1.8 V / 3.3 V	O	
H21	CAN3_TX	FDCAN3_TX/PD2	VDD_IO	1.8 V / 3.3 V	O	
G20	CAN3_RX	FDCAN3_RX/PD1	VDD_IO	1.8 V / 3.3 V	I	

11.6 USB Interfaces

The phyFLEX-STM32MP2x provides

1. 1x USB 2.0/3.0 DRD SuperSpeed up to 5 Gbit/s = refered as phyFlex USB1 (DFU Mode interface)
2. 1x USB 2.0 Host = refered as phyFlex USB2

The two USB 2.0 interfaces support high-speed (480 Mbit/s), full-speed (12 Mbit/s), and low-speed (1.5 Mbit/s) operation. The applicable interface signals can be found on the phyFLEX-Connector X1. If overcurrent and power enable signals are needed for the USB host interface, the functionality can be easily implemented with designated GPIOs.

At USB,1 a voltage divider 22k / 10k is integrated on the SoM to scale down the 5V (max. 5.5V) USB1 to a matching voltage level for SOC.

TABLE 20: USB 1 Signal Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
AD61	USB1_D_N	X_USB1_D_N	USB3DR	USB	USB_I/O	USB 1 Data- (USB-DFU Mode)
AC62	USB1_D_P	X_USB1_D_P	USB3DR	USB	USB_I/O	USB 1 Data+ (USB-DFU Mode)
AE60	USB1_ID	X_PH4	VDD_IO	1.8 V / 3.3 V	I	GPIO as a replacement for the dedicated ID pin
AE58	USB1_OC	X_PG7	VDD_IO	1.8 V / 3.3 V	I	GPIO as a replacement for the dedicated USB 1 overcurrent input
AD57	USB1_PWR_EN	X_PF12	VDD_IO	1.8 V / 3.3 V	O	GPIO as a replacement for the dedicated USB 1 power enable output
AF67	USB1_RX0_N	COMBOPHY_RX1N	VDDCOMBOPHY		I	PCIe-1-Lane-Bus / RX 5Gbit USB3 super speed
AE66	USB1_RX0_P	COMBOPHY_RX1P	VDDCOMBOPHY		I	PCIe-1-Lane-Bus / RX 5Gbit USB3 super speed

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
AF71	USB1_TX0_N	COMBOPHY_TX1N	VDDCOMBOPHY		O	PCIe-1-Lane-Bus / TX 5GBit USB3 super speed
AE70	USB1_TX0_P	COMBOPHY_TX1P	VDDCOMBOPHY		O	PCIe-1-Lane-Bus / TX 5GBit USB3 super speed
AC60	USB1_VBUS	X_USB1_VBUS	VDDIO / VBUS(PMIC input)	5V	A	must not exceed 5V USB 1 bus voltage detection on Port X_PI8 via voltage divider also connected to PMIC's VBUS input

TABLE 21: USB 2 Signal Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
AB61	USB2_D_N	X_USB2_D_N	USBH_HS_DM	USBH_HS_D M	USB_I/O	USB 2 Data-
AA62	USB2_D_P	X_USB2_D_P	USBH_HS_DP	USBH_HS_D P	USB_I/O	USB 2 Data+
AA60	USB2_ID	nc	-	-	-	no ID pin because only USB HOST
AC58	USB2_nOC	X_PZ9	VDD_IO	1.8 V / 3.3 V	I	USB 2 overcurrent input
AB57	USB2_PWR_EN	X_PI0	VDD_IO	1.8 V / 3.3 V	O	USB 2 power enable output
AC66	USB2_RX0_N	nc				
AB67	USB2_RX0_P	nc				
AC70	USB2_TX0_N	nc				
AB71	USB2_TX0_P	nc				

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
AA58	USB2_VBUS	nc	-	-	-	USB2 is host only, no Vbus sesing neccessary

11.7 Ethernet Interfaces ETH1 and RGMII (ETH2)

The phyFLEX-STM32MP2x FPSC provides two Ethernet Interfaces, ETH1 and RGMII2. Connection of the phyFLEX-STM32MP2x FPSC to the World Wide Web or a local area network (LAN) is possible using the on-board GbE PHY at U6, which is connected to ETH1 (RGMII) . The PHY operates with a data transmission speed of 10 Mbit/s, 100 Mbit/s, or 1000 Mbit/s. Additionally, the RGMII2 (ETH2) is available on the phyFLEX-Connector and can be used to connect to an external PHY. ([ENET1 RGMII Interface](#)).

Note

PHYTEC has chosen to make the RGMII1 available as RGMII for customers to accommodate their individual needs when it comes to choosing the right PHY or switching components applicable to their network topology.

As an example, we have connected a TSN-capable Ethernet PHY to RGMII2 on the carrier board, which may be used for reference in your own design. See [Ethernet \(X8/X9\)](#) for details.

11.7.1 ETH1 Ethernet PHY (U7)

With an Ethernet PHY mounted at U6, the phyFLEX-STM32MP2x FPSC has been designed for use in 10Base-T, 100Base-T, and 1000Base-T networks. The 10/100/1000Base-T interface with its LED signals extends to the phyFLEX-Connector X1. **In a Linux environment, the ETH1 interface is called end0 as it is the port with the on-board PHY.**

TABLE 22: Ethernet PHY Signal Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name	SOM Voltage Domain	Signal Level	Signal Type	Description
AJ58	GB_ETH1_A_P	X_ETH_A_P	-	-	ETH_I/O	Gb Ethernet1 A N
AH57	GB_ETH1_A_N	X_ETH_A_N	-	-	ETH_I/O	Gb Ethernet1 A P
AG58	GB_ETH1_B_P	X_ETH_B_P	-	-	ETH_I/O	Gb Ethernet1 B N
AF57	GB_ETH1_B_N	X_ETH_B_N	-	-	ETH_I/O	Gb Ethernet1 B P
AH61	GB_ETH1_C_P	X_ETH_C_P	-	-	ETH_I/O	Gb Ethernet1 C N
AG62	GB_ETH1_C_N	X_ETH_C_N	-	-	ETH_I/O	Gb Ethernet1 C P
AF61	GB_ETH1_D_P	X_ETH_D_P	-	-	ETH_I/O	Gb Ethernet1 D N
AE62	GB_ETH1_D_N	X_ETH_D_N	-	-	ETH_I/O	Gb Ethernet1 D P
AG60	GP_ETH1_LED_ACT	X_ETH_LED2_ACT	-	-	O	OD Output
AJ60	GP_ETH1_LED_LINK	X_ETH_LINK	-	-	O	OD Output

11.7.1.1 Ethernet Signal Locations of ETH1

The on-board GbE PHY supports HP Auto-MDIX technology, eliminating the need for a direct-connect LAN or cross-over patch cable. It detects the TX and RX pins of the connected device and automatically configures the PHY TX and RX pins accordingly. The Ethernet PHY also features an auto-negotiation to automatically determine the best speed and duplex mode.

The Ethernet PHY is connected to the RGMII interface RGMII (ETH1) of the STM32MP2x. Please refer to the *STMicroelectronics® STM32MP2x Reference Manual* for more information about this interface.

The following table shows the ports used for the RGMII (ETH1) Interface connected to the onboard Ethernet PHY:

TABLE 23: RGMII Port Information

STM32MP2 Port Name	RGMII (ETH1) Interface
ETH1_MDC	PF0
ETH1_MDIO	PF2
ETH1_PHY_INTN	PA12
ETH1_RGMII_RX_CLK	PA14
ETH1_RGMII_RXD1	PC2
ETH1_RGMII_TXD0	PA15
ETH1_RGMII_TXD3	PH11
ETH1_RGMII_RXD0	PF1
ETH1_RGMII_RXD3	PH13
ETH1_RGMII_TXD2	PH10
ETH1_RGMII_RXD2	PH12
ETH1_RGMII_GTX_CLK	PC0
ETH1_RGMII_TXD1	PC1
ETH1_RGMII_TX_CTL	PA13
ETH1_RGMII_RX_CTL	PA11

In order to connect the module to an existing 10/100/1000Base-T network, some external circuitry is required. The required termination resistors on the analog signals (ETH_A±, ETH_B±, ETH_C±, ETH_D±) are integrated into the chip, so there is no need to connect external termination resistors to these signals. Connection to external Ethernet magnetics should be done using very short signal traces. The ETH_A±, ETH_B±, ETH_C±, and ETH_D± signals should be routed as 100 Ω differential pairs. The same applies to the signal lines after the transformer circuit. The carrier board layout should avoid any other signal lines crossing the Ethernet signals.

 **Warning**

Please refer to the Ethernet PHY datasheet when designing the Ethernet transformer circuitry or request the schematic of the applicable carrier board (Libra Development Board STM32MP2x).

11.7.2 Reset of the Ethernet Controller

The reset input of the Ethernet PHY at U6 is connected to the system reset nRST (X_nRESET_IN).

11.7.3 MAC Address

In a computer network such as a local area network (LAN), the MAC (Media Access Control) address is a unique computer hardware number. For a connection to the internet, a table is used to convert the assigned IP address to the hardware's MAC address. In order to guarantee that the MAC address is unique, all addresses are managed in a central location. PHYTEC has acquired a pool of MAC addresses. The MAC address of the phyFLEX-STM32MP2x FPSC is located on the 2D-code sticker attached to the module. This number is a 12-digit HEX value. The MAC addresses are additionally stored in the factory area of the EEPROM. PHYTEC u-boot / Linux uses these addresses as MACs.

11.7.4 RGMII (ETH2) Interface

In order to use an external Ethernet PHY, the second RGMII (ETH2) interface of the STM32MP2x is brought out at phyFLEX-Connector X1 as RGMII, which supports TSN network operation. For that use case, an external TSN-ready Ethernet switch device is used. **In a Linux environment, the RGMII (ETH2) interface is called eth1 as it is the port with the external PHY.**

TABLE 24: ETH2 RGMII Interface Signal Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name	SOM Voltage Domain	Signal Level**	Signal Type	Description
AH45	GMII2_EVENT_IN	nc				
AJ44	RGMI2_EVENT_OUT	nc				
AG46	RGMI2 MDC	X_ETH2_MDC/PC6	VDD_IO	1.8 V / 3.3 V	O	Management Clock
AG44	RGMI2 MDIO	X_ETH2_MDIO/PC5	VDD_IO	1.8 V / 3.3 V	IO	Management Data
AG48	RGMI2 nINT	_ETH2_MDINT/PF5	VDD_IO	1.8 V / 3.3 V	I	Interrupt In
AG54	RGMI2 RX CTL	X_ETH2_RX_CTL/PC3	VDD_IO	1.8 V / 3.3 V	I	Receive Control
AJ56	RGMI2 RX D0	X_ETH2_RXD0/PG0	VDD_IO	1.8 V / 3.3 V	I	Receive Data 0
AJ54	RGMI2 RX D1	X_ETH2_RXD1/PC12	VDD_IO	1.8 V / 3.3 V	I	Receive Data 1
AJ52	RGMI2 RX D2	X_ETH2_RXD2/PF9	VDD_IO	1.8 V / 3.3 V	I	Receive Data 2
AH53	RGMI2 RX D3	X_ETH2_RXD3/PC11	VDD_IO	1.8 V / 3.3 V	I	Receive Data 3

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name	SOM Voltage Domain	Signal Level**	Signal Type	Description
AG56	RGMI2 RXC	X_ETH2_RX_CLK/PF6	VDD_IO	1.8 V / 3.3 V	I	Receive Clock
AG50	RGMI2 TX CTL	X_ETH2_TX_CTL/PC4	VDD_IO	1.8 V / 3.3 V	O	Transmit Control
AJ50	RGMI2 TX D0	X_ETH2_TXD0/PC7	VDD_IO	1.8 V / 3.3 V	O	Transmit Data 0
AJ48	RGMI2 TX D1	X_ETH2_TXD1/PC8	VDD_IO	1.8 V / 3.3 V	O	Transmit Data 1
AH49	RGMI2 TX D2	X_ETH2_TXD2/PC9	VDD_IO	1.8 V / 3.3 V	O	Transmit Data 2
AJ46	RGMI2 TX D3	X_ETH2_TXD3/PC10	VDD_IO	1.8 V / 3.3 V	O	Transmit Data 3
AG52	RGMI2 TXC	X_ETH2_GTX_CLK/PF7	VDD_IO	1.8 V / 3.3 V	O	Transmit Clock

11.8 SPI Interface

The Serial Peripheral Interface (SPI) is a four-wire, bidirectional serial bus that provides a simple and efficient method for data exchange among devices. The phyFLEX provides three SPI and one QSPI connections on the phyFLEX-Connector X1. The SPI provides one chip select signal for each interface. The SPI modules are master/slave configurable. The following table lists the Q/SPI signals on the phyFLEX-Connector.

TABLE 25: SPI Interface Signal Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
L34	SPI1_nCS	X_SPI3_NSS/PB1	VDD_IO	1.8 V / 3.3 V	O	SPI1 CS
M33	SPI1_SCLK	X_SPI3_SCLK/PB7	VDD_IO	1.8 V / 3.3 V	O	SPI1 CLK
N32	SPI1_MOSI	X_SPI3_MOSI/PB8	VDD_IO	1.8 V / 3.3 V	O	SPI1 D0
N34	SPI1_MISO	X_SPI3_MISO/PB10	VDD_IO	1.8 V / 3.3 V	I	SPI1 D1
N30	SPI2_nCS	X_SPI8_NSS/PZ6	VDD_IO	1.8 V / 3.3 V	O	SPI2 CS
M29	SPI2_SCLK	X_SPI8_SCLK/PZ2	VDD_IO	1.8 V / 3.3 V	O	SPI2 CLK
L30	SPI2_MOSI	X_SPI8_MOSI/PZ0	VDD_IO	1.8 V / 3.3 V	O	SPI2 D0
L32	SPI2_MISO	X_SPI8_MISO/PZ1	VDD_IO	1.8 V / 3.3 V	I	SPI2 D1
AM41	SPI3_nCS	X_SPI2_NSS/PB3	VDD_IO	1.8 V / 3.3 V	O	SPI3 CS

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
AL40	SPI3_SCLK	X_SPI2_SCLK/PB0	VDD_IO	1.8 V / 3.3 V	O	SPI3 CLK
AL38	SPI3_MISO	X_SPI2_MOSI/PB2	VDD_IO	1.8 V / 3.3 V	O	SPI3 D0
AL36	SPI3_MOSI	X_SPI2_MISO/PB6	VDD_IO	1.8 V / 3.3 V	I	SPI3 D1

11.9 QSPI Interface

The Quad Serial Peripheral Interface (QSPI) is a bidirectional serial bus with up to 4 data lanes that provides a simple and efficient method for data exchange among devices. The phyFLEX provides QSPI on the phyFLEX-Connector X1. The QSPI provides one chip select signal for the interface. The FlexSPI of the STM32MP2x supports single, dual, and quad modes in single data rate (SDR) and double data rate (DDR) transfer modes. The interface signals of FlexSPI mode are made available on the phyFLEX-Connector. The following table lists the QSPI signals on the phyFLEX-Connector.

TABLE 26: QSPI Interface Signal Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Muxing / Description
AJ24	QSPI_nCE	X_QSPI1_NCS1/PD3	VDD_IO	1.8 V / 3.3 V	O	QSPI Chip Select
AG24	QSPI_CLK	X_QSPI1_CLK/PD0	VDD_IO	1.8 V / 3.3 V	O	QSPI CLK
AF21	QSPI_DATA_0	X_QSPI1_IO1/PD4	VDD_IO	1.8 V / 3.3 V	IO	QSPI D0
AG20	QSPI_DATA_1	X_QSPI1_IO2/PD5	VDD_IO	1.8 V / 3.3 V	IO	QSPI D1
AG22	QSPI_DATA_2	X_QSPI1_IO3/PD6	VDD_IO	1.8 V / 3.3 V	IO	QSPI D2
AH21	QSPI_DATA_3	X_QSPI1_IO4/PD7	VDD_IO	1.8 V / 3.3 V	IO	QSPI D3
AJ22	QSPI_DQS	nc				

11.10 I²C Interface

The Inter-Integrated Circuit (I²C) interface is a two-wire, bidirectional serial bus that provides a simple and efficient method for data exchange among devices. The STM32MP2x contains 5 identical and independent Multimaster fast-mode I²C modules. The interface of 4 modules is available on the phyFLEX-Connector X1. I2C7_SCL is reserved for controlling the onboard PMIC.

 **Tip**

To ensure the proper functioning of the I²C interface, external pull resistors matching the load at the interface must be connected. There are no pull-up resistors mounted on the module. For detailed information on the voltage levels for the pull-up resistors, please refer to the *STM32MP2x Datasheet*.

The following table lists the I²C ports on the phyFLEX-Connector:

TABLE 27: I2C / I3C Interface Signal Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
L26	I2C1_SCL_DNU	I2C7_SCL/PD15	VDD_IO	1.8 V / 3.3 V	I/OD	Internal I2C1 Clock - Do not use!
L28	I2C1_SDA_DNU	I2C7_SDA/PD14	VDD_IO	1.8 V / 3.3 V	I/OD	Internal I2C1 Data - Do not use!
L60	I2C2_SCL	X_I2C2_SCL/PB5	VDD_IO	1.8 V / 3.3 V	I/OD	I2C2 Data
L58	I2C2_SDA	X_I2C2_SDA/PB4	VDD_IO	1.8 V / 3.3 V	I/OD	I2C2 Clock
M61	I2C3_SCL	X_I2C8_SCL/PZ4	VDD_IO	1.8 V / 3.3 V	I/OD	I2C3 Data
N60	I2C3_SDA	SDA/PZ3	VDD_IO	1.8 V / 3.3 V	I/OD	I2C3 Clock

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
AN36	I2C4_SCL	pcb PL1633.0: X_I2C1_SCL/PG13 PL1633.1: X_I2C4_SCL/ PD11	VDD_IO	1.8 V / 3.3 V	I/OD	I2C4 Data
AN38	I2C4_SDA	pcb PL1633.0: X_I2C1_SDA/PI1 PL1633.1: X_I2C4_SDA/ PD10	VDD_IO	1.8 V / 3.3 V	I/OD	I2C4 Clock
AN40	I2C5_SCL/I3C_SCL	pcb PL1633.0: X_I2C4_SCL/PD11 PL1633.1: X_I2C1_SCL/ PG13 (I3C1_SCL)	VDD_IO	1.8 V / 3.3 V	I/OD	I2C5 Data
AN42	I2C5_SDA/I3C_SDA	pcb PL1633.0: X_I2C4_SDA/PD10 PL1633.1: X_I2C1_SDA/ PI1 (I3C1_SDA)	VDD_IO	1.8 V / 3.3 V	I/OD	I2C5 Clock

11.11 Audio Interface

The STM32MP2x supports multiple audio interfaces. One of them is available as listed below:

TABLE 28: phyFLEX-STM32MP2x FPSC Audio Interfaces

Interface	RX Data Line	TX Data Line
SAI2	1	1

11.11.1 SAI Audio Interface

The phyFLEX-STM32MP2x FPSC features a Synchronous Audio Interface that supports full-duplex serial interfaces with frame synchronization, such as I2S, AC97, and TDM.

The tables below show the signal locations of the McASP0 interface.

11.11.1.1 SAI1 Interface

TABLE 29: SAI1 Interface Signal Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level**	Signal Type	Description
AJ32	SAI1_MCLK	n.a.	-	-	-	(relates to R116) Add an external clock generator
AG28	SAI1_RX_BCLK	X_ADC1_INP16/ SAI2_SCK_B/PF3	VDD_IO	1.8 V / 3.3 V	IO	SAI1 RX BCLK PF3 is also connected to the FPSC Pin V15 If used as SAI1_RX_BCLK ADC5 on the FPSC pin, V15 can not be used
AG30	SAI1_RX_DATA	X_ADC1_INP15/ SAI2_SD_B/PB15	VDD_IO	1.8 V / 3.3 V	IO	SAI1 RX Data
AG32	SAI1_RX_SYNC	X_ADC1_INP3/ SAI2_FS_B/PG3	VDD_IO	1.8 V / 3.3 V	IO	SAI1 RX SYNC
AH29	SAI1_TX_BCLK	X_SAI2_SCK_A/PF11	VDD_IO	1.8 V / 3.3 V	IO	SAI1 TX BCLK
AJ28	SAI1_TX_DATA	X_SAI2_SD_A/PG1	VDD_IO	1.8 V / 3.3 V	IO	SAI1 TX Data
AJ30	SAI1_TX_SYNC	X_SAI2_FS_A/PH5	VDD_IO	1.8 V / 3.3 V	IO	SAI1 TX SYNC

11.12 PCI Express Interface

The one 1-lane PCI Express interface of the phyFLEX-STM32MP2x FPSC provides PCIe Gen. 3.0 functionality, which supports up to 8 GT/s operations. Additional control signals that might be required (e.g., “present” and “wake”) can be implemented with GPIOs. Please refer to the schematic of a suitable PHYTEC carrier board (e.g., phyBOARD-Pollux) for a circuit example.

The position of the PCIe signals on the phyFLEX-Connector X1 is shown below:

TABLE 30: PCIe Interface Signal Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level ^[2]	Signal Type	Muxing / Description
AA14	PCIE1_CLK_N	X_PCIE_REF_PAD_CLK_N	VDDPCIECLK		PCIe_I/O	PCIe1 Ref CLK- Input (AC coupling capacitor is located on the module)
AB15	PCIE1_CLK_P	X_PCIE_REF_PAD_CLK_P	VDDPCIECLK		PCIe_I/O	PCIe1 Ref CLK+ Input (AC coupling capacitor is located on the module)
AC16	PCIE1_nCLKREQ	X_PZ5	VDD_IO	1.8 V / 3.3 V	I	PCIe1 Clk request Input
AC14	PCIE1_nPERST	X_PD8	VDD_IO	1.8 V / 3.3 V	O	PCIe1 reset Output
AB11	PCIE1_RXN_N	COMBOPHY_RX1N	VDDCOMBOPHY		PCIe_I	PCIe1 RXN- (AC coupling capacitor is located on the module) PCIe-1-Lane-Bus / RX 5Gbit USB3 super speed

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level [2]	Signal Type	Muxing / Description
AC12	PCIE1_RXN_P	COMBOPHY_RX1P	VDDCOMBOPHY		PCle_I	PCle1 RXN+ (AC coupling capacitor is located on the module) PCle-1-Lane-Bus / RX 5GBit USB3 super speed
Y11	PCIE1_TXN_N	COMBOPHY_TX1N	VDDCOMBOPHY		PCle_O	PCle1 TXN- (AC coupling capacitor is located on the module) PCle-1-Lane-Bus / RX 5GBit USB3 super speed
AA12	PCIE1_TXN_P	COMBOPHY_TX1P (via 100nF to CPU)	VDDCOMBOPHY		PCle_O	PCle1 TXN+ (AC coupling capacitor is located on the module) PCle-1-Lane-Bus / RX 5GBit USB3 super speed

2. WARN: short cite used before fully qualified cite

12 General Purpose I/Os & PWM

All pins not used by any of the other interfaces specifically described in this manual can be used as GPIO without harming other features of the phyFLEX-STM32MP2x FPSC. These pins are shown below:

TABLE 31: GPIO Pin Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
N40	GPIO1	X_GPIO/USART1_DE/PB9	VDD_IO	1.8 V / 3.3 V	I/O	-
L40	GPIO2	X_GPIO/USART1_TX/ PG14	VDD_IO	1.8 V / 3.3 V	I/O	-
AL32	GPIO3	X_GPIO/USART1_RX/ PG15	VDD_IO	1.8 V / 3.3 V	I/O	-
AL34	GPIO4	X_GPIO/USART3_TX/ WKUP4/PI6	VDD_IO	1.8 V / 3.3 V	I/O	-
AN30	GPIO5	X_GPIO/USART3_RX/PI7	VDD_IO	1.8 V / 3.3 V	I/O	-
AN32	GPIO6	X_GPIO/LPUART1_TX/ PZ7	VDD_IO	1.8 V / 3.3 V	I/O	-
AN34	GPIO7	X_GPIO/LPUART1_RX/ PZ8	VDD_IO	1.8 V / 3.3 V	I/O	-

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
N48	PWM1	X_TIM8_CH3_1_PWM/ PI2	VDD_IO	1.8 V / 3.3 V	O	-
N58	PWM2	X_TIM8_CH3_2_PWM/ PI3	VDD_IO	1.8 V / 3.3 V	O	-
AL42	PWM3	X_TIM8_CH3_3_PWM/ PI4	VDD_IO	1.8 V / 3.3 V	O	-
AN52	PWM4	X_TIM2_CH4_PWM/PG6	VDD_IO	1.8 V / 3.3 V	O	-

Besides these pins, most of the STM32MP2x signals that are connected directly to the module connector can be configured to act as GPIOs, due to the multiplexing functionality of most controller pins.

13 Debug Interface

phyFLEX-STM32MP2x FPSC is equipped with a JTAG interface to download program code into the external flash, internal controller RAM, or any debugging programs being executed. The JTAG pin locations on the phyFLEX-Connector X1 are below:

TABLE 32: Debug Interface Signal Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level ^[2]	Signal Type	Muxing / Description
AC20	JTAG_TCK	X_JTCK_SWCLK	VDD_IO	1.8 V / 3.3 V	I	JTAG clock signal. Has 2.2 kOhm pull-down.
AC22	JTAG_TDI	X_JTDI	VDD_IO	1.8 V / 3.3 V	I	JTAG data in signal
AD25	JTAG_TDO	X_JTDO_SWDO	VDD_IO	1.8 V / 3.3 V	O	JTAG data out signal
AC24	JTAG_TMS	X_JTMS_SWDIO	VDD_IO	1.8 V / 3.3 V	I	JTAG test mode select signal
AE24	JTAG_TRST	X_JTAG_NJTRS	VDD_IO	1.8 V / 3.3 V	I	
AD21	JTAG_RESERVED	nc				

2. WARN: short cite used before fully qualified cite

13.1 UART Debug

The default debug UART Interfaces are FPSC UART3 (STM32MP2x USART2) for Cortex-A53 Cores and FPSC UART2 (STM32MP2x UART5) for Cortex-M33 Core. FPSC UART3 is accessible on connector X1 pins AE22 (RXD) and AE20 (TXD), and FPSC UART2 on pins N46 (RXD) and N44 (TXD).

For more information, refer to [Universal Asynchronous Interfaces \(UARTs\)](#).

14 Display Interfaces

14.1 Low Voltage Differential Signal Display Interface (LVDS)

phyFLEX-STM32MP2x FPSC offers one LVDS display interface, which supports two output channels.

The locations of the LVDS signals are shown below:

TABLE 33: Display Interface LVDS Signal Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Muxing / Description
LVDS channel 0						
L52	LVDS1_DATA0_N	X_LVDS0_CLK_N	VDDLVD	LVDS	LVDS_O	LVDS0 DATA0-
L50	LVDS1_DATA0_P	X_LVDS0_CLK_P	VDDLVD	LVDS	LVDS_O	LVDS0 DATA0+
L54	LVDS1_DATA1_N	X_LVDS0_D0_N	VDDLVD	LVDS	LVDS_O	LVDS0 DATA1-
M53	LVDS1_DATA1_P	X_LVDS0_D0_P	VDDLVD	LVDS	LVDS_O	LVDS0 DATA1+
N52	LVDS1_CLK_N	X_LVDS0_D1_N	VDDLVD	LVDS	LVDS_O	LVDS0 Clock-
N50	LVDS1_CLK_P	X_LVDS0_D1_P	VDDLVD	LVDS	LVDS_O	LVDS0 Clock+
N56	LVDS1_DATA2_N	X_LVDS0_D2_N	VDDLVD	LVDS	LVDS_O	LVDS0 DATA2-
N54	LVDS1_DATA2_P	X_LVDS0_D2_P	VDDLVD	LVDS	LVDS_O	LVDS0 DATA2+
M57	LVDS1_DATA3_N	X_LVDS0_D3_N	VDDLVD	LVDS	LVDS_O	LVDS0 DATA3-

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Muxing / Description
L56	LVDS1_DATA3_P	X_LVDS0_D3_P	VDDLVD	LVDS	LVDS_O	LVDS0 DATA3+
LVDS channel 1						
AN54	LVDS2_CLK_N	X_LVDS1_D1_N	VDDLVD	LVDS	LVDS_O	LVDS1 Clock-
AN56	LVDS2_CLK_P	X_LVDS1_D1_P	VDDLVD	LVDS	LVDS_O	LVDS1 Clock+
AN60	LVDS2_DATA0_N	X_LVDS1_CLK_N	VDDLVD	LVDS	LVDS_O	LVDS1 DATA0-
AM61	LVDS2_DATA0_P	X_LVDS1_CLK_P	VDDLVD	LVDS	LVDS_O	LVDS1 DATA0+
AL56	LVDS2_DATA1_N	X_LVDS1_D0_N	VDDLVD	LVDS	LVDS_O	LVDS1 DATA1-
AL58	LVDS2_DATA1_P	X_LVDS1_D0_P	VDDLVD	LVDS	LVDS_O	LVDS1 DATA1+
AM57	LVDS2_DATA2_N	X_LVDS1_D2_N	VDDLVD	LVDS	LVDS_O	LVDS1 DATA2-
AN58	LVDS2_DATA2_P	X_LVDS1_D2_P	VDDLVD	LVDS	LVDS_O	LVDS1 DATA2+
AL52	LVDS2_DATA3_N	X_LVDS1_D3_N	VDDLVD	LVDS	LVDS_O	LVDS1 DATA3-

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Muxing / Description
AL54	LVDS2_DATA3_P	X_LVDS1_D3_P	VDDLVD	LVDS	LVDS_O	LVDS1 DATA3+

14.2 MIPI-DSI Display Interface (DSI)

phyFLEX-STM32MP2x FPSC offers one MIPI-DSI display interface.

The locations of the MIPI-DSI signals are shown below:

TABLE 34: Display Interface MIPI / DSI Signal Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Muxing / Description
AN46	DSI1_CLK_N	X_MIPI_DSI1_CLK_N	VDDLVDS	LVDS	DSI2_O	DSI Clock-
AN48	DSI1_CLK_P	X_MIPI_DSI1_CLK_P	VDDLVDS	LVDS	DSI2_O	DSI Clock+
AL48	DSI1_D0_N	X_MIPI_DSI1_D0_N	VDDLVDS	LVDS	DSI2_O	DSI DATA0-
AL50	DSI1_D0_P	X_MIPI_DSI1_D0_P	VDDLVDS	LVDS	DSI2_O	DSI DATA0+
AM49	DSI1_D1_N	X_MIPI_DSI1_D1_N	VDDLVDS	LVDS	DSI2_O	DSI DATA1-
AN50	DSI1_D1_P	X_MIPI_DSI1_D1_P	VDDLVDS	LVDS	DSI2_O	DSI DATA1+
AN44	DSI1_D2_N	X_MIPI_DSI1_D2_N	VDDLVDS	LVDS	DSI2_O	DSI DATA2-
AM45	DSI1_D2_P	X_MIPI_DSI1_D2_P	VDDLVDS	LVDS	DSI2_O	DSI DATA2+
AL44	DSI1_D3_N	X_MIPI_DSI1_D3_N	VDDLVDS	LVDS	DSI2_O	DSI DATA3-
AL46	DSI1_D3_P	X_MIPI_DSI1_D3_P	VDDLVDS	LVDS	DSI2_O	DSI DATA3+

15 Camera Connections

The phyFLEX-STM32MP2x FPSC offers 1 MIPI-CSI interface to connect digital cameras. The MIPI/CSI-1 camera interfaces of the STM32MP2x extend to the phyFLEX-Connector X1 with 2 data lanes and one clock lane.

The locations of the MIPI-CSI signals are shown below:

TABLE 35: Camera Interface MIPI / CSI-2 Signal Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball]	SOM Voltage Domain	Signal Level	Signal Type	Muxing / Description
R62	CSI1_CLK_N	X_MIPI_CSI1_CLK_N	VDDCSI	LVDS	CSI2_I	CSI1 Clock-
R60	CSI1_CLK_P	X_MIPI_CSI1_CLK_P	VDDCSI	LVDS	CSI2_I	CSI1 Clock+
T57	CSI1_D0_N	X_MIPI_CSI1_D0_N	VDDCSI	LVDS	CSI2_I	CSI1 DATA0-
U58	CSI1_D0_P	X_MIPI_CSI1_D0_P	VDDCSI	LVDS	CSI2_I	CSI1 DATA0+
T61	CSI1_D1_N	X_MIPI_CSI1_D1_N	VDDCSI	LVDS	CSI2_I	CSI1 DATA1-
U62	CSI1_D1_P	X_MIPI_CSI1_D1_P	VDDCSI	LVDS	CSI2_I	CSI1 DATA1+
P57	CSI1_D2_N	nc	-	-	-	-
R58	CSI1_D2_P	nc	-	-	-	-
N62	CSI1_D3_N	nc	-	-	-	-
P61	CSI1_D3_P	nc	-	-	-	-

16 ADC Inputs

The phyFLEX-STM32MP2x FPSC provides a 4-channel 10-bit SAR ADC with single-ended or differential inputs and up to 4 MSPS.

TABLE 36: ADC Inputs Signal Locations

SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Description
R16	ADC1	X_ADC1_INP2/PG2	VREFP	1.8 V	A	ADC Analog Inut 1
T15	ADC2	X_ADC3_INP4/PH9	VREFP	1.8 V	A	ADC Analog Inut 2
U16	ADC3	X_ADC1_INP4/PG4	VREFP	1.8 V	A	ADC Analog Inut 3
U14	ADC4	X_ADC3_INP2/PF10	VREFP	1.8 V	A	ADC Analog Inut 4
V15	ADC5	X_ADC1_INP16/PF3 option	VREFP	1.8 V	A	ADC Analog Inut 5 only usable if FPSC Pin AG28 (SAI1_RX_BCLK) not used
W16	ADC6	n.a.	-	-	-	-
W14	ADC7	n.a.	-	-	-	-
Y15	ADC8	n.a.	-	-	-	-

17 FPSC Reserved Target-specific Proprietary Signals

The following signals are not defined according to [FPSC Gamma Feature Set Specifications \(LAN-118e.A6\)](#). These signals are processor-specific and should only be used in applications if no direct compatibility between different SOMs is required.

TABLE 37: FPSC Reserved Target-specific Proprietary Signals

FPSC Contact	FPSC Signal	SOM Signal Name (CPU Ball]	SOM Voltage Domain	Signal Level	Signal Type	Muxing / Description
V25	RESERVED1	X_PMIC_WAKEUPn/PC13	VDD_IO	1.8 V / 3.3 V	I/O	connected on the module with PMIC U3 do not use
W22	RESERVED1	X_MP257_WAKEUP/PA0	VDD_IO	1.8 V / 3.3 V	I/O	connected on the module with PMIC U3 do not use
AG34	RESERVED4	X_ETH3_MDINT/PA1	VDD_IO	1.8 V / 3.3 V	I/O	ETH3 RGMII interface
AG36	RESERVED5	X_ETH3_TX_CTL/PA3	VDD_IO	1.8 V / 3.3 V	I/O	ETH3 RGMII interface
AG38	RESERVED6	X_ETH3_GTX_CLK/PH2	VDD_IO	1.8 V / 3.3 V	I/O	ETH3 RGMII interface
AG40	RESERVED7	X_ETH3_RX_CTL/PA2	VDD_IO	1.8 V / 3.3 V	I/O	ETH3 RGMII interface
AG42	RESERVED8	X_SAI2_SD_B/ ETH3_RX_CLK/PA5	VDD_IO	1.8 V / 3.3 V	I/O	ETH3 RGMII interface

FPSC Contact	FPSC Signal	SOM Signal Name (CPU Ball]	SOM Voltage Domain	Signal Level	Signal Type	Muxing / Description
AH25	RESERVED9	ETH1_MDIO/PF2	VDD_IO	1.8 V / 3.3 V	I/O	ETH1/3 Management Data also used for onboard PHY
AH33	RESERVED10	X_SAI2_FS_B/ETH3_TXD0/PA6	VDD_IO	1.8 V / 3.3 V	I/O	ETH3 RGMII interface
AL28	RESERVED25	VDDCORE	VDDCORE	670mV/ 820mV	Power	VDDCORE measure point, no load allowed
AL30	RESERVED26	VDDCPU	VDDCPU	670mV/ 800mV/ 910mV	Power	VDDCPU measure point, no load allowed
AD67	RESERVED27	UCPD1_CC1	VDD33UCPD		analog	STMP32MP2 USB-C CC1 Pin
AM29	RESERVED50	X_VBAT_CPU				
AM33	RESERVED51	VDD_IO	VDD_CORE	1.8 V / 3.3 V	Power	VDD_IO measure point, no load allowed
AJ68	RESERVED54	X_ETH_GPIO0	1V8	1.8 V	IO	ETH_GPIO0 out from ETH- Phy U6

FPSC Contact	FPSC Signal	SOM Signal Name (CPU Ball]	SOM Voltage Domain	Signal Level	Signal Type	Muxing / Description
AJ70	RESERVED82	X_ETH_GPIO1	1V8	1.8 V	IO	ETH_GPIO1 out from ETH-Phy U6
AD71	RESERVED83	UCPD1_CC2	VDD33UCPD		analog	STMP32MP2 USB-C CC1 Pin
AH37	RESERVED11	X_ETH3_TXD3/PH3	VDD_IO	1.8 V / 3.3 V	I/O	ETH3 RGMII interface
AH41	RESERVED12	X_ETH3_RXD1/PA10	VDD_IO	1.8 V / 3.3 V	I/O	ETH3 RGMII interface
AJ26	RESERVED14	ETH1_MDC/PF0	VDD_IO	1.8 V / 3.3 V	I/O	ETH1/3 Management Clock also used for onboard PHY
AJ34	RESERVED15	X_PCIE_CLKREQN/ ETH3_TXD1/PA7	VDD_IO	1.8 V / 3.3 V	I/O	ETH3 RGMII interface
AJ36	RESERVED16	X_ETH3_TXD2/PH6	VDD_IO	1.8 V / 3.3 V	I/O	ETH3 RGMII interface
AJ38	RESERVED17	X_ETH3_RXD3/PH8	VDD_IO	1.8 V / 3.3 V	I/O	ETH3 RGMII interface
AJ40	RESERVED18	X_ETH3_RXD2/PH7	VDD_IO	1.8 V / 3.3 V	I/O	ETH3 RGMII interface

FPSC Contact	FPSC Signal	SOM Signal Name (CPU Ball]	SOM Voltage Domain	Signal Level	Signal Type	Muxing / Description
AJ42	RESERVED19	X_SAI2_SCK_B/ ETH3_RXD0/PA9	VDD_IO	1.8 V / 3.3 V	I/O	ETH3 RGMII interface
J54	RESERVED35	X_RTC_EVTI	VDD_3V3 or X_RTC_VBACKUP	3.3 V or X_RTC_VBACK UP voltage level	I	Event Input of the RTC RV-3028-C7 U10. X_RTC_EVTI has a 100k pull-down and can be left unconnected. Input high level is 0.8xVDD, determined by VDD_3V3 or the voltage level at X_RTC_VBACKUP in backup mode. For more information, refer to the Micro Crystal RV-3028-C7 App-Manual.
J52	RESERVED36	x_nTEMP_ALERT	VDD_IO	1.8 V / 3.3 V	O	Alert from temperature sensor. Use external PU to VCC_1V8_SYS

FPSC Contact	FPSC Signal	SOM Signal Name (CPU Ball]	SOM Voltage Domain	Signal Level	Signal Type	Muxing / Description
J50	RESERVED37	X_EEPROM1_WC	VDD_IO	1.8 V / 3.3 V	I	Write Control input of EEPROM U11. Pin is floating and is unprotected by default. Drive X_EEPROM2_WC high to protect the device.
J24	RESERVED46	X_PMIC_LDO6	X_PMIC_LDO6		Power	LDO6_OUT from PMIC
G48	RESERVED91	X_PZ5	VDD_IO	1.8 V / 3.3 V	I/O	used on the module for PCIE1_nCLKREQ
G46	RESERVED92	X_PI8	VDD_IO	1.8 V / 3.3 V	I/O	used on a module for sensing X_USB1_VBUS

18 RTC

The phyFLEX-STM32MP2x FPSC has an on-board, externally mounted RTC. The RV-3028-C7 is the newest generation of RTC from Micro Crystal with an extremely low backup current of typically 40 nA at 25 °C. PHYTEC uses the most optimal implementation in each phyFLEX design to give the most optimal usage for all customers.

The RTC is accessible over I2C on Address 0x52. In a normal operation state, the RTC power is supplied from the SOM voltage VDD_3V3. If the SOM is not powered, an RTC backup can be applied; the VBACKUP Pin of the RTC can be supplied over the X_RTC_VBACKUP pin X1-AA22.

The RTC provides an interrupt open-drain output signal (X_RTC_INT), which is fed to the module connector X1-T21. To use the X_RTC_INT signal, add an external pull-up resistor (e.g., 10k) to an appropriate I/O voltage level (e.g., X_RTC_VBACKUP).

Furthermore, the RTC is able to supply a programmable clock output signal (push-pull), RTC_CLKOUT. Frequencies of 1/32/64/1024/8192 Hz and 32.768 Hz (default) are programmable. The RTC_CLKOUT signal is fed to the module connector at X1-U20. For a detailed description of the programming capabilities of the RTC, refer to the *Micro Crystal RV-3028-C7 App-Manual*.

TABLE 38: EEPROM I2C Interface

I2C Interface for EEPROM (RTC, Temp-Sensor) pcb PL1633.1	I2C Interface for EEPROM (RTC , Temp-Sensor) pcb PL1633.0 (Alpha SOM)
X_I2C8_SDA/PZ3	I2C7_SDA/PD14
X_I2C8_SCL/PZ4	I2C7_SCL/PD15
	I2C7 is exclusively used for PMIC, therefore on PL1633.0, I2C is not applicable for other devices!

EEPROM (RTC, Temp-Sensor) on the same bus has the following address:

TABLE 39: EEPROM RTC & Temperature Sensor

EEPROM (RTC, Temp-Sensor) Device	I2C slave address
EEPROM U11	0x50/0x58
RTC U10 (optional)	0x52
Temperature Sensors U9 (optional)	0x48

TABLE 40: RTC Signal Locations

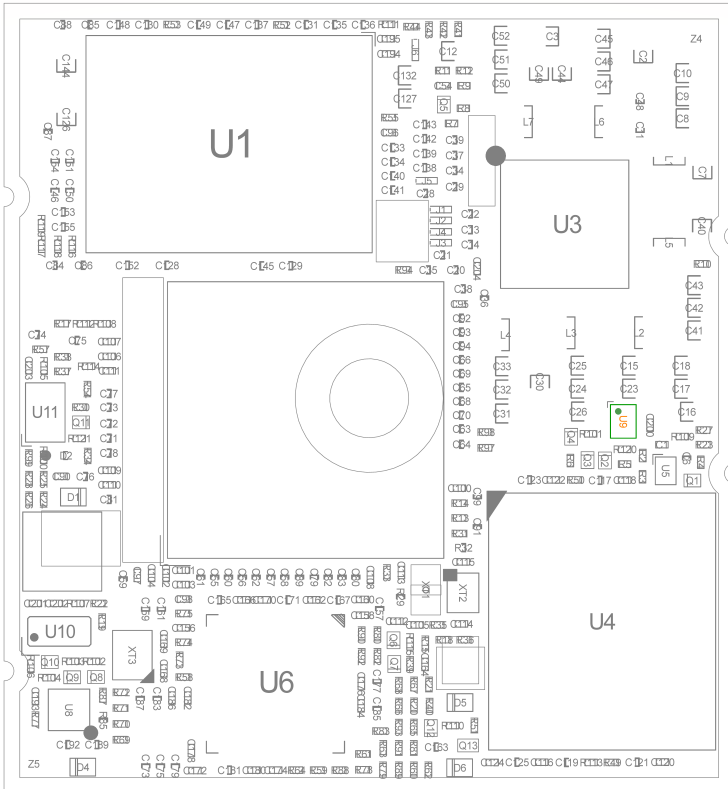
SOM Connector Pin / Libra Development Board Carrier Board Connector Pin	FPSC Signal Mandatory Optional Specialized	SOM Signal Name (CPU Ball)	SOM Voltage Domain	Signal Level	Signal Type	Muxing / Description
U20	RTC_CLKOUT	X_RTC_CLKOUT	VDD_3V3	1.8 V	O	
T21	RTC_nINT	X_RTC_INT	-	-	OD	RTC IRQ output. Needs an external Pull-Up resistor.
AA22	VCC_RTC	X_RTC_VBACKUP	-	3.3 V (1.1 V to 5.5V)	PWR_I	3.3 V backup voltage input. If not needed, pull with 10k to GND.
J54	Specialized	X_RTC_EVTI	VDD_3V3 or X_RTC_VBACKUP	3.3 V or X_RTC_VBACKUP voltage level	I	Event Input of the RTC RV-3028-C7 U9. X_RTC_EVTI has a 100k pull-down and can be left unconnected. Input high level is 0.8xVDD, determined by VDD_3V3 or the voltage level at X_RTC_VBACKUP in backup mode. For more information, refer to the Micro Crystal RV-3028-C7 App-Manual.

19 Temperature Sensor

The phyFLEX-STM32MP2x FPSC supports one temperature sensor. The presence of the sensors depends on the delivery variant of the module.

The external temperature sensor is located at the following position.

FIGURE 4: Temperature Sensor Location



The TMP102 temperature sensor devices used are connected to the I2C bus. TMP102 measures temperatures from -40 °C to +125 °C. For a more detailed description of TMP102, refer to the Texas Instruments *TMP102 Datasheet*.

TABLE 41: I2C1 Temperature Sensor Slave Addresses

I2C Interface for EPROM (RTC, Temp-Sensor) pcb PL1633.1	I2C Interface for EPROM (RTC, Temp-Sensor) pcb PL1633.0 (Alpha SOM)
X_I2C8_SDA/PZ3	I2C7_SDA/PD14
X_I2C8_SCL/PZ4	I2C7_SCL/PD15
	I2C7 is exclusively used for PMIC, therefore on PL1633.0 I2C is not applicable for other devices!

EPROM (RTC, Temp-Sensor) on the same bus has the following address:

TABLE 42: EPROM Temperature Sensor Addresses

EPROM (RTC, Temp-Sensor) Device	I2C slave address
EEPROM U11	0x50/0x58
RTC U10 (optional)	0x52
Temperature Sensors U9 (optional)	0x48

20 Technical Specifications

Warning

Due to changes in functionality and design that are currently being developed, there are several values that cannot be determined in time for the release of this manual. All values with "TBD (To Be Determined)" are currently being evaluated. These values will be added to future manual editions.

The module's profile is max. 4 mm thick, with a maximum component height of the top side. No components on the bottom side. The board itself is approximately 2 mm thick. The phyFLEX-STM32MP2x Footprint can be seen below.

phyFLEX-STM32MP2x FPSC Footprint (top to bottom view; unit in mm)

phyFLEX-STM32MP2x FPSC Footprint (bottom view top down; unit is mm)

Tip

For a downloadable version of the phyFLEX-STM32MP2x FPSC footprint, go to the download section of our product website: [phyFLEX-STM32MP2x FPSC Download Page](#)
Additionally, refer to the "Design-In Guide - FPSC Gamma Feature Set", for this phyFLEX-STM32MP2x, the footprints S, M, and L are applicable.

Additional specifications:

TABLE 43: Technical Specifications

Dimensions:	(37 x 40) mm
Weight:	ca. 9 g
Storage Temperature:	-40 to +85 °C
Operating Temperature:	Product Temperature Grades
Humidity:	10 % - 90 % (non-condensing)
Operating Voltage:	4.75 V .. 5.25 V
Power Consumption:	phyFLEX-STM32MP2x FPSC Power Consumption

These specifications describe the standard configuration of the phyFLEX-STM32MP2x FPSC as of the printing of this manual.

20.1 phyFLEX-STM32MP2x FPSC Power Consumption

The values listed in the table below are guidelines to determine the required dimensions of the power supply circuitry on a carrier board. They do not take application-specific load situations into account. These values have been generated by looking at the maximum power consumption measured using different load scenarios and

adding a voltage source of 5.0 V. These values are based on internal PHYTEC testing. Customers need to consider their application power requirements to ensure they do not generate a load greater than the values listed here.

 **Note**

As we are still testing, there are currently no values for these case scenarios. These values will be given as soon as possible.

TABLE 44: phyFLEX-STM32MP2x FPSC Power Consumption

Required Supply Voltage	5.0 V
Ramp-Up Time (10 %-90 %)	100 μ s to 10 ms
Allowed Tolerance of Supply Voltage	4.75 V .. 5.25 V (Abs. max 5.5 V)
Max. current consumption	1.1 A

For power measurement, a SOM (PFL-G-04) *with tbd. used together with PDx.x.x.*

TABLE 45: phyFLEX-STM32MP2x FPSC Power Consumption Test Scenarios

	Case 1	Case 2	Case 3	Case 4	Case 5	Case 6
eMMC-Boot system idle	TBD	TBD	TBD	TBD	TBD	TBD
<i>iperf3 client end0 (~900MBit/s)</i>	TBD	TBD	TBD	TBD	TBD	TBD
CPU-Load (2x dd from /dev/urandom to /dev/null)	TBD	TBD	TBD	TBD	TBD	TBD
RAM-Load (memtester)	TBD	TBD	TBD	TBD	TBD	TBD
GPU-Load	TBD	TBD	TBD	TBD	TBD	TBD
Power Consumption [Watt]	TBD	TBD	TBD	TBD	TBD	TBD
CPU Thermal Zone 0 [°C]	TBD	TBD	TBD	TBD	TBD	TBD
CPU Thermal Zone 1 [°C]	TBD	TBD	TBD	TBD	TBD	TBD
CPU Surface Temperature [°C]	TBD	TBD	TBD	TBD	TBD	TBD
RAM Surface Temperature [°C]	TBD	TBD	TBD	TBD	TBD	TBD

	Case 1	Case 2	Case 3	Case 4	Case 5	Case 6
Eth-PHY Surface Temperature [°C]	TBD	TBD	TBD	TBD	TBD	TBD
PMIC Surface Temperature [°C]	TBD	TBD	TBD	TBD	TBD	TBD
Ambient [°C]	TBD	TBD	TBD	TBD	TBD	TBD

Additionally, there are some values that cannot be tested. Situations such as suspending to RAM, suspend freeze, and standby mode must be tested on a case-by-case basis to ensure the application's power consumption stays within the guidelines stated above.

 **Tip**

For further information and assistance regarding your application's power consumption, please contact PHYTEC sales.

20.2 Product Temperature Grades

 **Warning**

The right temperature grade for the module greatly depends on the use case. It is necessary to determine if the use case suits the temperature range of the chosen module (see below). A heat spreader can be used if temperature compensation is required.

The feasible operating temperature of the SOM highly depends on the use case of your software application. Modern high-performance microcontrollers and other active parts, such as the ones described within this manual, are usually rated by qualifications based on tolerable junction or case temperatures. Therefore, making a general statement about minimum or maximum ambient temperature ratings for the described SOM is not possible.

However, the above-mentioned parts are available at different temperature qualification levels by the producers. We offer our SOMs in different configurations, making use of those temperature qualifications. To indicate which level of temperature qualification is used for active and passive parts of a SOM configuration, we have categorized our SOMs into three temperature grades.

The table below describes these grades in detail. This table describes a set of components that, in combination, add up to a useful set of product options with different temperature grades. This enables us to make use of cost optimizations depending on the required temperature range.

In order to determine the right temperature grade and whether the minimum or maximum qualification levels are met within an application, the following conditions must be defined by considering the use case:

- Determined the processing load for the given software use case
- Maximum temperature ranges of components (table below)
- Power consumption resulting from a baseload and the calculating power required (in consideration of peak loads as well as time periods for system cooldown)
- Surrounding temperatures and existing airflow in case the system is mounted in a housing
- Heat resistance of the heat dissipation paths within the system, along with the considered usage of a heat spreader or a heat sink to optimize heat dissipation

TABLE 46: Product Temperature Grades

Product Temperature Grade	Controller Range (Junction Temperature)	RAM (Case Temperature)	Other (Ambient)
I	Industrial: -40 °C to +105 °C	Industrial: -40 °C to +95 °C	Industrial: -40 °C to +85 °C
C	Commercial: 0 °C to +95 °C	Consumer: 0 °C to +95 °C	Consumer: 0 °C to +70 °C

21 FPSC Footprint on the phyFLEX-STM32MP2x FPSC

For information on the footprint, mating baseboard footprint, numbering schema, etc., please refer to the corresponding FPSC Gamma Feature Set Specifications [FPSC Gamma Feature Set Specifications \(LAN-118e.A6\)](#).

Pin numbering schema:

[FPSC Gamma Feature Set Specifications \(LAN-118e.A6\) - Pin Numbering](#)

Mating FPSC Baseboard Footprint;

[FPSC Gamma Feature Set Specifications \(LAN-118e.A6\) - Baseboard](#)

22 Interface Signal Trace Length Table

PHYTEC recommends a control delay and trace length for the high-speed interface signals. Signal delay and trace length of the high-speed interface signals routed on the front of the phyFLEX-STM32MP2x FPSC are listed in the following table. Take these values into consideration for the calculation of the overall delay and trace length budgets.

TABLE 47: Interface Signal Trace Length

Signal	Length [μm]		Signal	Length [μm]
tbd.			tbd.	

23 Hints for Integrating and Handling the phyFLEX-STM32MP2x FPSC

23.1 Integrating the phyFLEX-STM32MP2x FPSC

Besides this hardware manual, more information is available to facilitate the integration of the phyFLEX-STM32MP2x FPSC into customer applications.

1. The design of the Libra Development Board can be used as a reference for any customer application.
2. Many answers to common questions can be found at: <https://www.phytec.de/produkte/system-on-modules/phyflex-stm32mp2x-fpsc/#downloads/>
3. The link “Carrier Board” within the category Dimensional Drawing leads to the layout data [phyFLEX-STM32MP2x FPSC Footprint](#). It is available in different file formats. The use of this data allows the user to integrate the phyFLEX-STM32MP2x FPSC SOM as a single component into their design.
4. Different support packages are available for support in all stages of embedded development. Please visit <https://www.phytec.de/support/support-pakete/> or <https://www.phytec.eu/support/support-packages/> or contact our sales team for more details.

23.2 Handling the phyFLEX-STM32MP2x FPSC

23.2.1 phyFLEX Module Modifications

The removal of various components, such as the microcontroller or the standard quartz, is not advisable, given the compact nature of the module. Should this nonetheless be necessary, please ensure that the board, as well as surrounding components and sockets, remain undamaged while desoldering. Overheating the board can cause the solder pads to loosen, rendering the module inoperable. If soldered components need to be removed, the use of a desoldering pump, desoldering braid, an infrared desoldering station, desoldering tweezers, a hot air rework station, or other desoldering method is strongly recommended. Follow the instructions carefully for whatever method of removal is used.

Warning

If any modifications to the module are performed, regardless of their nature, the manufacturer's guarantee may be null and void.

23.2.2 Integrating the phyFLEX into a Target Application

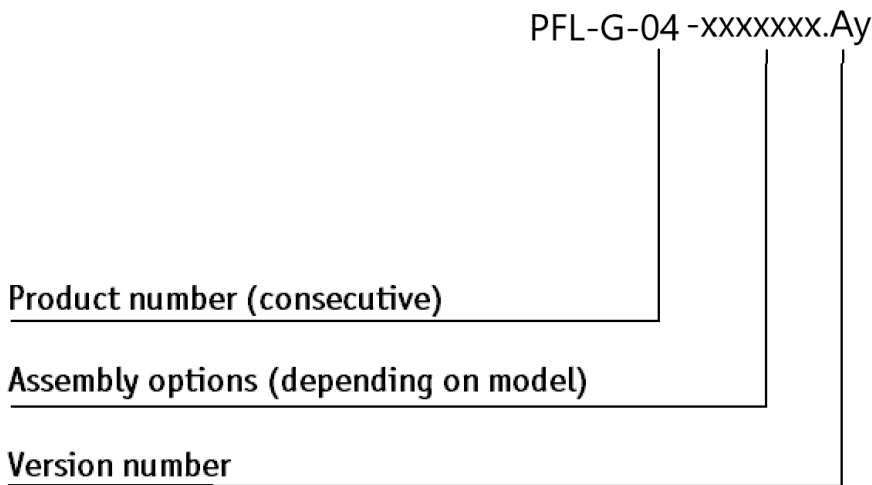
Successful integration in the user target circuitry greatly depends on adherence to the layout design rules for the GND connections of the phyFLEX module. For maximum EMI performance, PHYTEC recommends, as a general design rule, connecting all GND pins to a solid ground plane. At a minimum, all GND-pinned neighboring signals that are being used in the application circuitry should be connected to GND.

✓ **Tip**

Specific details may need to be considered when designing a customer-specific carrier board. For design information on carrier board components, please check the **Design Considerations** in each component section of [phyFLEX-STM32MP2x FPSC on the Libra Development Board](#). Be aware that not all components need to be considered when designing your own carrier board.

23.2.3 Ordering Information

The part numbering of the phyFLEX PFL-G-04 has the following structure:



23.2.4 Product-Specific Information and Technical Support

In order to receive product-specific information on all future changes and updates, we recommend registering at: <http://www.phytec.de/support/registrierung.html> or <http://www.phytec.eu/europe/support/registration.html>

For technical support and additional information concerning your product, please visit the support section of our website, which provides product-specific information, such as errata sheets, application notes, FAQs, etc.

<https://www.phytec.de/produkte/system-on-modules/phyflex-stm32mp2x-fpsc/>

or

<https://www.phytec.eu/en/produkte/system-on-modules/phyflex-stm32mp2x-fpsc/>

24 phyFLEX-STM32MP2x FPSC on the Libra Development Board

24.1 Hardware Overview

The Libra Development Board for phyFLEX-STM32MP2x FPSC is a low-cost, feature-rich software development platform supporting the STMicroelectronics STM32MP2x microcontroller. Due to numerous standard interfaces, the Libra Development Board STM32MP2x can serve as the bedrock for any application. At the core of the Libra Development Board is the PFL-G-04/phyFLEX-STM32MP2x FPSC System On Module (SOM) containing the processor, LPDDR4 RAM, eMMC Flash, power regulation, supervision, transceivers, and other core functions required to support the STM32MP2x processor. Surrounding the SOM is the PCM-937-L/Libra Development Board carrier board, adding power input, buttons, connectors, signal breakout, and Ethernet connectivity, along with other peripherals.

24.2 Libra Development Board Concept

PHYTEC phyFLEX carrier boards are fully equipped with all mechanical and electrical components necessary for a fast, secure start-up. Subsequent communication to and programming of the applicable PHYTEC System on Modules (SOM) is made easy. phyFLEX carrier boards are designed for evaluation, testing, and prototyping of PHYTEC System on Modules in laboratory environments prior to their use in customer-designed applications.

This modular development platform concept includes the following components:

- The **phyFLEX-STM32MP2x FPSC Module** populated with the STM32MP2x microcontroller and all applicable SOM circuitry, such as LPDDR4 SDRAM, eMMC-Flash, Ethernet-PHY, PMIC, etc.
- The **Libra Development Board Carrier Board** offers all essential components and connectors for a start-up, including a power supply for 24 V input voltage and interface connectors such as **LCD**, **USB**, and **Ethernet**, which enable the use of the SOM's interfaces with a standard cable.

The carrier board can also serve as a reference design for developing custom target hardware in which the phyFLEX SOM can be deployed. Carrier board schematics are available under a Non-Disclosure Agreement (NDA). The reuse of carrier board circuitry enables users of PHYTEC SOMs to shorten time-to-market, reduce development costs, and avoid substantial design issues and risks.

SBCplus Concept

The SBCplus concept was developed to meet the many small differences in customer requirements with little development effort. This greatly reduces the time-to-market. The core of the SBCplus concept is the SBC design library (a kind of construction set) that consists of a large number of function blocks (so-called "building blocks") that are continuously being refined and updated.

Recombining these function blocks allows PHYTEC to develop a customer-specific SBC within a short time. We are able to deliver production-ready custom single-board computers within a few weeks at very low costs. The already developed SBCs, such as the Libra Development Board, each represent a combination of different customer wishes. This means all necessary interfaces are already available on the standard versions, allowing PHYTEC SBCs to be integrated into a large number of applications without modification.

For any necessary detail adjustment, extension connectors are available, which enable a wide variety of functions to be added.



Tip

For further information, please contact PHYTEC sales.

24.3 Libra Development Board Features

supports the following features:

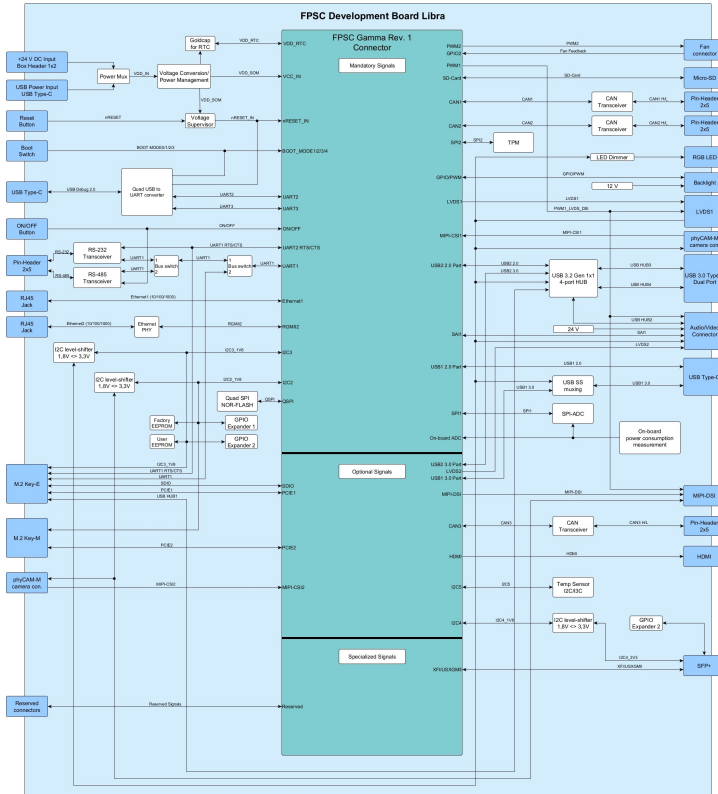
[1]

- Developed under PHYTEC's FPSC concept
- Implements FPSC Featureset Gamma Rev. 1
- Populated with PHYTEC's phyFLEX FPSC SoM (see [phyFLEX SoM Feature List](#))
- Dimensions of 200 mm × 130 mm
- Boot from eMMC, SD Card, or over USB with the Serial Downloader
- 24 V input voltage
- USB-C input power
- 64 MByte QSPI-NOR
- 2 kBit EEPROM
- 2x RJ45 jack for 10/100/1000 Mbps Ethernet
- 1x SFP+ receptacle for 10/100/1000/2500/5000/10000 Mbps Ethernet
- 1x Dual USB 3.0 Type-A connector (Actual USB speed depends on mounted SoM)
- 1x USB-C 3.2 interface connected to phyFLEX FPSC SoM (Actual USB speed depends on mounted SoM)
- 1x Secure Digital / MultiMedia Memory Card interface brought out to a Micro SD-Card receptacle
- 1x HDMI interface brought out to a standard Type-A connector (HDMI availability depends on mounted SoM)
- 1x MIPI-DSI brought out to be used with PEB-AV-12 (MIPI-DSI availability depends on the mounted SoM)
- 2x MIPI-CSI-2 camera interfaces brought out as a phyCAM-M interface (MIPI-DSI availability depends on mounted SoM)
- 1x M.2 Key-E connector with (Key-E interface availability depends on the mounted SoM):
 - 1x PCIe
 - 1x SDIO
 - 1x UART with flow-control
 - 1x I2C
 - 1x USB 2.0 (no protective circuitry on carrier board)
- 1x M.2 Key-M connector with (Key-M interface availability depends on the mounted SoM):
 - 1x PCIe
 - 1x I2C
- RS-232 or RS-485 available at 2x5 pin header 2.54 mm RS-232 (up to Mbps) including a handshake and RS-485 Half-Duplex (up to Mbps)
- Up to 8 ADC input pins (Number of useable ADC input signals depends on the mounted SoM)
- 8-Bit SPI-ADC
- Reset button
- ON/OFF button
- 1x multicolor LED
- 1x PHYTEC Audio/Video connector for PEB-AV-10/13 with:
 - 1x LVDS (LVDS interface availability depends on the mounted SoM)
 - 1x Synchronous Audio Interface
 - 1x USB 2.0 (no protective circuitry on carrier board)
- SAI Audio brought out via an A/V connector
- 1x JTAG at 2x10 pin socket 2.54 mm
- Goldcap backup supply for SoM RTC
- On-board measurement of SoM Power Consumption
- I2C/I3C Temperature Sensor (Temperature Sensor availability depends on I2C capabilities of mounted SoM)
- Trusted Platform Module (TPM)

1. PCM-937-L

24.4 Block Diagram

FIGURE 5: Libra Development Board Block Diagram



24.5 SoM Feature List on the Libra Development Board

There are several SoMs that can be used with the Libra Development Board. Below is a comprehensive list of features that each SoM contains and can be used with the Libra Development Board. For more information, please contact your PHYTEC representative ([Contact Information](#)).

TABLE 48: FPSC Gamma Feature Set Signals

		phyFLEX-i.MX 95	phyFLEX-i.MX 8M Plus	phyFLEX-STM32MP2	phyFLEX-AM62Lx	phyFLEX-i.MX 93	phyFLEX-i.MX 91	phyFLEX i.MX952	phyFLEX SL2610
	Featureset	Gamma	Gamma	Gamma	Gamma Light	Gamma	Gamma Light	Gamma	Gamma Lite
	Subclass	1 / 2 / 3	1 / 2 / 3	1 / 2 / 3	2 / 3	1 / 2 / 3	3	1 / 2 / 3	
Mandatory Signals	RGMII	x	x	x	x	x	x	x	x
	Ethernet	x	x	x	x	x	x	x	x
	USB 2.x	x	x	x	x	x	x	x	x
	USB 2.x	x	x	x	x	x	x	x	x (via onboard HUB)
	LVDS	x	x	x	x	x	NA	x	NA
	MIPI-CSI-2 (2 or 4 lanes)	x	x	x	NA	x	NA	x	x (2 Lanes)
	SD Card	x	x	x	x	x	x	x	x
	QSPI	x	x	x	x	x	x	x	x
	CAN(-FD) (2)	x	x	x	x	x	x	x	x

	UART+Flow (2)	x	x	x	x	x	x	x	x
	UART	x	x	x	x	x	x	x	x
	SPI+CS (2)	x	x	x	x	x	x	x	x
	I2C (2)	x	x	x	x	x	x	x	x
	PWM (2)	x	x	x	x	x	x	x	x
	SAI 2-Lane	x	x	x	x	x	x	x	x (w/o TDM)
	JTAG	x	x	x	x	x	x	x	x
	PWR_IN	x	x	x	x	x	x	x	x
	Control/Misc	x	x	x	x	x	x	x	x
	GPIO (4)	x	x	x	x	x	x	x	x
Optional Signals	USB 3.x (1-2)	1	2	1	0	0	0	0	0
	LVDS	1	1	1	0	0	0	1	0
	MIPI-DSI	1	1	1	1	1	0	1	1

	MIPI-CSI (2 or 4 lanes)	1	1	0	0	0	0	1 (2 Lanes)	0
	HDMI/eARC	0	1	0	0	0	0	0	0
	PCIe 2-Lane (1-2)	2	1	1	0	0	0	1	0
	CAN(-FD)	0	0	0	1	0	0	0	0
	SDIO4	1	1	1	1	0	0	1	1
	SPI+CS	1	1	1	1	0	0	1	0
	I2C (1-2)	1	1	2	1	0	0	2	1
	PWM (1-2)	2	2	2	2	0	0	2	2
	ADC (1-8)	8	0	4 (5)	4	4	4	8	8
	GPIO (1-3)	3	3	3	3	0	0	3	3
Specialized Signals	10G Ethernet	1	0	0	0	0	0	0	0
	USB 3 SS Signals	1	0	1 (or PCIe)	0	0	0	0	0

	GPIO	1	4	4	4	0	0	7	5
--	------	---	---	---	---	---	---	---	---

24.6 Temperature Range

Most components on the Libra Development Board have an operating temperature range of -40 °C to 85 °C. The following components are the exception:

TABLE 49: Libra Development Board Component Temperature Range

BOM No.	Component Description	Temperature Range	Advice
C111	Double-layer capacitor for RTC Backup	-25 °C to 70 °C	
X37	HDMI Connector	-25 °C to 85 °C	There is no replacement available
X43	LVDS1 Data Connector	-35 °C to 85 °C	There is no replacement available
X44	LVDS1 Backlight Connector	-25 °C to 85 °C	There is no replacement available
X68	Fan Connector	-35 °C to 85 °C	
X60	Micro SD-Card Slot	-25 °C to 85 °C	The SD-Card slot can be used in the range of -40 °C to 85 °C without mechanical changes

For this reason, the operation temperature range for the kit variant is: -25 °C to 70 °C. The storage temperature range is -40 °C to 85 °C.

24.7 Mechanical Dimensions

For detailed dimensions, refer to the provided CAD data (e.g., DXF file) in the download section of our specific FPSC SoMs:

- [phyFLEX-i.MX 95 FPSC](#)
- [phyFLEX-i.MX 8M Plus FPSC](#)
- [phyFLEX-STM32MP2x FPSC](#)
- [phyFLEX-AM62Lx FPSC](#)
- [phyFLEX-i.MX 91/93 FPSC](#)
- [phyFLEX-AM62P FPSC \(COMING SOON\)](#)

25 Libra Development Board Components

Tip

For high-resolution pictures of the Libra Development Board, please go to the download section of our specific FPSC SoMs.

Note

For easy reference, Pin 1 for each component has been highlighted.

25.1 Libra Development Board Component Placement Diagram

FIGURE 6: Libra Development Board Components (Top)

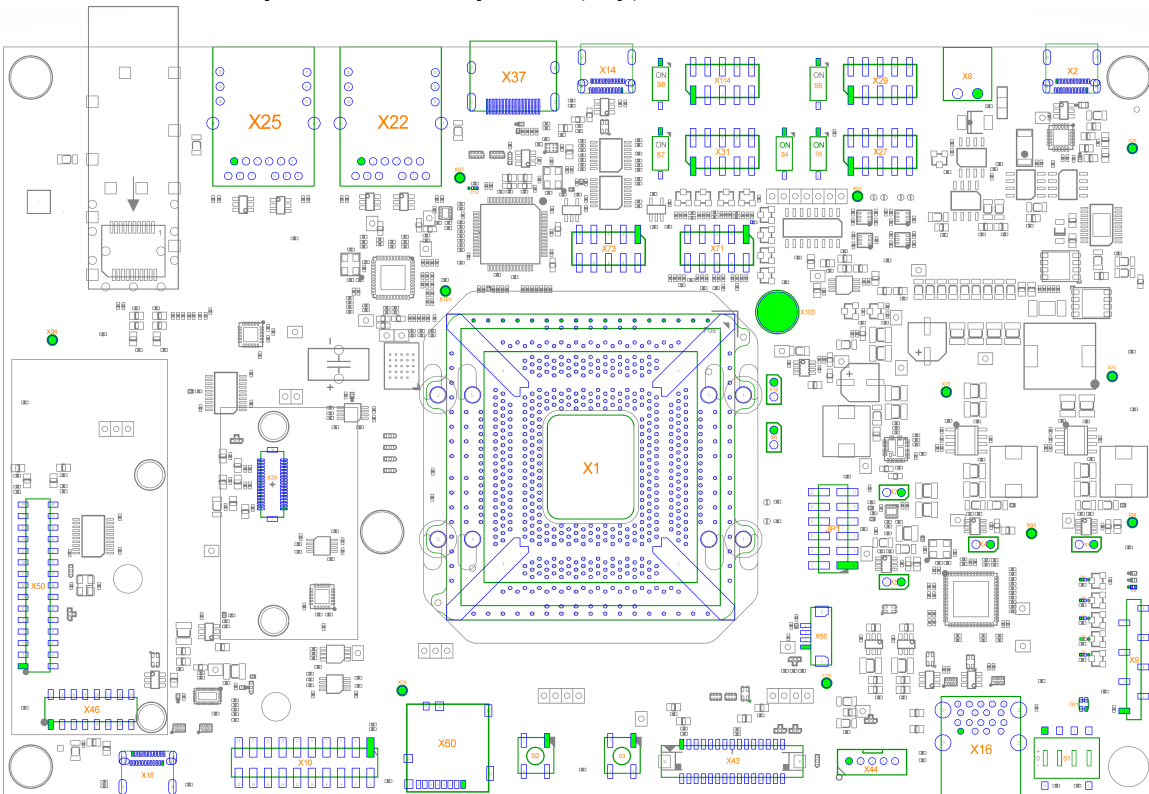
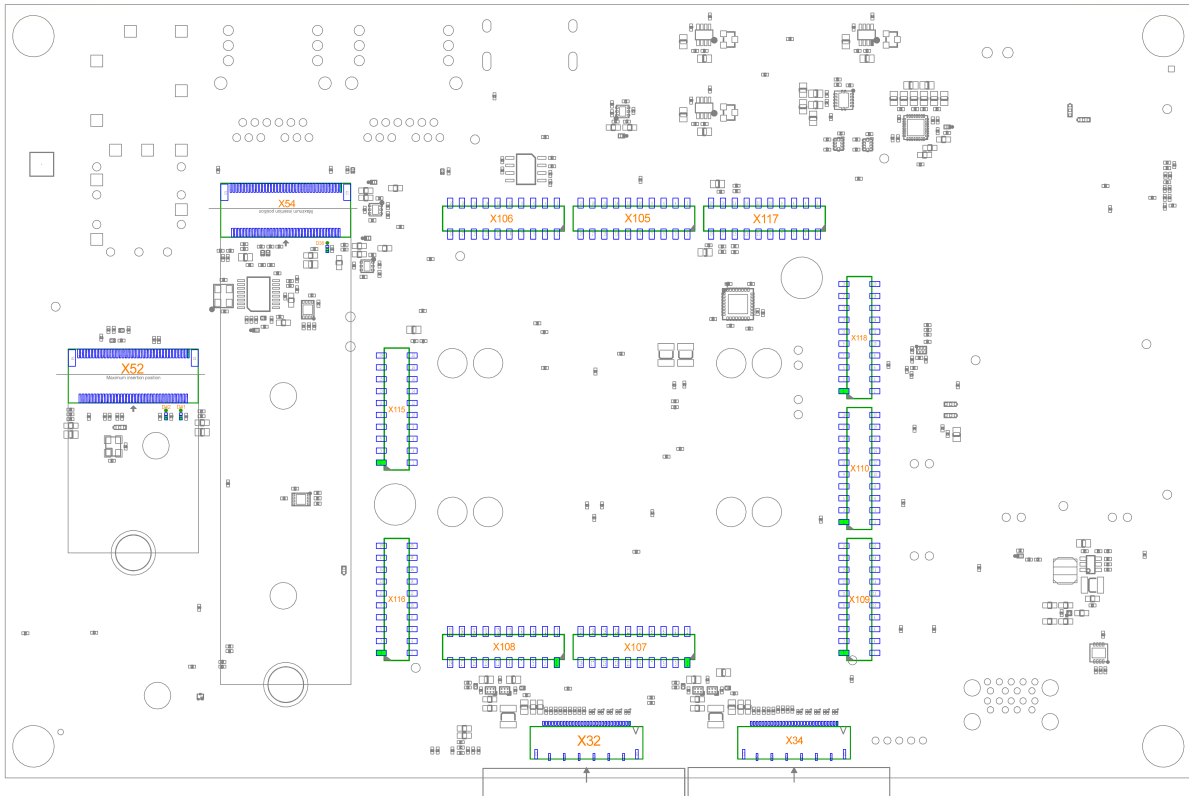


FIGURE 7: Libra Development Board Components (Bottom)



25.2 Libra Development Board Component Overview

The Libra Development Board features many interfaces and is equipped with the components listed in the table [Connectors and Pin Header](#). For a more detailed description of each component, refer to the appropriate section listed in the table below. [Libra Development Board Components \(Top\)](#) and [Libra Development Board Components \(Bottom\)](#) highlight the location of each component for easy identification.

25.2.1 Connectors and Pin Header

The table below lists all available connectors on the Libra Development Board.

TABLE 50: Libra Development Board Connectors and Pin Headers

Reference Designator	Description	Section
X1	SoM FPSC solder connection	phyFLEX Connector (X1)
X2	Carrier board power in USB-C	Power Supply (X2/X8)
X3	VDD_5V0 current amp header 2,54 mm (not mounted)	
X4	VDD_3V3 current amp header 2,54 mm(not mounted)	
X5	VDD_1V8 current amp header 2,54 mm(not mounted)	
X6	SoM 3,3 V output header 2,54 mm(not mounted)	
X7	SoM 1,8 V output header 2,54 mm (not mounted)	
X8	Carrier board power in a 2-pin connector	Power Supply (X2/X8)
X9	Boot Mode manipulation header	Boot Header (X9)
X10	JTAG header 2,54 mm voltage level 1,8 V	JTAG (X10)

Reference Designator	Description	Section
X12	SoM input current amp header 2,54 mm(not mounted)	SoM Input Current Amp Header (X12)
X14	USB-C-Debug	USB Debug (X14)
X16	Dual USB-A 3.0	USB Type-A 3.0 Interface (X16)
X18	Dual-role USB-C 3.2	USB-C 3.2 GEN 1 Interface (X18)
X22	Ethernet Gigabit RJ-45	Ethernet (X22/X25)
X25	Ethernet Gigabit RJ-45	
X27	RS232/RS485 10-pin header 2,54 mm	RS-232/RS-485 (X27)
X29	CAN-FD1 10-pin header 2,54 mm	CAN FD (X29/X31/X114)
X31	CAN-FD2 10-pin header 2,54 mm	
X114	CAN-FD3 10-pin header 2,54 mm	
X32	phyCAM-M CSI1	phyCAM-M MIPI CSI Camera Connectors (X32/34)
X34	phyCAM-M CSI2	

Reference Designator	Description	Section
X37	HDMI	HDMI (X37)
X39	MIPI-DSI 36-pin board-to-board	MIPI-DSI (X39)
X43	LVDS1 data connector	LVDS1 (X43/X44)
X44	LVDS1 backlight connector	
X46	LVDS2 AV-Connector display data 16-pin header 2 mm	Audio/Video (LVDS2/SAI1)
X50	AV-Connector audio + control 30-pin header 2 mm	
X52	M.2 Key-E	M.2 Key-E (X52)
X54	M.2 Key-M	M.2 Key-M (X54)
X60	Micro SD-Card receptacle	Secure Digital Memory Card / MultiMedia Card (X60)
X68	Fan Connector 4-pin	Fan (X68)
X71	SPI-ADC input 10-pin header 2,54 mm	SPI-ADC (X71)

Reference Designator	Description	Section
X73	ADC input 10-pin header 2,54 mm	ADC (X73)
X74, X75, X76, X79, X88, X89, X92, X93, X96, X97, X100, X101	GND Stud	
X105-X110, X115-X118	FPSC reserved a 20-pin socket 2 mm	

Warning

Ensure that all module connections do not exceed their expressed maximum voltage or current. Maximum signal input values are indicated in the corresponding controller User's Manual/Data Sheets. As damage from improper connections varies according to use and application, the user must take appropriate safety measures to ensure that the module connections are protected from overloading through connected peripherals.

25.2.2 LEDs

FIGURE 8: Libra Development Board LEDs (Top)

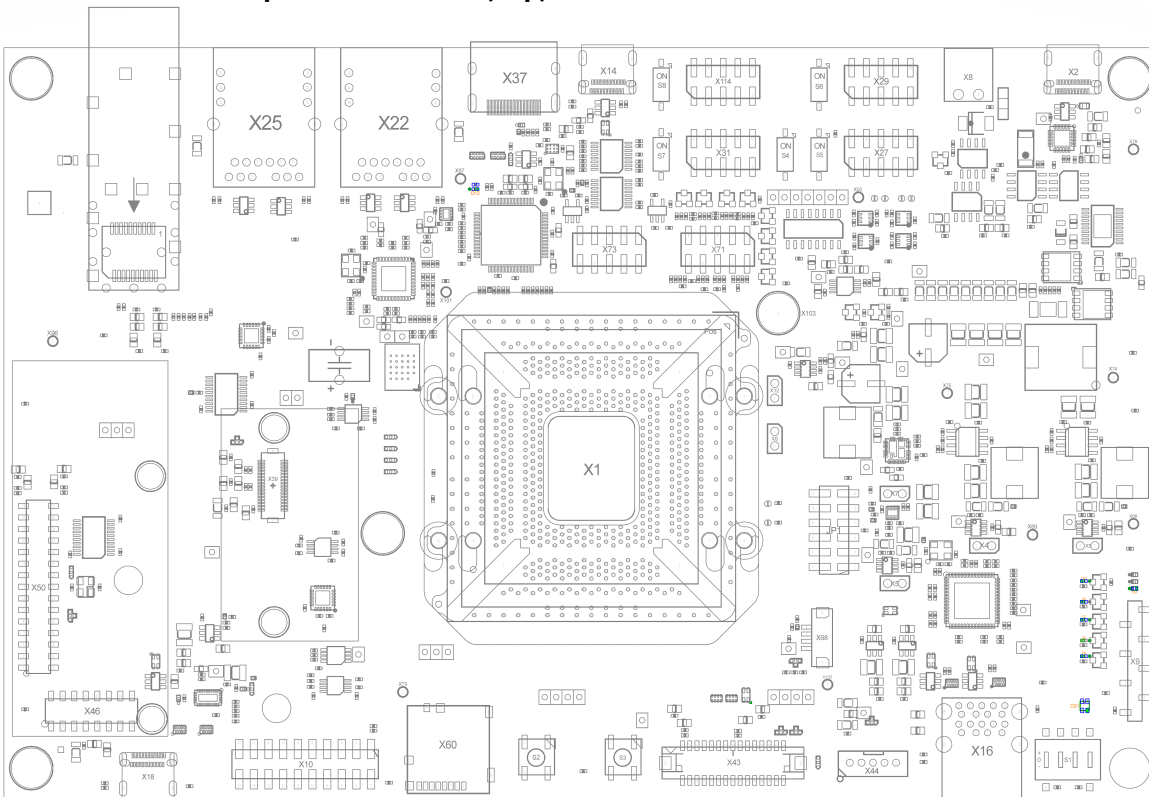
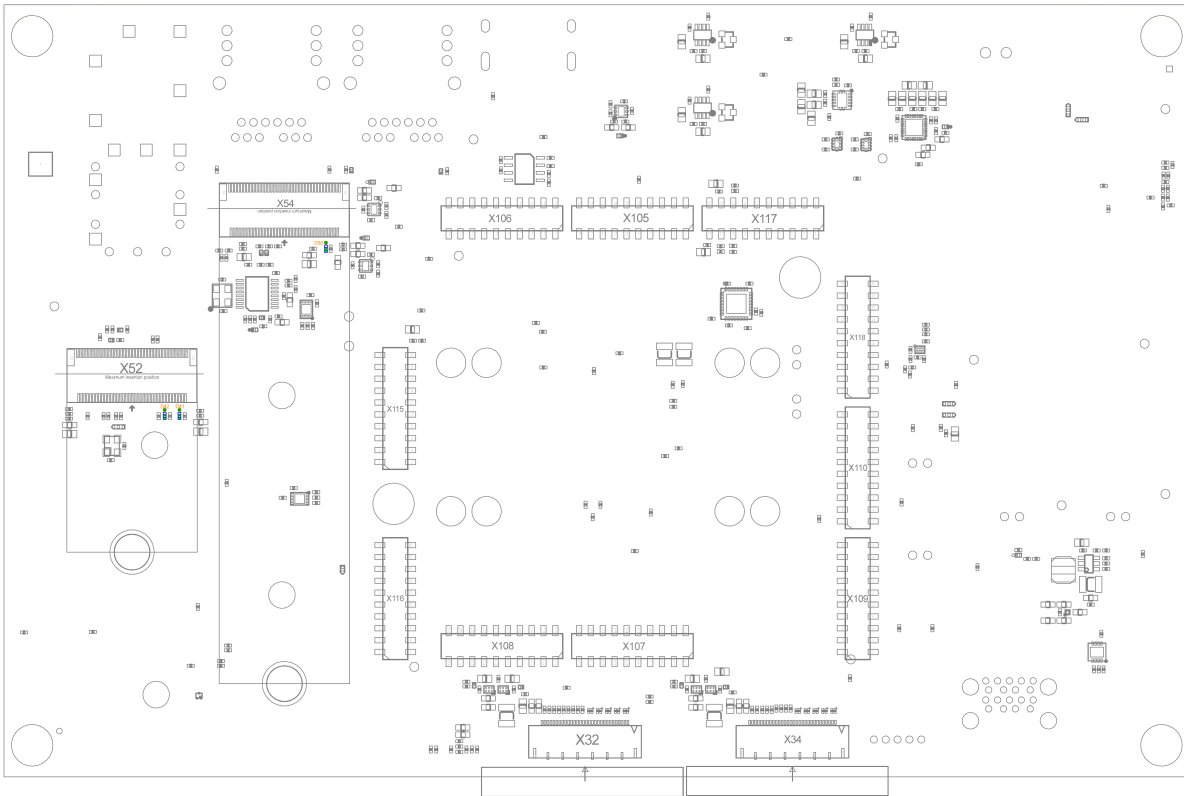


FIGURE 9: Libra Development Board LEDs (Bottom)



The Libra Development Board is populated with 7 LEDs. [Libra Development Board Components \(Top\)](#) and [Libra Development Board Components \(Bottom\)](#) show the location of the LEDs. Their functions are listed in the table below:

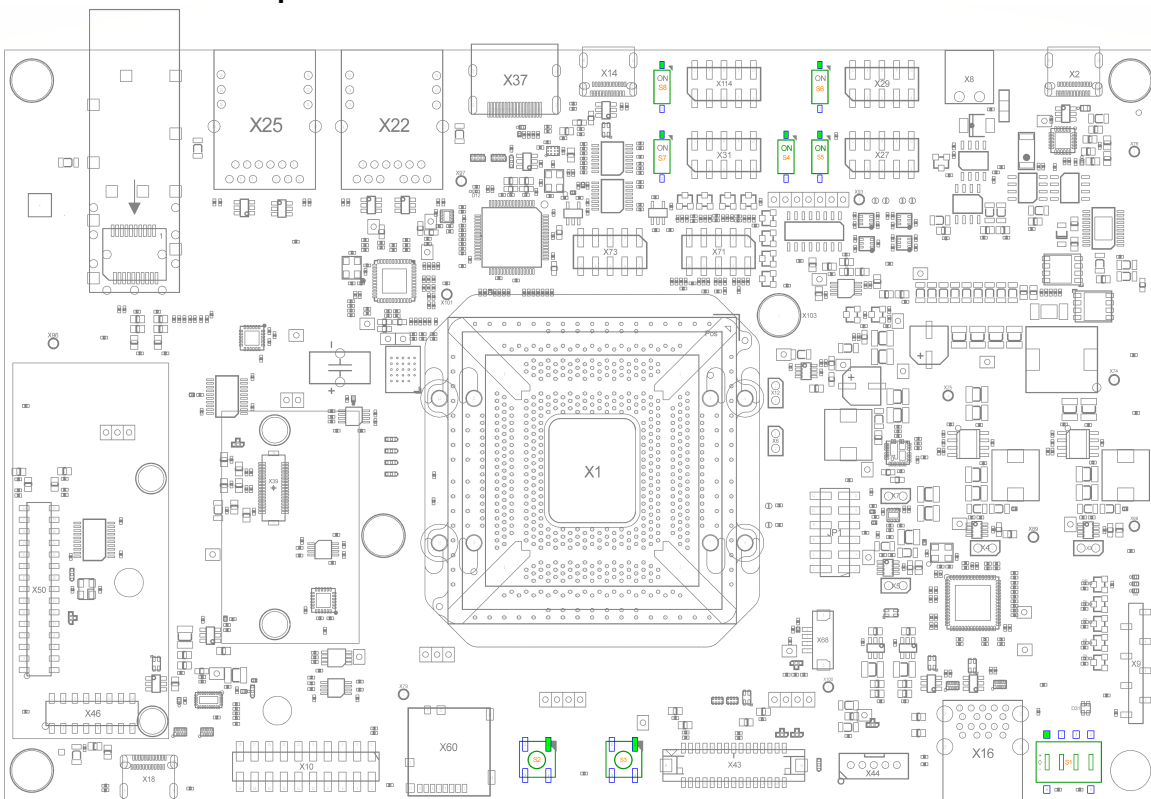
TABLE 51: Libra Development Board LED Descriptions

LED	Color	Description	Section
D6	Blue	VDD_5V0 good indicator	
D7	Blue	VDD_3V3 good indicator	
D8	Blue	VDD_1V8 good indicator	
D9	Blue	VDD_SOM good indicator	
D12	Red	Debug USB-C VBUS good indicator	
D30	Yellow	M.2 SSD activity indicator	
D31	RGB	Multi-color LED user-controllable	Multicolor (RGB) LED (D31)

LED	Color	Description	Section
D41	Yellow	M.2 status LED 1#	
D42	Yellow	M.2 status LED 2#	
D43	Blue	VDD_12V0 good indicator	

25.2.3 Switches and Buttons

FIGURE 10: Libra Development Board Switch Locations



The Libra Development Board is populated with multiple switches and buttons. The table below shows their functions:

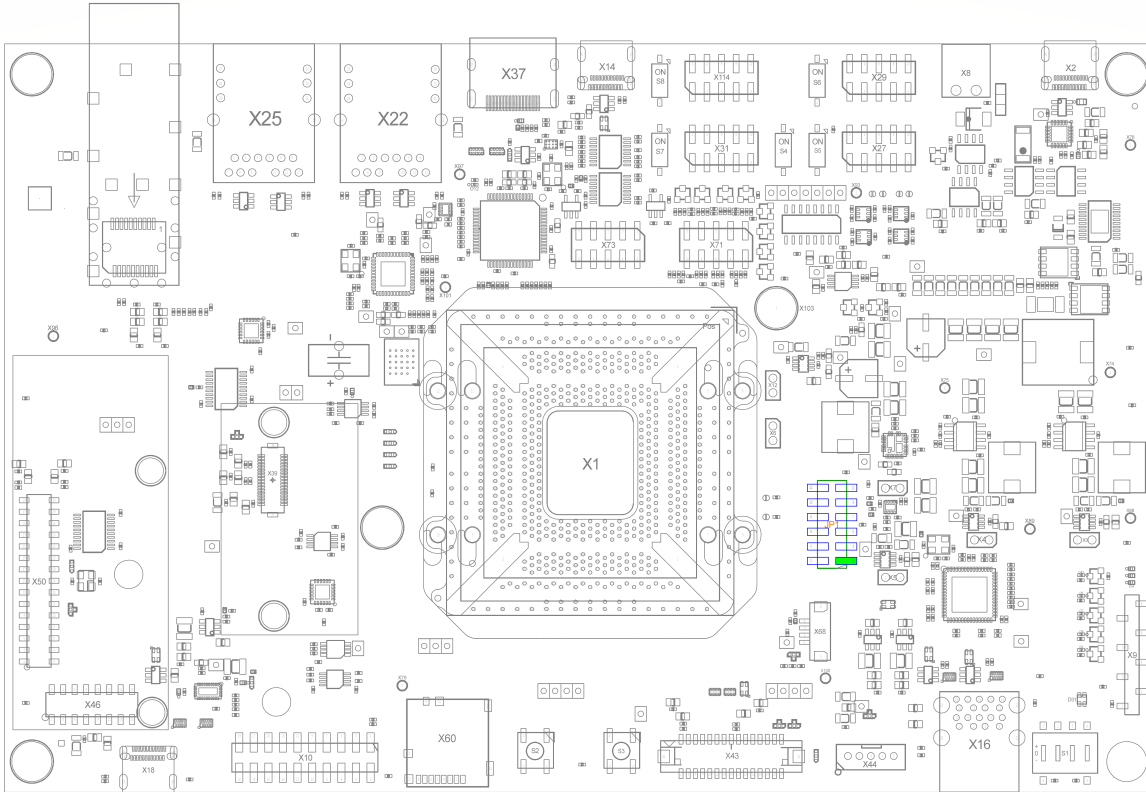
TABLE 52: Libra Development Board Switches

Switch	Description	Section
S1	4-port tri-state Boot Mode switch	Boot Switch (S1)
S2	Reset push button	System Reset Button (S2)
S3	ON/OFF push button	System ON/OFF Button (S3)

Switch	Description	Section
S4	RS485 termination switch ON: Bus is terminated with 120 Ω OFF: Bus is not terminated	
S5	UART1 target switch ON: UART1 is converted to RS232 OFF: UART1 is converted to RS485	
S6	CAN FD1 termination switch ON: Bus is terminated with 120 Ω OFF: Bus is not terminated	
S7	CAN FD2 termination switch ON: Bus is terminated with 120 Ω OFF: Bus is not terminated	
S8	CAN FD3 termination switch ON: Bus is terminated with 120 Ω OFF: Bus is not terminated	

25.2.4 Jumpers

FIGURE 11: Jumper (JP1)



The Libra Development Board comes pre-configured with several removable jumpers (JP) and solder jumpers (J). These jumpers enable the flexible configuration of a limited number of features for development purposes.

⚠ Warning

Due to the small footprint of the solder jumpers (J), PHYTEC does not recommend manual jumper modifications. This may also render the warranty invalid. Only the removable jumper (JP) is described in this section. Contact our sales team if you need jumper configurations different from the default configuration.

The function of the removable jumper on the Libra Development Board is shown below. More detailed information can be found in the appropriate section.

TABLE 53: Libra Development Board Jumper Settings

Jumper	Position	Default	Description	Section
JP1		1+2 3+4 5+6 9+10	UART3_RXD - USB Debug 1 UART3_TXD - USB Debug 1 UART2_RXD - USB Debug 2 UART2_TXD - USB Debug 2	

25.3 Libra Development Board Component Detail

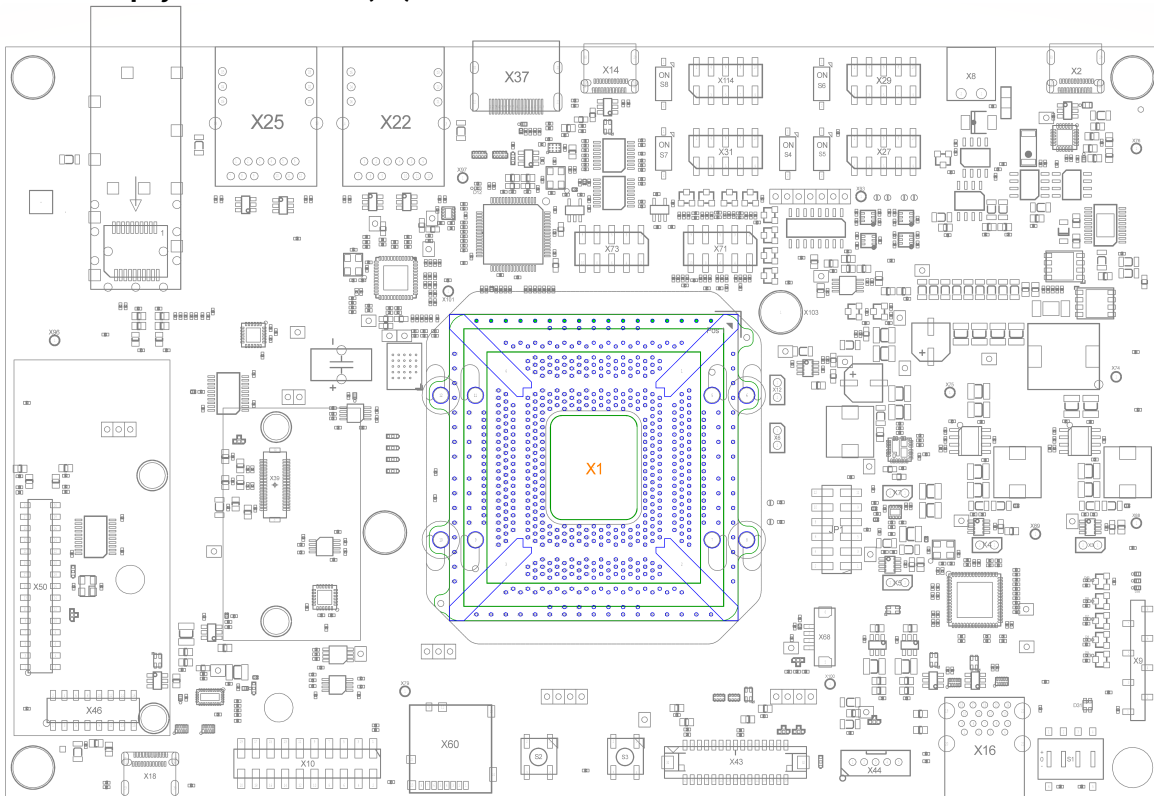
This section provides a more detailed look at the Libra Development Board components. Each subsection details a particular connector/interface and associated jumpers for configuring that interface.

Tip

Where possible, we also provide useful information regarding design considerations for components. This can be used if you plan to design your own carrier board.

25.3.1 phyFLEX Connector (X1)

FIGURE 12: phyFLEX Connector (X1)

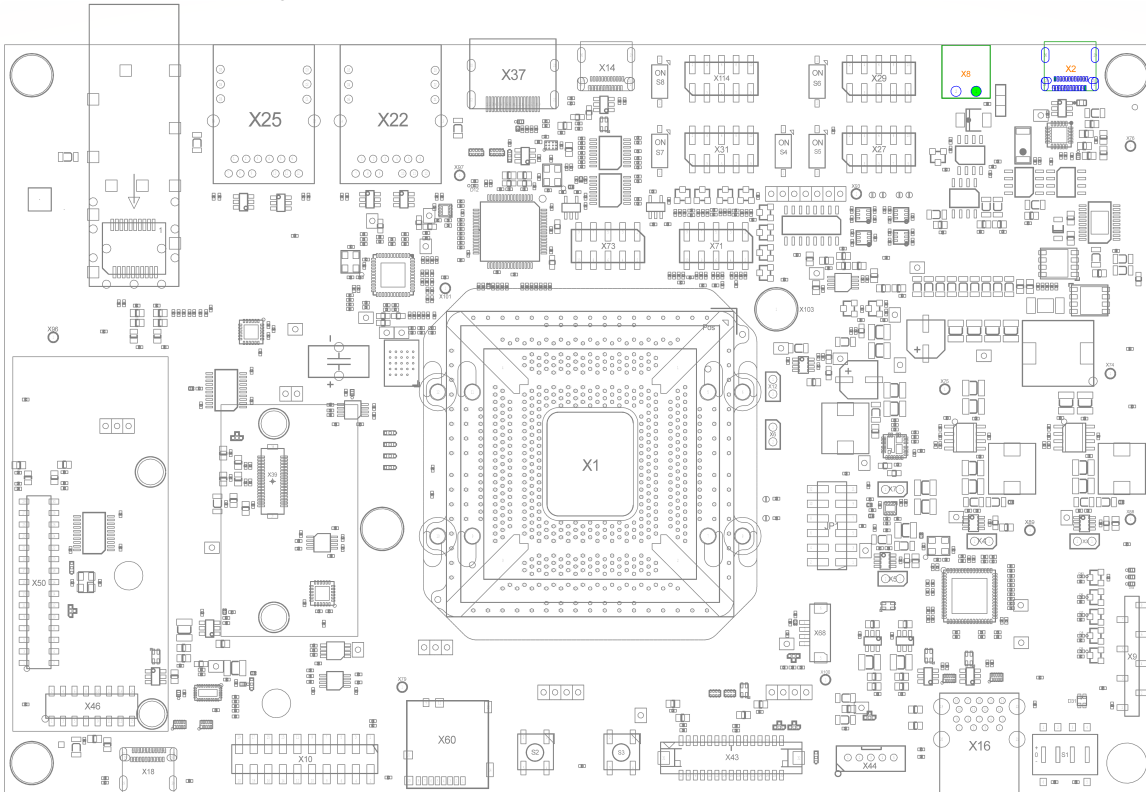


25.3.2 Power Supply (X2/X8)

Warning

Do not change modules or jumper settings while the Libra Development Board is supplied with power!

FIGURE 13: Power Supply Connectors (X2/X8)



The Libra Development Board can be powered either by a 2-pole Phoenix Contact MINI COMBICON base strip 3.5 mm connector (X8) or by a USB Power Delivery Supply (X2).

⊗ Warning

Do not power the Libra Development Board via X2 and X8 at the same time!
Do not connect a USB device that is not a certified USB Power Delivery supply to X8!

The Libra Development Board is available with one power supply connector, a 2-pole Phoenix Contact MINI COMBICON base strip 3.5 mm connector (X8) suitable for a single 24 V supply voltage. The required capacity for all power supply solutions depends on the specific configuration of the phyFLEX-SoM mounted on the Libra Development Board, the particular interfaces enabled while executing software, as well as whether an optional expansion board is connected to the carrier board.

The permissible input voltage is 24 V DC if your Development Board is equipped with a 2-pole Phoenix Contact MINI COMBICON base strip. A 24 V power supply capable of providing at least 3.5 A is recommended to power the board via the 2-pole base strip. The pin assignment for power supply connector X8:

TABLE 54: X8 Pin Assignment

Interface Pin #	Signal	Description
1	VDD_IN_PWR_CON	24 V ± 10%, 85 W
2	GND	Ground

25.3.2.1 USB Power Delivery Connector (X2)

The Libra Development Board can be powered by a USB Power Delivery Supply. The Libra Development Board provides the needed voltage and current from the connected supply and enables the on-board voltages. A 85 W USB-PD supply is recommended to power the Libra Development Board.

Note

Please note that connector X2 is only usable as a power supply input. It doesn't offer any USB communication interface functionality. Only use a certified USB Power Delivery supply.

25.3.2.2 RTC Backup Supply

The Libra Development Board has a double-layer capacitor equipped to back up the VDD_RTC rail of the phyFLEX FPSC SoM. The capacitor is also charged through a diode circuit from VDD_3V3. The mounted 330 mF capacitor is capable of backing up the SoM RTC for at least (TBD) at 25 °C.

25.3.3 UART

The Libra Development Board features 3 UART interfaces. This paragraph describes their default and alternative purposes.

UART1 (full flow control) is configurable to provide one of three functions via 2 integrated switches (U38/U40) and one hardware switch S5. The following table explains the necessary settings for a desired UART1 target:

TABLE 55: UART1 Target Selection

UART1 Target	S5	U38	U40
Bluetooth over M.2 Key-E	X	UART1_BT_RS_SEL = 1 Default = 0	X
RS232 at X27 through U37	0	UART1_BT_RS_SEL = 0	UART1_RS232_485_SEL = 1 S5 override GPIO
RS485 at X27 through U39	1	UART1_BT_RS_SEL = 0	UART1_RS232_485_SEL = 0 S5 override GPIO

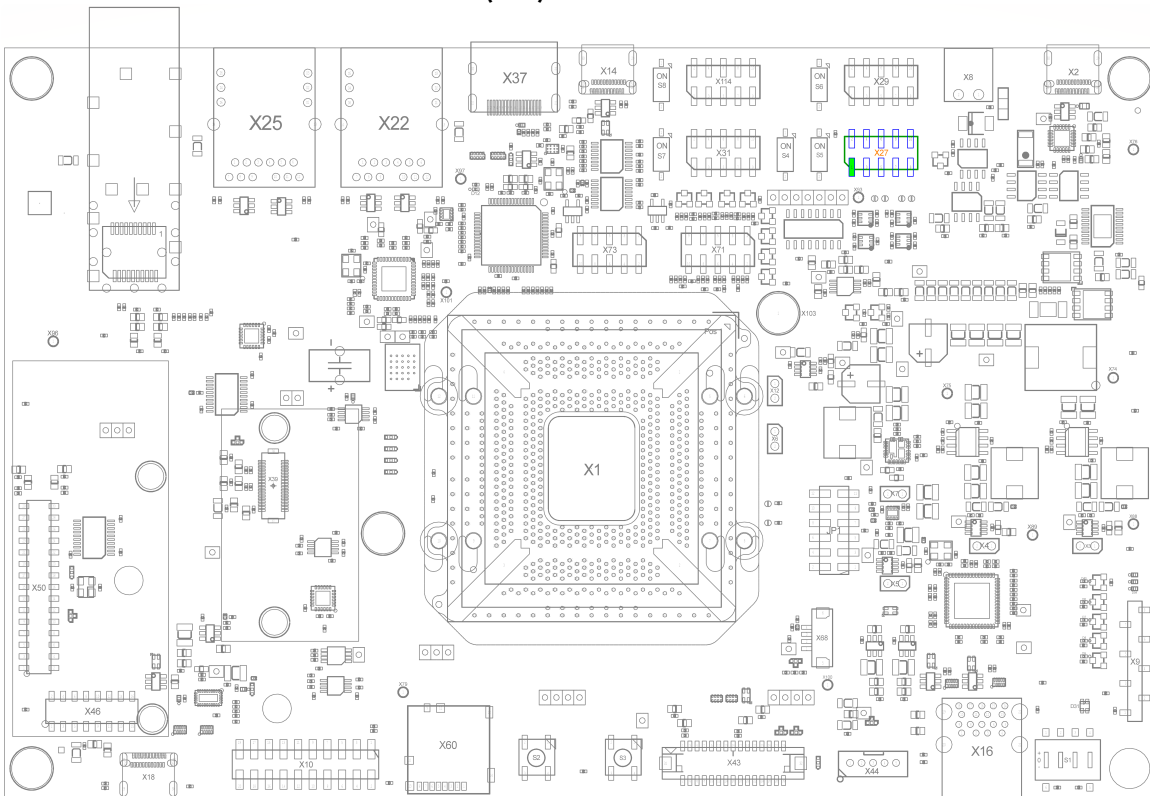
UART2 (full flow control) is connected to the USB debug channel 2 via the default setting of JP1. UART3 is connected to the USB debug channel 1 via the default setting of JP1.

25.3.3.1 UART Design Considerations

When designing a custom carrier board, remember the FPSC output TTL level is 1.8 V.

25.3.4 RS-232/RS-485 (X27)

FIGURE 14: RS-232 and RS-485 Connector (X27)



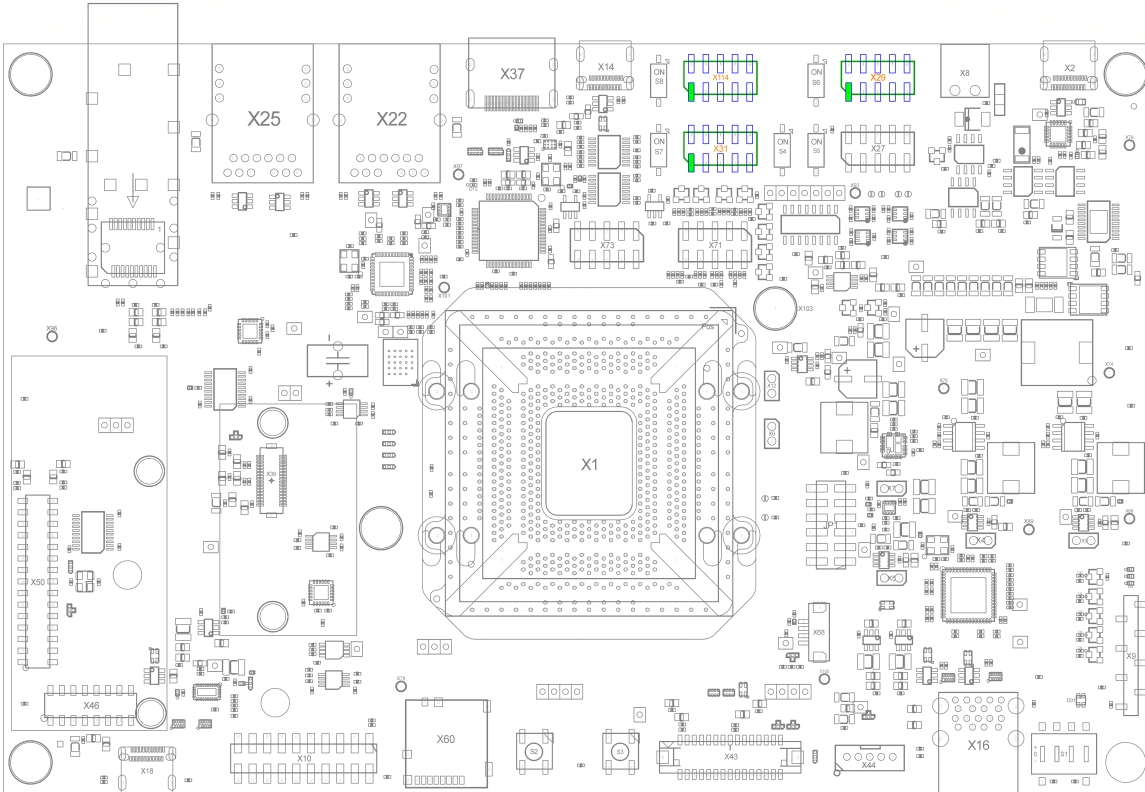
Pin header connector X27 provides the UART1 signals of the phyFLEX FPSC SoM as either RS-232 or RS-485 signal. Mode is selected by routing UART1 to the applicable converter. Please refer to the [UART1 Target Selection](#). The RS-232 interface is intended to be used as data terminal equipment (DTE) and allows for a 5-wire connection, including the signals RTS and CTS for hardware flow control. RS-485 is available in Half-Duplex (4-wire). The table below shows the signal mapping of the RS-232 and RS-485 level signals at connector X27.

TABLE 56: RS-232/RS-485 (X27) Pin Assignment

Interface Pin #	Signal Name	Signal Type	Signal Level	Description
1	NC	-	-	No connect
2	NC	-	-	No connect
3	X_RS232_RXD	I	-	RS232 receive data
4	X_RS232_RTS	O	-	RS232 request to send
5	X_RS232_TXD	O	-	RS232 transmits data
6	X_RS232_CTS	I	-	RS232 clear to send
7	X_RS485_A	I/O	-	RS485 non-inverted
8	X_RS485_B	I/O	-	RS485 inverted
9	GND	-	0.0 V	Ground
10	GND	-	0.0 V	Ground

25.3.5 CAN FD (X29/X31/X114)

FIGURE 15: CAN FD (X29/X31/X114)



The phyFLEX FPSC SoM FLEXCAN1, FLEXCAN2, and FLEXCAN3 interfaces are brought out at X29, X31 and X114, each as CAN FD. The maximum permissible CAN FD data rate is 8 Mbit/s. For development purposes, a 120 Ω termination can be added by closing SW5 (CAN1), SW6 (CAN2) or SW8 (CAN3). For standard use, it is possible to mount a more suitable split termination in a customer-specific BOM.

The pinout is chosen to fit the official standard CAN pinout and is displayed in the table below.

TABLE 57: CAN FD1 (X29) Pin Assignment

Interface Pin #	Signal Name	Signal Type	Signal Level	Description
1	NC	-	-	No connect
2	GND	-	0.0 V	Ground
3	X_CAN1_L	CAN_I/O	-	Low-level CAN bus input/output line
4	X_CAN1_H	CAN_I/O	-	High-level CAN bus input/output line
5	GND	-	0.0 V	Ground
6	NC	-	-	No connect
7	NC	-	-	No connect
8	NC	-	-	No connect
9	NC	-	-	No connect
10	NC	-	-	No connect

TABLE 58: CAN FD2 (X31) Pin Assignment

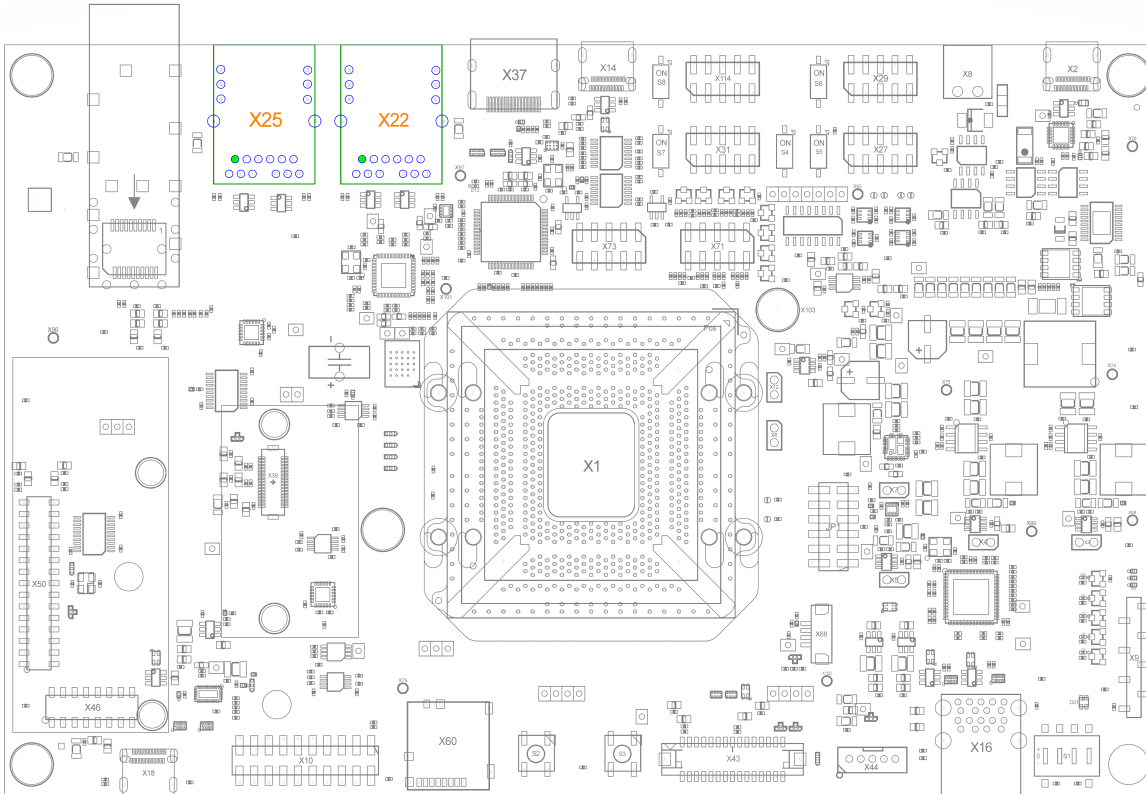
Interface Pin #	Signal Name	Signal Type	Signal Level	Description
1	NC	-	-	No connect
2	GND	-	0.0 V	Ground
3	X_CAN2_L	CAN_I/O	-	Low-level CAN bus input/output line
4	X_CAN2_H	CAN_I/O	-	High-level CAN bus input/output line
5	GND	-	0.0 V	Ground
6	NC	-	-	No connect
7	NC	-	-	No connect
8	NC	-	-	No connect
9	NC	-	-	No connect
10	NC	-	-	No connect

TABLE 59: CAN FD3 (X114) Pin Assignment

Interface Pin #	Signal Name	Signal Type	Signal Level	Description
1	NC	-	-	No connect
2	GND	-	0.0 V	Ground
3	X_CAN3_L	CAN_I/O	-	Low-level CAN bus input/output line
4	X_CAN3_H	CAN_I/O	-	High-level CAN bus input/output line
5	GND	-	0.0 V	Ground
6	NC	-	-	No connect
7	NC	-	-	No connect
8	NC	-	-	No connect
9	NC	-	-	No connect
10	NC	-	-	No connect

25.3.6 Ethernet (X22/X25)

FIGURE 16: Ethernet Connectors (X22/X25)



The Libra Development Board is equipped with 2 RJ45 connectors. The table below describes the properties of each Ethernet interface:

TABLE 60: RJ45 Ethernet connectors X22/X25

Interface Name	Ethernet Connector	Interface Description
Ethernet2	X22	10/100/1000 Ethernet interface over a Gigabit Ethernet transceiver on a carrier board
Ethernet1	X25	10/100/1000 Ethernet interface over a Gigabit Ethernet transceiver on a mounted SoM

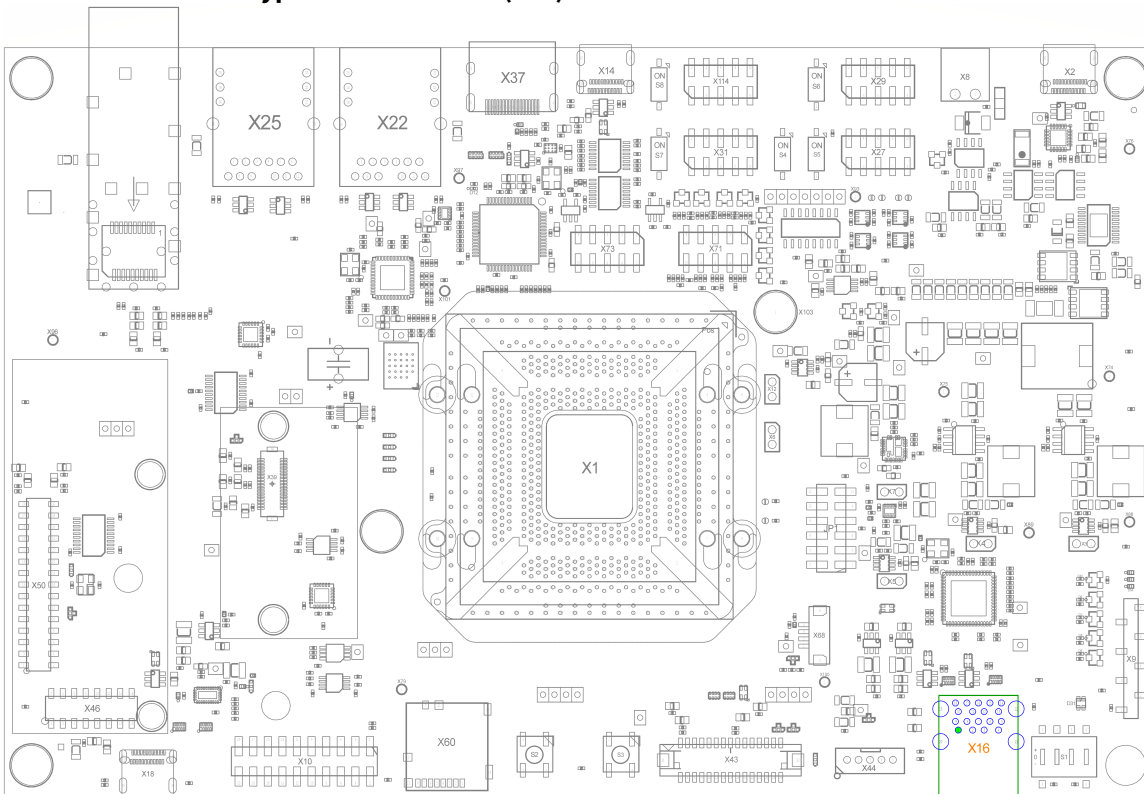
The LEDs for LINK (green) and ACTIVITY (orange) indications are integrated into the connector. The Ethernet transceivers support Auto MDI-X, eliminating the need for a direct connect LAN or cross-over path cable. They detect the TX and RX pins of the connected device and automatically configure the PHY TX and RX pins accordingly.

25.3.6.1 Ethernet Design Considerations

The data lanes should be routed with a differential impedance of 100 Ohms. The center taps of each pair's transformer have to be connected to GND through a 100nF capacitor. The LED pins are open-drain outputs of the SoM without a resistor, so they should be connected to the cathodes of the LEDs through a resistor.

25.3.7 USB Dual Type-A 3.0 Interface (X16)

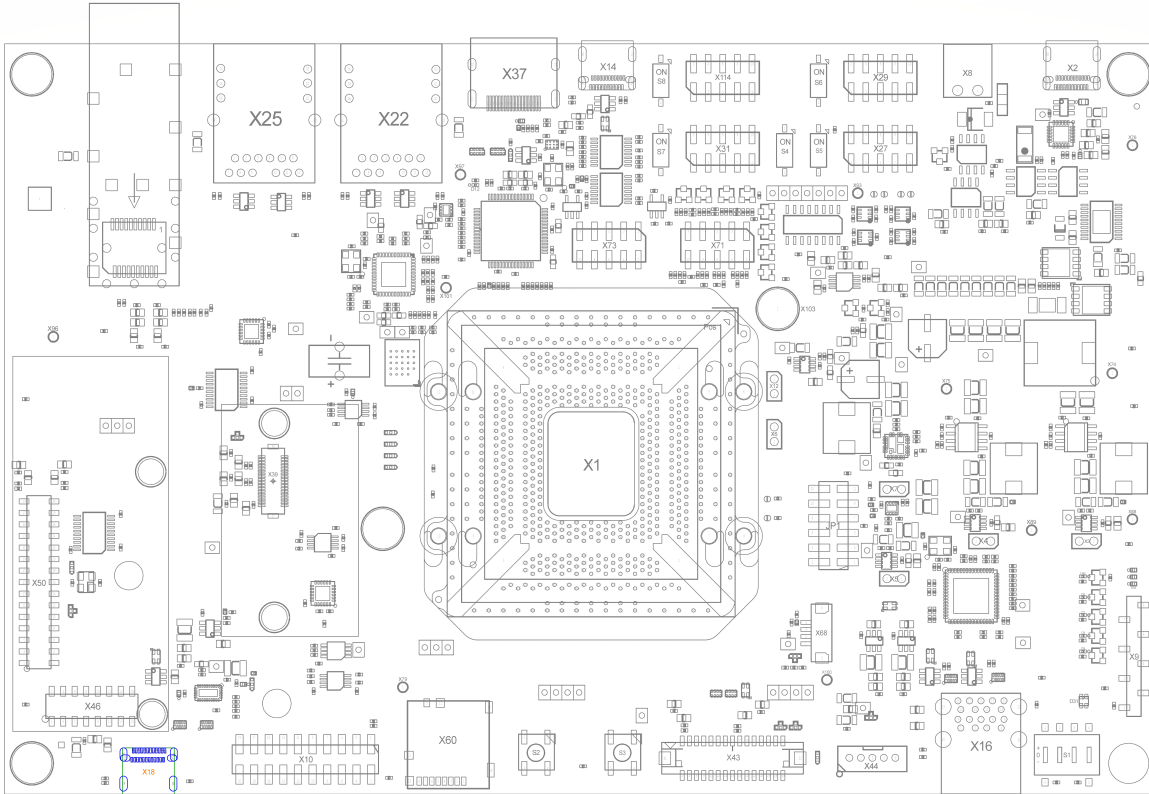
FIGURE 17: USB Dual Type-A 3.0 Connector (X16)



The Libra Development Board provides two USB 3.0 interfaces at the USB Dual Type-A connector X16. They are HOST interfaces made available through a 4-port USB HUB. USB1 will be at the connector's top and USB2 at the bottom receptacle.

25.3.8 USB-C 3.2 GEN 1 Interface (X18)

FIGURE 18: USB 3.2 Gen1 Connector (X18)



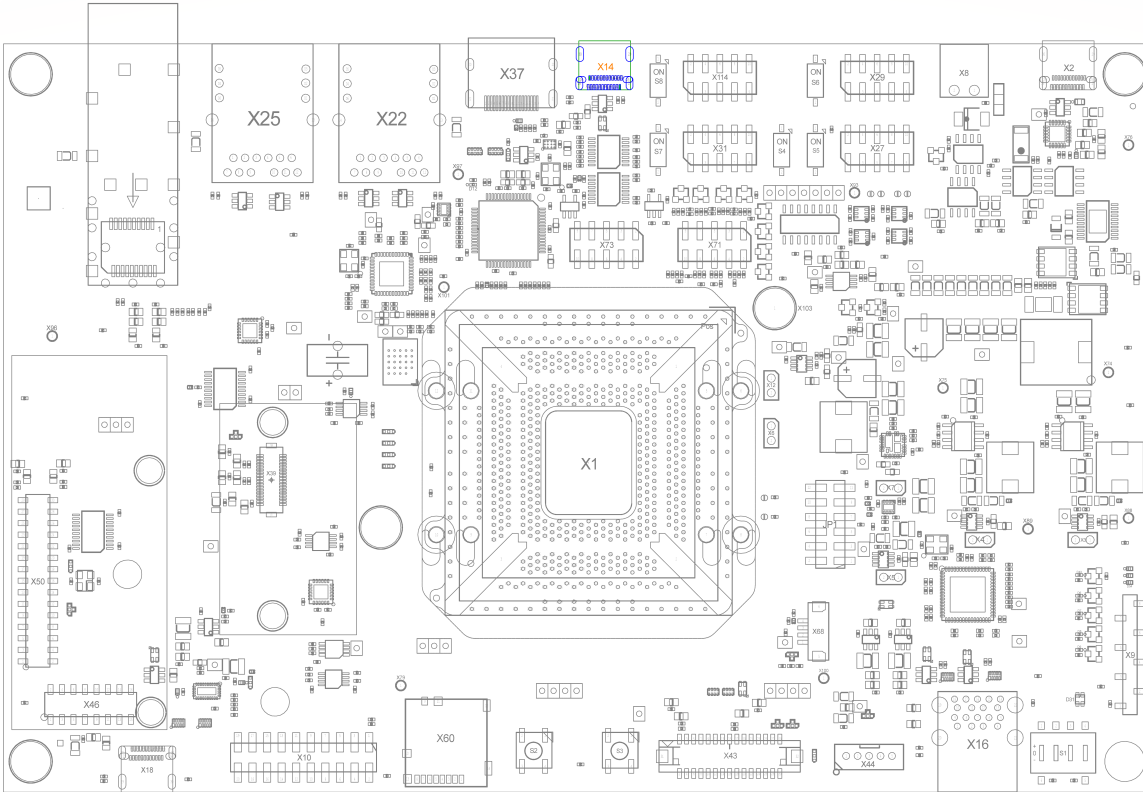
The Libra Development Board provides a USB-C 3.2 GEN 1 Dual Role interface. Muxing of super-speed differential data lanes is handled through a dedicated muxing IC (U66). The mounted SoM's USB Serial Downloader requires this interface to be able to boot from USB.

25.3.8.1 USB 3.2 Gen1 Design Considerations

Series capacitors are already present on the phyFLEX FPSC SoM. It is not necessary to provide additional series capacitors in the TX lines. Double-check the signal direction of the high-speed lines where TX is output and RX is input on the phyFLEX FPSC SoM. The TX and RX lines should be routed with an impedance of 50 Ohms to a ground plane and 100 Ohms differential impedance. Route USB 2.0 data lines with 45 Ohms to Ground and 90 Ohms differential impedance.

25.3.9 USB Debug (X14)

FIGURE 19: USB Debug Connector (X14)



The primary debug interface is UART3. UART2 is the special debug interface used to connect to an M-core or similar provided by the SoM. Both UART interfaces are connected to a UART-to-USB converter (U15 FTDI FT4232H). The USB 2.0 interface is brought out at a USB-C socket (X14). Use the following terminal settings to connect to the Libra Development Board serial interfaces:

- Speed: 115200 baud
- Data bits: 8
- Stop bits: 1
- Parity: None
- Flow control: None

The USB debug interface is also capable of manipulating the Boot Mode signals through FT4232H bank D and triggering a reset through FT4232H bank C. BOOT_MODE manipulation has to be enabled by pulling the signal DEBUG_BOOT_EN (DDBUS4 at U15) high.

The table below shows the pinout of the USB Debug connector:

TABLE 61: X14 Pin Assignment

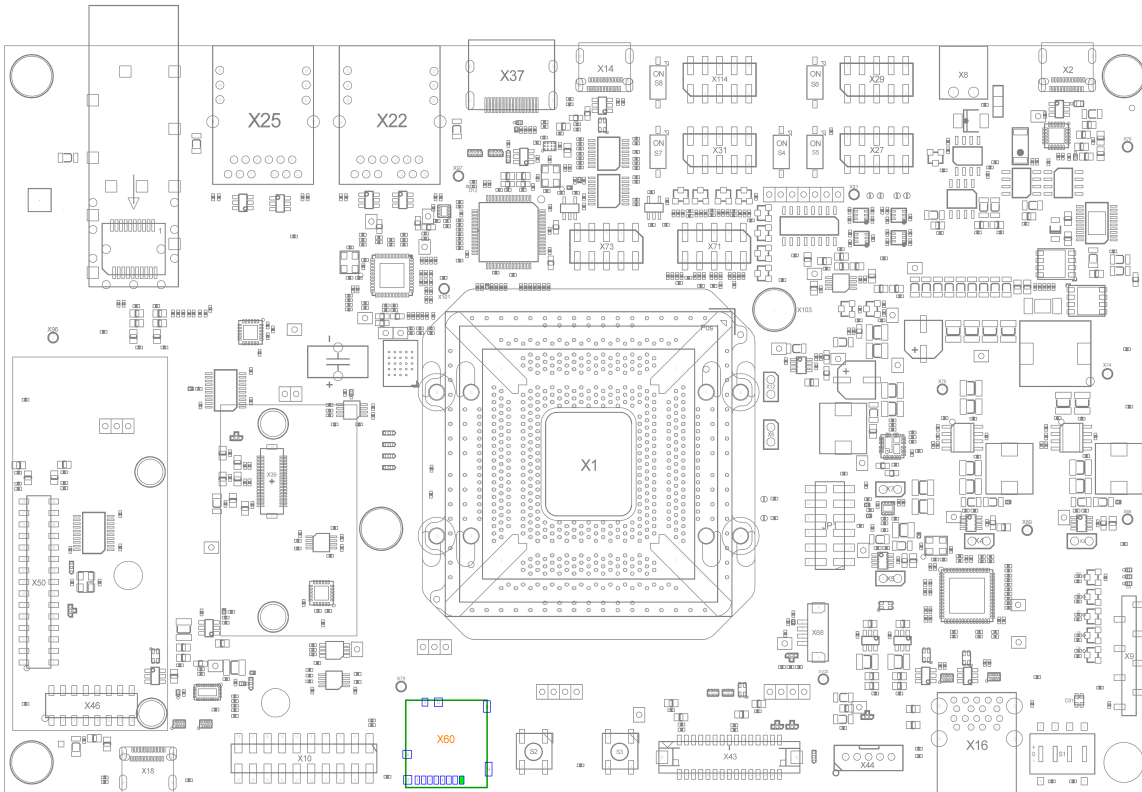
Interface Pin #	Signal name	Signal Type	Signal Level	Description
A1	GND	-	0.0 V	Ground
A2	NC	-	-	No connect
A3	NC	-	-	No connect
A4	VBUS	I	5.0 V	USB VBUS provided by Host
A5	CC1	I/O	-	Configuration channel 5k1 pull down
A6	X_DEBUG_USB_DP	USB_I/O	-	USB Debug Data+
A7	X_DEBUG_USB_DM	USB_I/O	-	USB Debug Data-
A8	NC	-	-	No connect
A9	VBUS	I	5.0 V	USB VBUS provided by Host
A10	NC	-	-	No connect
A11	NC	-	-	No connect
A12	GND	-	0.0 V	Ground

Interface Pin #	Signal name	Signal Type	Signal Level	Description
B1	GND	-	0.0 V	Ground
B2	NC	-	-	No connect
B3	NC	-	-	No connect
B4	VBUS	I	5.0 V	USB VBUS provided by Host
B5	CC2	I/O	-	Configuration channel 5k1 pull down
B6	X_DEBUG_USB_DP	USB_I/O	-	USB Debug Data+
B7	X_DEBUG_USB_DM	USB_I/O	-	USB Debug Data-
B8	NC	-	-	No connect
B9	VBUS	I	5.0 V	USB VBUS provided by Host
B10	NC	-	-	No connect
B11	NC	-	-	No connect
B12	GND	-	0.0 V	Ground

Interface Pin #	Signal name	Signal Type	Signal Level	Description
25	GND	-	0.0 V	Ground
26	GND	-	0.0 V	Ground
27	GND	-	0.0 V	Ground
28	GND	-	0.0 V	Ground
29	GND	-	0.0 V	Ground
30	GND	-	0.0 V	Ground

25.3.10 Secure Digital Memory Card / MultiMedia Card (X60)

FIGURE 20: SD / MM Card Connector (X60)



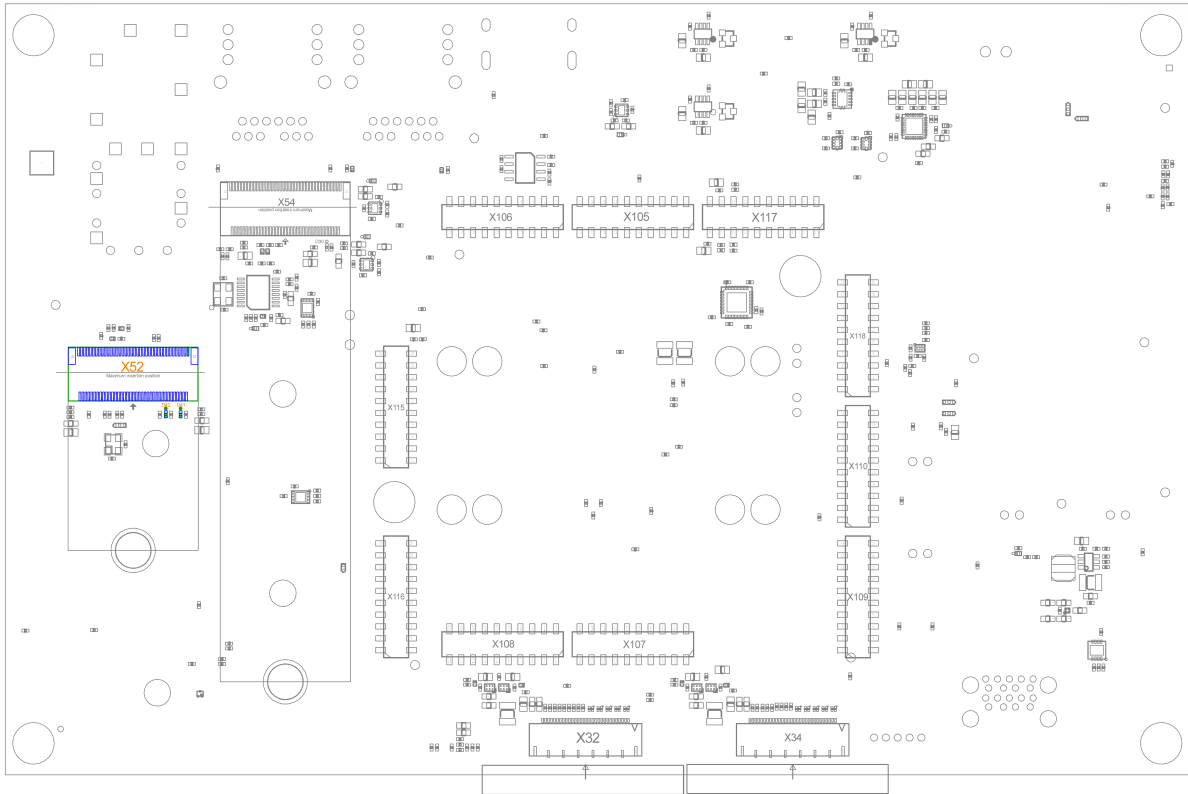
The Libra Development Board provides a standard microSDHC card slot at X60 for use with SD/MMC interface cards. It allows for a fast, easy connection to peripheral devices like microSD and MMC cards. Power to the SD interface is supplied by inserting the appropriate card into the SD/MMC connector. It also features card detection, a lock mechanism, and a smooth extraction function by pushing the card in and out.

25.3.10.1 SD / MM Card Design Considerations

Series resistors might be required to adapt the drive strength of the card. SD interface should be routed with an impedance of 50 Ohms to a ground plane. The trace length between CLK, CMD, and DATA lanes should be matched and kept as short as possible. Avoid Vias and take care of the signal current return path.

25.3.11 M.2 Key-E (X52)

FIGURE 21: M.2 Key-E Connector (X52)



The 1-lane PCI Express interface provides PCIe Gen. 3.0 functionality, which supports up to 8 GT/s operations. Various control signals are implemented with GPIOs. The PCIE1 interface is brought out at the M.2 Key-E connector X52 shown above. The M.2 Key-E connector also features UART with flow-control, SDIO, I2C and USB 2.0.

The table below shows in-depth information, such as pin assignment and signals used to implement special features of the Mini PCIe interface.

TABLE 62: X52 Pin Assignment

Interface Pin #	Signal name	Signal Type	Signal Level	Description
1	GND	-	0.0 V	Ground
2	VDD_3V3	PWR_O	3.3 V	3.3 V power rail
3	X_USB_HUB_DN1_P	USB_I/O	-	USB 2.0 Data+
4	VDD_3V3	PWR_O	3.3 V	3.3 V power rail
5	X_USB_HUB_DN1_N	USB_I/O	-	USB 2.0 Data-
6	LED_1	I	3,3 V	Status LED 1
7	GND	-	0.0 V	Ground
8	NC	-	-	No connect
9	X_SDIO_CLK	O	1.8 V	SDIO clock signal
10	NC	-	-	No connect
11	X_SDIO_CMD	O	1.8 V	SDIO command signal
12	NC	-	-	No connect

Interface Pin #	Signal name	Signal Type	Signal Level	Description
13	X_SDIO_D0	I/O	1.8 V	SDIO data 0 signal
14	NC	-	-	No connect
15	X_SDIO_D1	I/O	1.8 V	SDIO data 1 signal
16	LED_2	I	3.3 V	Status LED 2
17	X_SDIO_D2	I/O	1.8 V	SDIO data 2 signal
18	GND	-	0.0 V	Ground
19	X_SDIO_D3	I/O	1.8 V	SDIO data 3 signal
20	X_UART1_nWAKE	O	3.3 V	UART1 sideband platform wake signal
21	X_SDIO_nWAKE	O	1.8 V	SDIO sideband wake signal
22	X_UART1_RXD_BT	I	1.8 V	UART1 receive data signal
23	X_SDIO_nRESET	PCIE_I	1.8 V	SDIO sideband enable/disable (reset) signal
24	NC	-	-	No connect

Interface Pin #	Signal name	Signal Type	Signal Level	Description
25	NC	-	-	No connect
26	NC	-	-	No connect
27	NC	-	-	No connect
28	NC	-	-	No connect
29	NC	-	-	No connect
30	NC	-	-	No connect
31	NC	-	-	No connect
32	X_UART1_TXD_BT	O	1.8 V	UART1 transmit data signal
33	GND	-	0.0 V	Ground
34	X_UART1_CTS	I	1.8 V	UART1 clear to send signal
35	X_PCIE1_TXN_P	O	-	PCI Express 1 positive transmit data signal
36	X_UART1_RTS	O	1.8 V	USB 2.0 Data-

Interface Pin #	Signal name	Signal Type	Signal Level	Description
37	X_PCIE1_TXN_N	O	-	PCI Express 1 negative transmit data signal
38	NC	-	-	No connect
39	GND	-	0.0 V	Ground
40	NC	-	-	No connect
41	X_PCIE1_RXN_P	I	-	PCI Express 1 positive receive data signal
42	NC	-	-	No connect
43	X_PCIE1_RXN_N	I	-	PCI Express 1 negative receive data signal
44	TP84	O	1.8 V	Test point for COEX3 signal
45	GND	-	0.0 V	Ground
46	TP85	I	1.8 V	Test point for COEX_RXD signal
47	X_PCIE1_CLK_P	O	-	PCI Express 1 positive reference clock signal
48	TP86	O	1.8 V	Test point for COEX_TXD signal

Interface Pin #	Signal name	Signal Type	Signal Level	Description
49	X_PCIE1_CLK_N	O	-	PCI Express 1 negative reference clock signal
50	X_KEY-E_32k_SUSCLK	O	3.3 V	32768 Hz suspend clock signal
51	GND	-	0.0 V	Ground
52	X_PCIE1_nPERST_3V3		3.3 V	PCI Express 1 add-in card reset
53	X_PCIE1_nCLKREQ_3V3	I/O	3.3 V	PCI Express 1 clock request signal
54	X_W_nDISABLE1	O	3.3 V	Disable radio operation on add-in card 1 signal
55	X_PCIE1_nWAKE	I/O	3.3 V	PCI Express wake signal, OBFF
56	X_W_nDISABLE2	O	3.3 V	Disable radio operation on add-in card 2 signal
57	GND	-	0.0 V	Ground
58	X_I2C3_SDA	I/O	1.8 V	I2C3 serial data signal
59	NC	-	-	No connect
60	X_I2C3_SCL	O	1.8 V	I2C3 serial clock signal

Interface Pin #	Signal name	Signal Type	Signal Level	Description
61	NC	-	-	No connect
62	X_KEY-E_nALERT	I	1.8 V	Key-E interrupt signal
63	GND	-	0.0 V	Ground
64	NC	-	-	No connect
65	NC	-	-	No connect
66	NC	-	-	No connect
67	NC	-	-	No connect
68	NC	-	-	No connect
69	GND	-	0.0 V	Ground
70	NC	-	-	No connect
71	NC	-	-	No connect
72	VDD_3V3	PWR_O	3.3 V	3.3 V power rail

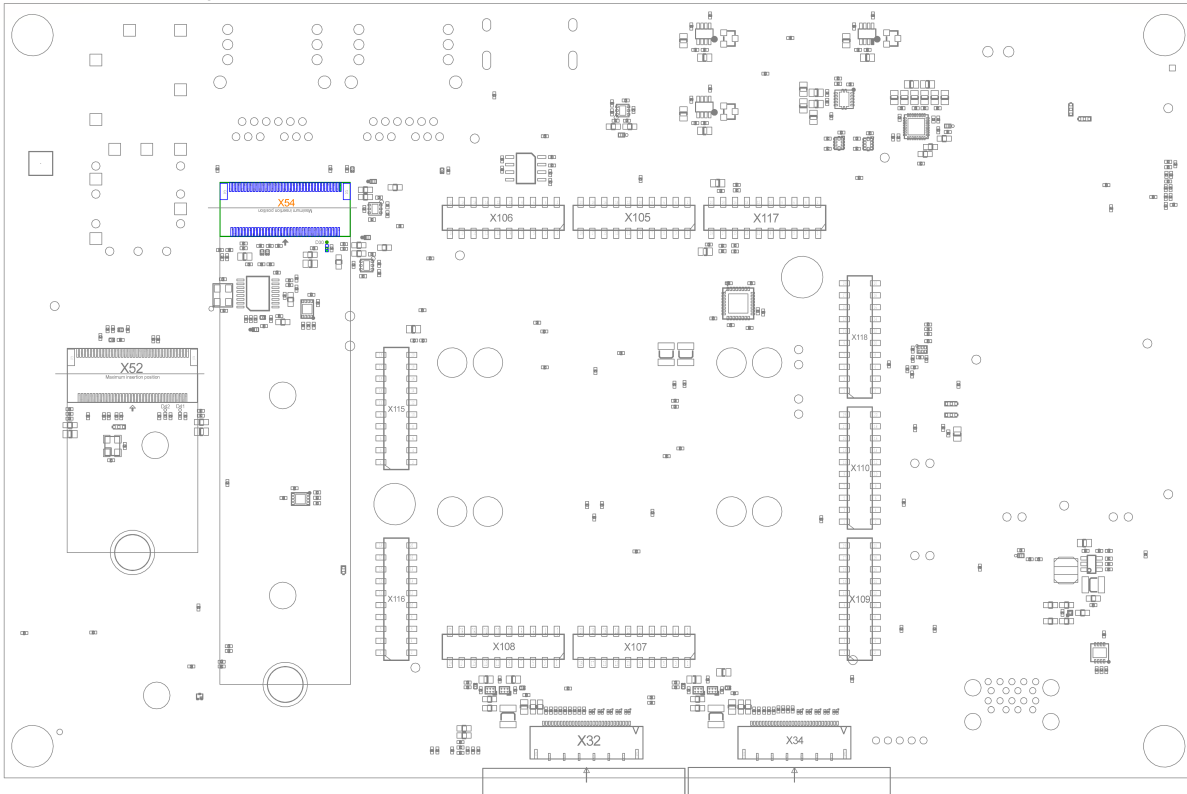
Interface Pin #	Signal name	Signal Type	Signal Level	Description
73	NC	-	-	No connect
74	VDD_3V3	PWR_O	3.3 V	3.3 V power rail
75	GND	-	0.0 V	Ground
S1	GND	-	0.0 V	Ground
S2	GND	-	0.0 V	Ground

25.3.11.1 PCIe Design Considerations

100nF AC coupling capacitors are placed at the output of the phyFLEX FPSC SoM in series to the TX lanes. A clock generator on the carrier board generates the PCIe clock.

25.3.12 M.2 Key-M (X54)

FIGURE 22: M.2 Key-M (X54)



The second 1-lane PCI Express interface provides PCIe Gen. 3.0 functionality, which supports up to 8 GT/s operations. The mounted M.2 Key-M connector is mainly used for SSD cards. Various control signals are implemented with GPIOs. The PCIe2 interface is brought out at the M.2 Key-M connector X54 shown above. The PCIe clock is generated by the dedicated PCIe clock generator U51. This feature is not available for all mountable FPSC SoMs.

The table below shows in-depth information, such as pin assignment and signals used to implement special features of the M.2 Key-M interface.

TABLE 63: X54 Pin Assignment

Interface Pin #	Signal name	Signal Type	Signal Level	Description
1	GND	-	0.0 V	Ground
2	VDD_3V3	PWR_O	3.3 V	3.3 V power rail
3	GND	-	0.0 V	Ground
4	VDD_3V3	PWR_O	3.3 V	3.3 V power rail
5	NC	-	-	No connect
6	NC	-	-	No connect
7	NC	-	-	No connect
8	NC	-	-	No connect
9	GND	-	0.0 V	Ground
10	LED1	I	3.3 V	M.2 Key-M activity LED signal
11	NC	-	-	No connect
12	VDD_3V3	PWR_O	3.3 V	3.3 V power rail

Interface Pin #	Signal name	Signal Type	Signal Level	Description
13	NC	-	-	No connect
14	VDD_3V3	PWR_O	3.3 V	3.3 V power rail
15	GND	-	0.0 V	Ground
16	VDD_3V3	PWR_O	3.3 V	3.3 V power rail
17	NC	-	-	No connect
18	VDD_3V3	PWR_O	3.3 V	3.3 V power rail
19	NC	-	-	No connect
20	NC	-	-	No connect
21	GND	-	0.0 V	Ground
22	NC	-	-	No connect
23	NC	-	-	No connect
24	NC	-	-	No connect

Interface Pin #	Signal name	Signal Type	Signal Level	Description
25	NC	-	-	No connect
26	NC	-	-	No connect
27	GND	-	0.0 V	Ground
28	NC	-	-	No connect
29	NC	-	-	No connect
30	NC	-	-	No connect
31	NC	-	-	No connect
32	NC	-	-	No connect
33	GND	-	0.0 V	Ground
34	NC	-	-	No connect
35	NC	-	-	No connect
36	NC	-	-	No connect

Interface Pin #	Signal name	Signal Type	Signal Level	Description
37	NC	-	-	No connect
38	NC	-	-	No connect
39	GND	-	0.0 V	Ground
40	X_I2C2_SCL	O	1.8 V	I2C2 serial clock
41	X_PCIE2_TXN_N	O	-	PCI Express 2 negative transmit data signal
42	X_I2C2_SDA	I/O	1.8 V	I2C2 serial data
43	X_PCIE2_TXN_P	O	-	PCI Express 2 positive transmit data signal
44	X_KEY-M_nALERT	I	1.8 V	Key-M interrupt signal
45	GND	-	0.0 V	Ground
46	NC	-	-	No connect
47	X_PCIE2_RXN_N	I	-	PCI Express 2 negative receive data signal
48	NC	-	-	No connect

Interface Pin #	Signal name	Signal Type	Signal Level	Description
49	X_PCIE2_RXN_P	I	-	PCI Express 2 positive receive data signal
50	X_PCIE2_nCLKREQ_3V3	I/O	3.3 V	PCI Express 2 clock request signal
51	GND	-	0.0 V	Ground
52	X_PCIE2_nPERST_3V3		3.3 V	PCI Express 2 add-in card reset
53	X_PCIE2_CON_REFPAD_CLK_N	O	-	PCI Express 2 negative reference clock signal
54	X_PCIE2_nWAKE	I/O	3.3 V	PCI Express wake signal, OBFF
55	X_PCIE2_CON_REFPAD_CLK_P	O	-	PCI Express 2 positive reference clock signal
56	NC	-	-	No connect
57	GND	-	0.0 V	Ground
58	NC	-	-	No connect
59	NC	-	-	No connect
60	NC	-	-	No connect

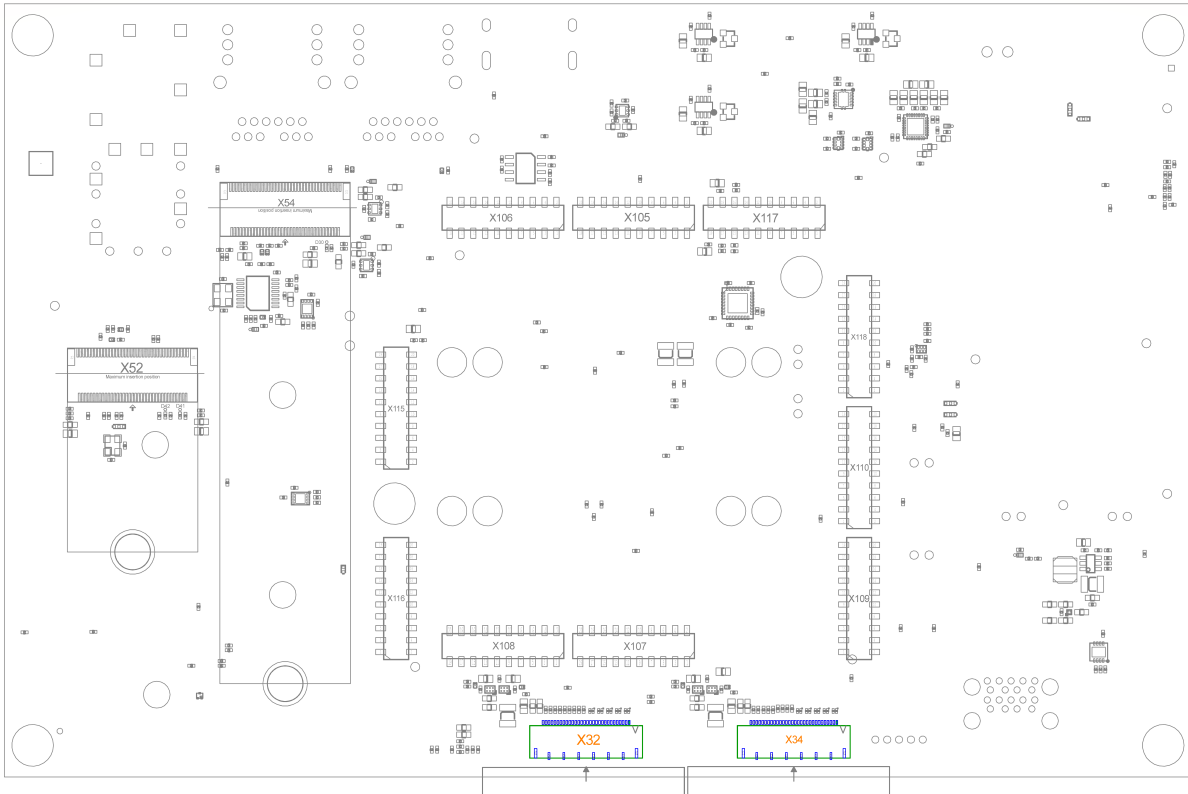
Interface Pin #	Signal name	Signal Type	Signal Level	Description
61	NC	-	-	No connect
62	NC	-	-	No connect
63	NC	-	-	No connect
64	NC	-	-	No connect
65	NC	-	-	No connect
66	NC	-	-	No connect
67	NC	-	-	No connect
68	X_KEY-M_32k_SUSCLK	O	3.3 V	32768 Hz suspend clock signal
69	NC	-	-	No connect
70	VDD_3V3	PWR_O	3.3 V	3.3 V power rail
71	GND	-	0.0 V	Ground
72	VDD_3V3	PWR_O	3.3 V	3.3 V power rail

Interface Pin #	Signal name	Signal Type	Signal Level	Description
73	GND	-	0.0 V	Ground
74	VDD_3V3	PWR_O	3.3 V	3.3 V power rail
75	GND	-	0.0 V	Ground
S1	GND	-	0.0 V	Ground
S2	GND	-	0.0 V	Ground

25.3.13 Camera Connectivity

25.3.13.1 phyCAM-M MIPI CSI Camera Connectors (X32/34)

FIGURE 23: phyCAM-M MIPI CSI-2 Camera Connectors (X32/X34)



The phyFLEX FPSC SoM on the Libra Development Board offers 2 independent interfaces to connect digital camera boards with the MIPI CSI-2 interface. The 4-lane MIPI CSI-2 interfaces are brought out as phyCAM-M camera interfaces at connectors X32 and X34. The pin assignments of connectors X32 and X34 are shown below. The phyCAM-M camera connectors fit the phyCAM-M product family with various color and monochrome sensors. Suitable camera modules are, e.g., VM-016-COL-M (1 MPix) or VM-017-BW-M (5 Mpix), which can be delivered with a complete objective. Contact the PHYTEC Sales Team for advice on how to tailor a camera module to your application.

TABLE 64: MIPI CSI-2 Camera 1 (X32) Pin Assignment

Interface Pin #	Signal name	Signal Type	Signal Level	Description
1	GND	-	-	Ground
2	X_MIPI_CSI1_D0_P	MIPI CSI-2	-	MIPI CSI-2 data 0 positive signal
3	X_MIPI_CSI1_D0_N	MIPI CSI-2	-	MIPI CSI-2 data 0 negative signal
4	GND	-	-	Ground
5	X_MIPI_CSI1_D1_P	MIPI CSI-2	-	MIPI CSI-2 data 1 positive signal
6	X_MIPI_CSI1_D1_N	MIPI CSI-2	-	MIPI CSI-2 data 1 negative signal
7	GND	-	-	Ground
8	X_MIPI_CSI1_CLK_P	MIPI CSI-2	-	MIPI CSI-2 clock positive signal
9	X_MIPI_CSI1_CLK_N	MIPI CSI-2	-	MIPI CSI-2 clock negative signal
10	GND	-	-	Ground
11	X_MIPI_CSI1_D2_P	MIPI CSI-2	-	MIPI CSI-2 data 2 positive signal
12	X_MIPI_CSI1_D2_N	MIPI CSI-2	-	MIPI CSI-2 data 2 negative signal

Interface Pin #	Signal name	Signal Type	Signal Level	Description
13	GND	-	-	Ground
14	X_MIPI_CSI1_D3_P	MIPI CSI-2	-	MIPI CSI-2 data 3 positive signal
15	X_MIPI_CSI1_D3_N	MIPI CSI-2	-	MIPI CSI-2 data 3 negative signal
16	GND	-	-	Ground
17	X_CSI1_CTRL4	OD-BI-PU	3.3 V	CSI1 control 4
18	X_CSI1_CTRL3	OD-BI-PU	3.3 V	CSI1 control 3
19	X_CSI1_CTRL2	OD-BI-PU	3.3 V	CSI1 control 2
20	X_CSI1_CTRL1	OD-BI-PU	3.3 V	CSI1 control 1
21	GND	-	-	Ground
22	X_I2C3_SCL_3V3	O	3.3 V	I2C3 serial clock
23	X_I2C3_SDA_3V3	I/O	3.3 V	I2C3 serial data
24	X_CSI1_ADDR	O	3.3 V	I2C camera address choice

Interface Pin #	Signal name	Signal Type	Signal Level	Description
25	X_CSI1_nRESET	O	3.3 V	Camera reset signal
26	X_CSI1_VDD_SELECT	OD-I-PU	3.3 V	Interface voltage selection: <ul style="list-style-type: none"> • open = 3.3 V • GND = 5 V
27	GND	-	-	Ground
28	VDD_CSI1_OUT	PWR_O	3.3 V / 5 V	Camera power supply
29	VDD_CSI1_OUT	PWR_O	3.3 V / 5 V	Camera power supply
30	VDD_CSI1_OUT	PWR_O	3.3 V / 5 V	Camera power supply

TABLE 65: MIPI CSI-2 Camera 2 (X34) Pin Assignment

Interface Pin #	Signal name	Signal Type	Signal Level	Description
1	GND	-	-	Ground
2	X_MIPI_CSI2_D0_P	MIPI CSI-2	-	MIPI CSI-2 data 0 positive signal
3	X_MIPI_CSI2_D0_N	MIPI CSI-2	-	MIPI CSI-2 data 0 negative signal
4	GND	-	-	Ground
5	X_MIPI_CSI2_D1_P	MIPI CSI-2	-	MIPI CSI-2 data 1 positive signal
6	X_MIPI_CSI2_D1_N	MIPI CSI-2	-	MIPI CSI-2 data 1 negative signal
7	GND	-	-	Ground
8	X_MIPI_CSI2_CLK_P	MIPI CSI-2	-	MIPI CSI-2 clock positive signal
9	X_MIPI_CSI2_CLK_N	MIPI CSI-2	-	MIPI CSI-2 clock negative signal
10	GND	-	-	Ground
11	X_MIPI_CSI2_D2_P	MIPI CSI-2	-	MIPI CSI-2 data 2 positive signal
12	X_MIPI_CSI2_D2_N	MIPI CSI-2	-	MIPI CSI-2 data 2 negative signal

Interface Pin #	Signal name	Signal Type	Signal Level	Description
13	GND	-	-	Ground
14	X_MIPI_CSI2_D3_P	MIPI CSI-2	-	MIPI CSI-2 data 3 positive signal
15	X_MIPI_CSI2_D3_N	MIPI CSI-2	-	MIPI CSI-2 data 3 negative signal
16	GND	-	-	Ground
17	X_CSI2_CTRL4	OD-BI-PU	3.3 V	CSI2 control 4
18	X_CSI2_CTRL3	OD-BI-PU	3.3 V	CSI2 control 3
19	X_CSI1_CTRL1	OD-BI-PU	3.3 V	CSI1 control 1, Camera 2 is set up to be triggered by Camera 1 strobe output
20	X_CSI2_CTRL1	OD-BI-PU	3.3 V	CSI2 control 1
21	GND	-	-	Ground
22	X_I2C4_SCL_3V3	O	3.3 V	I2C4 serial clock
23	X_I2C4_SDA_3V3	I/O	3.3 V	I2C4 serial data
24	X_CSI2_ADDR	O	3.3 V	I2C camera address choice

Interface Pin #	Signal name	Signal Type	Signal Level	Description
25	X_CSI2_nRESET	O	3.3 V	Camera reset signal
26	X_CSI2_VDD_SELECT	OD-I-PU	3.3 V	Interface voltage selection: <ul style="list-style-type: none"> • open = 3.3 V • GND = 5 V
27	GND	-	-	Ground
28	VDD_CSI2_OUT	PWR_O	3.3 V / 5 V	Camera power supply
29	VDD_CSI2_OUT	PWR_O	3.3 V / 5 V	Camera power supply
30	VDD_CSI2_OUT	PWR_O	3.3 V / 5 V	Camera power supply

25.3.13.2 Camera Design Considerations

Regarding camera connections when designing a customer carrier board:

1. The differential impedance should be 100 Ohms for all lanes to a Ground Plane. The lanes should be matched.
2. phyCAM-M interfaces offer 3.3 V or 5 V supply voltages (selected by interface pin 26). Both voltages should be provided by the board to guarantee full compatibility with the phyCAM-M interface.
3. Each phyCAM interface needs a different I²C address if connected to the same I²C Bus. Place a Pull-up resistor at pin 24 to select the secondary address.

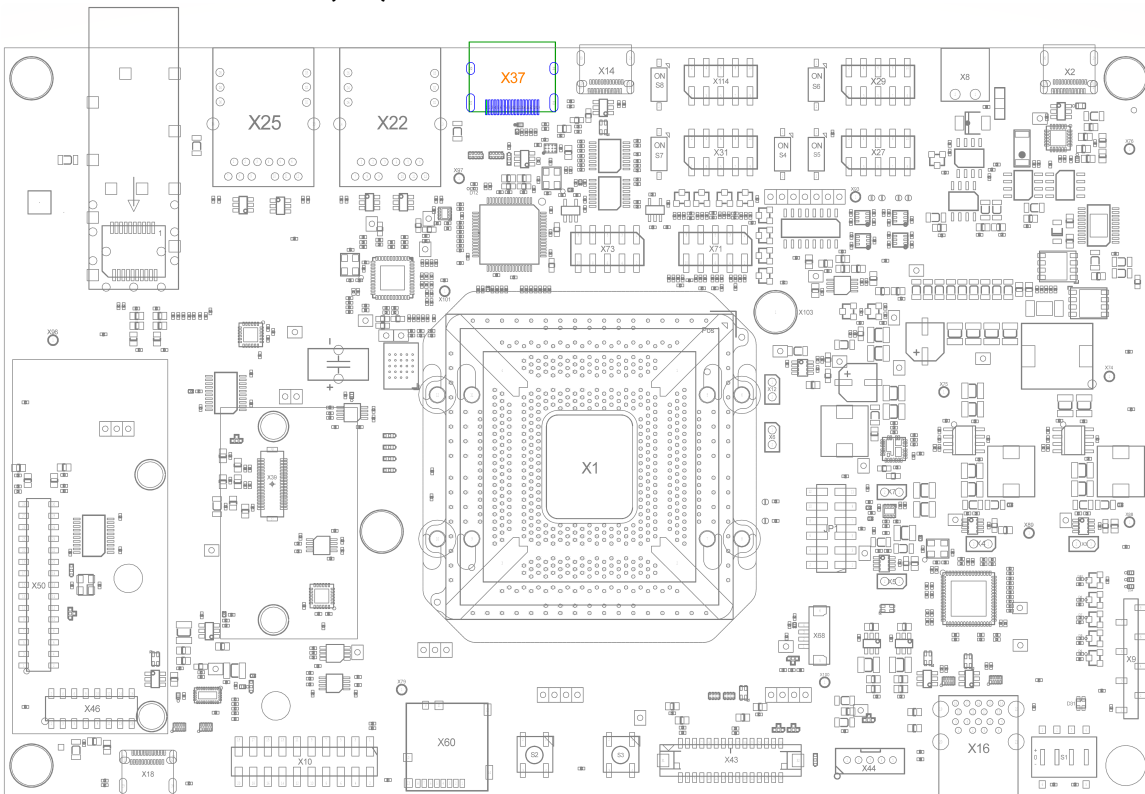
General information and design guidelines for PHYTEC camera interfaces can be found here:

- German: [L-867Bd.A9 phyCAM Basis-Spezifikation und Design-In Guide](#)
- English: [L-867Be.A9 phyCAM Basis Specification and Design-In Guide](#)

Specific information for each PHYTEC camera module can be found on that module's download page: [PHYTEC Embedded Vision \(Deutsch\)](#) or [PHYTEC Embedded Vision \(English\)](#).

25.3.14 HDMI (X37)

FIGURE 24: HDMI Connector (X37)



The Libra Development Board provides a High-Definition Multimedia Interface (HDMI), which is compliant with HDMI 2.0a. It supports a maximum resolution of 1920x1080p60, 1280x720p60, 720x480p60, and 640x480p60. Please refer to the applicable phyFLEX FPSC SoM Applications Processor Reference Manual for more information. This feature is not available for all mountable FPSC SoMs.

The HDMI interface is brought out at a standard HDMI type A connector (X37) on the Libra Development Board and comprises the following signal groups:

- Three pairs of data signals
- One pair of clock signals
- The Display Data Channel (DDC)
- The Consumer Electronics Control (CEC)
- The Hot Plug Detect (HPD) signal
- Audio Return Channel (ARC)

All signals are routed from the phyFLEX-Connector to the HDMI receptacle through ESD protection diodes and level shifting components.

TABLE 66: X32 Pin Assignment

Interface Pin #	Signal name	Signal Type	Signal Level	Description
1	X_HDMI_TX2_P	HDMI_O	-	HDMI data 2 positive signal
2	GND	-	0.0 V	Ground
3	X_HDMI_TX2_N	HDMI_O	-	HDMI data 2 negative signal
4	X_HDMI_TX1_P	HDMI_O	-	HDMI data 1 positive signal
5	GND	-	0.0 V	Ground
6	X_HDMI_TX1_N	HDMI_O	-	HDMI data 1 negative signal
7	X_HDMI_TX0_P	HDMI_O	-	HDMI data 0 positive signal
8	GND	-	0.0 V	Ground
9	X_HDMI_TX0_N	HDMI_O	-	HDMI data 0 negative signal
10	X_HDMI_TXC_P	HDMI_O	-	HDMI clock positive signal
11	GND	-	0.0 V	Ground
12	X_HDMI_TXC_N	HDMI_O	-	HDMI clock negative signal

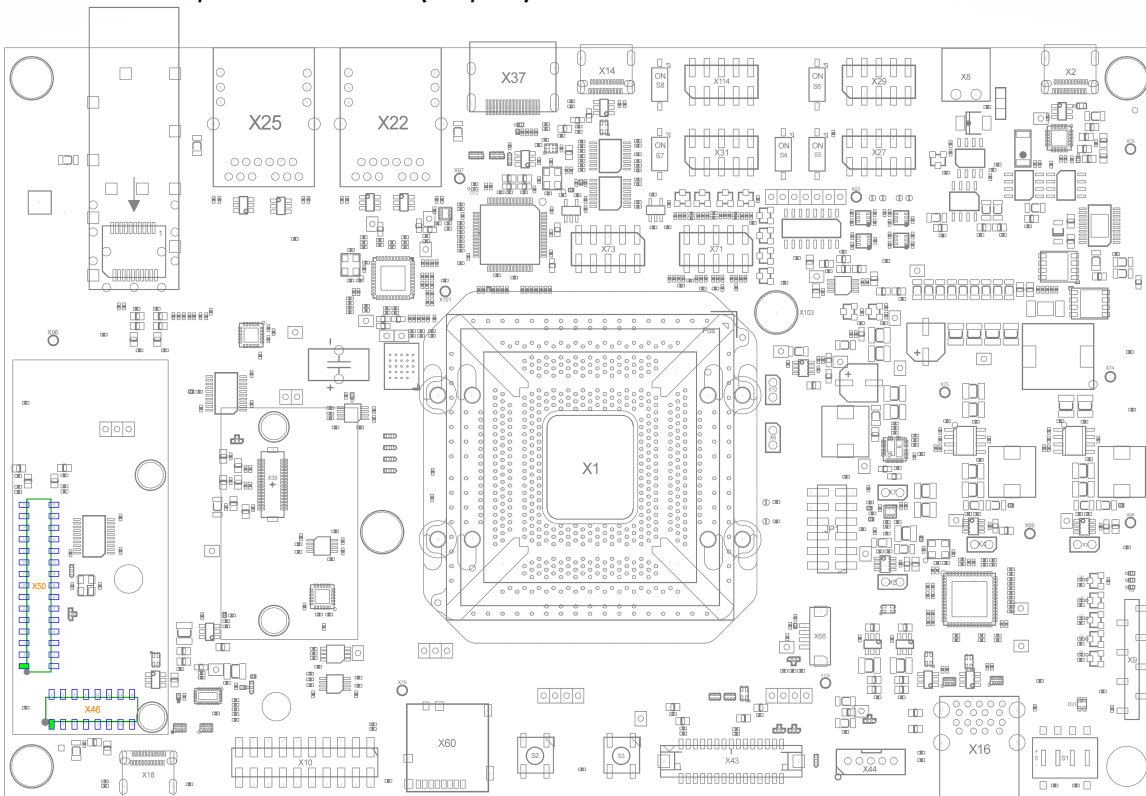
Interface Pin #	Signal name	Signal Type	Signal Level	Description
13	X_HDMI_CEC	OD-BI-PU	VDD_CEC	Consumer Electronics Control
14	X_EARC_P_UTIL	-	-	Not connected by default, may be connected via resistor jumpers R518 and R519
15	X_HDMI_DDC_SCL	OD-BI-PU	5 V	I2C serial clock
16	X_HDMI_DDC_SDA	OD-BI-PU	5 V	I2C serial data
17	GND	-	0.0 V	Ground
18	VCC_5V_HDMI_OUT	PWR_O	5 V	5 V supply for an HDMI device
19	X_EARC_N_HPD	-	5 V	Audio Return Channel Negative Lane / Hot Plug detect
20	SHIELD_1	-	0.0 V	Shield connected to Ground over 100 nF and 150 pF parallel to 1 MOhm
21	SHIELD_2	-	0.0 V	
22	SHIELD_3	-	0.0 V	
23	SHIELD_4	-	0.0 V	

25.3.14.1 HDMI Design Considerations

The differential impedance should be 100 Ohms for all lanes to a Ground Plane. The lanes should be matched. The DDC lanes need pull-up resistors between 1.5k and 2k to 5V. The CEC lane needs a 27k pull-up resistor connected to 3.3V through a diode. This prevents leaking current in a power-off state.

25.3.15 Audio/Video (SAI2/LVDS0)

FIGURE 25: Audio/Video Connectors (X46/X50)



The phyFLEX FPSC SoM offers two LVDS display interfaces. The Audio/Video (A/V) connectors X46 and X50 provide an easy way to add typical A/V functions and features to the Libra Development Board. Standard interfaces such as 4-lane LVDS, I2S, I2C, and USB, as well as different supply voltages, are available at the two A/V female pin-sockets. The A/V connector is intended to be used with phyBOARDS and PHYTEC Development Boards to add specific audio/video connectivity with custom expansion boards. A/V connector X46 makes all signals for display connectivity available and provides a supply voltage, while X50 provides signals for audio and touchscreen connectivity as well as an I2C interface, additional control signals and supply voltages. The tables below show the pin assignment of connectors X46 and X50.

TABLE 67: X46 Pin Assignment

Interface Pin #	Signal name	Signal Type	Signal Level	Description
1	GND	-	-	Ground
2	X_LVDS2_D2_P	LVDS_O	-	LVDS data 2 positive signal
3	X_LVDS2_CLK_P	LVDS_O	-	LVDS clock positive signal
4	X_LVDS2_D2_N	LVDS_O	-	LVDS data 2 negative signal
5	X_LVDS2_CLK_N	LVDS_O	-	LVDS clock negative signal
6	GND	-	-	Ground
7	GND	-	-	Ground
8	X_LVDS2_D3_P	LVDS_O	-	LVDS data 3 positive signal
9	X_LVDS2_D1_P	LVDS_O	-	LVDS data 1 positive signal
10	X_LVDS2_D3_N	LVDS_O	-	LVDS data 3 negative signal
11	X_LVDS2_D1_N	LVDS_O	-	LVDS data 1 negative signal
12	GND	-	-	Ground

Interface Pin #	Signal name	Signal Type	Signal Level	Description
13	GND	-	-	Ground
14	X_LVDS2_D0_P	LVDS_O	-	LVDS data 0 positive signal
15	VDD_IN_AV	PWR_O	24 V	A/V power out rail, connected to the carrier board power in
16	X_LVDS2_D0_N	LVDS_O	-	LVDS data 0 negative signal

TABLE 68: X50 Pin Assignment

Interface Pin #	Signal name	Signal Type	Signal Level	Description
1	X_USB_HUB_DN2_P	USB_I/O	-	USB 2.0 Data+
2	X_USB_HUB_DN2_N	USB_I/O	-	USB 2.0 Data-
3	X_nRESET_OUT	OD_O_PU	3.3 V	A/V reset signal
4	GND	-	-	Ground
5	NC	-	-	No connect
6	X_USB_HUB_OVERCUR2	-	3.3 V	USB over current detection
7	X_USB_HUB_nPWRCTL2	-	3.3 V	USB power control
8	X_SAI1_RXFS_3V3	O	3.3 V	A/V Backlight enable
9	X_PWM1_LVDS_DSI_3V3	O	3.3 V	A/V Backlight PWM, choice between 3.3 V, 0 V and shared PWM signal (default) via J30
10	X_nRESET_OUT	OD_O_PU	3.3 V	Global reset output
11	GND	-	-	Ground

Interface Pin #	Signal name	Signal Type	Signal Level	Description
12	NC	-	-	No connect
13	X_SAI1_TXD_3V3	O	3.3 V	SAI TXD
14	GND	-	-	Ground
15	NC	-	-	No connect
16	X_SAI1_TXC_3V3	O	3.3 V	SAI TXC
17	X_SAI1_RXC_3V3	O	3.3 V	SAI RXC
18	X_SAI1_TXFS_3V3	O	3.3 V	SAI TXFS
19	X_MCLK_AV	O	3.3 V	SAI MCLK
20	X_SAI1_RXD_3V3	I	3.3 V	SAI RXD
21	GND	-	-	Ground
22	X_I2C3_SDA_3V3	I/O	3.3 V	I2C3 serial data
23	NC	-	-	No connect

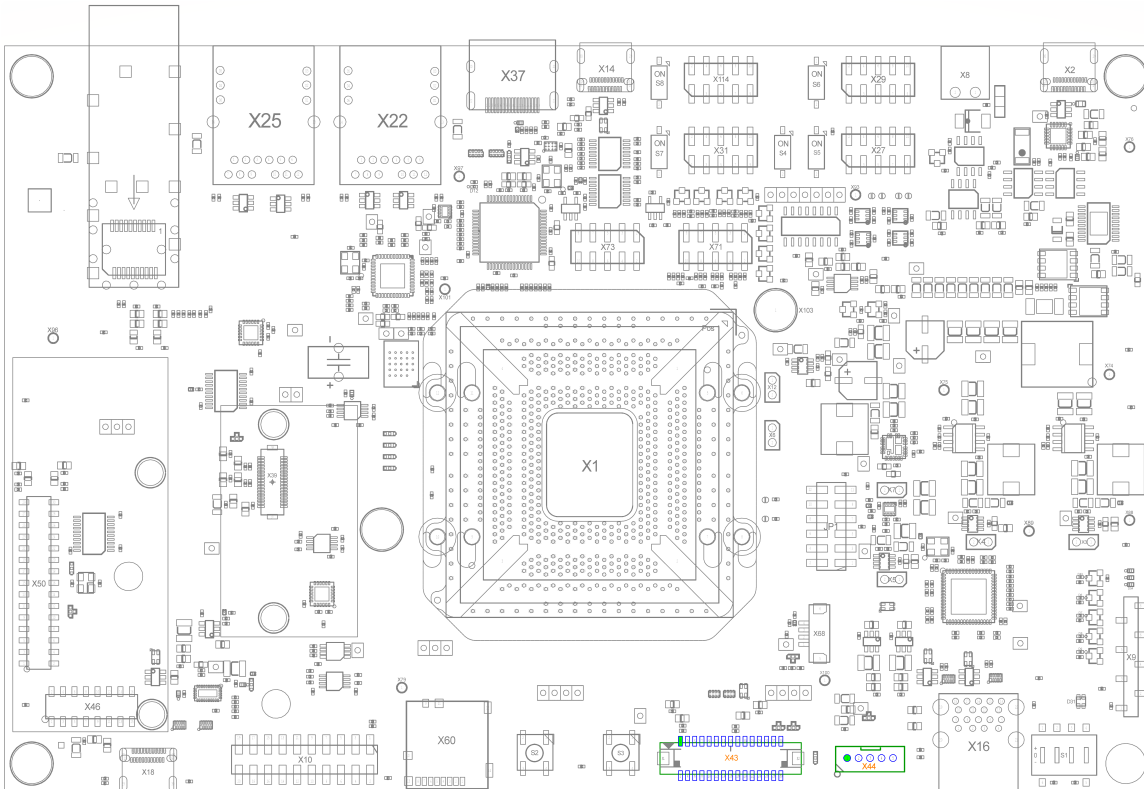
Interface Pin #	Signal name	Signal Type	Signal Level	Description
24	X_I2C3_SCL_3V3	O	3.3 V	I2C3 serial clock
25	NC	-	-	No connect
26	GND	-	-	Ground
27	VDD_5V0	PWR_O	5.0 V	A/V 5.0 V power rail
28	VDD_3V3	PWR_O	3.3 V	A/V 3.3 V power rail
29	VDD_5V0	PWR_O	5.0 V	A/V 5.0 V power rail
30	VDD_3V3	PWR_O	3.3 V	A/V 3.3 V power rail

25.3.15.1 Audio/Video Design Considerations

The differential impedance of LVDS2 lanes should be 100 Ohm and 50 Ohm to a ground plane for all lanes. Lanes should be matched. The audio signals should have a single-ended impedance of 50 Ohms to a ground plane.

25.3.16 LVDS1 (X43/X44)

FIGURE 26: LVDS1 Connectors (X43/X44)



The phyFLEX FPSC SoM offers two LVDS display interfaces. The video connectors X43 and X44 provide an easy way to connect a display to the Libra Development Board. The pinout of both connectors fits the Glyn LVDS Display Family with different display sizes and display resolutions. In addition to the Glyn LVDS signals, there is I²C for touch brought out at X34 as well. For USB-touch functionality please use the USB Dual Type-A connector X16. The connectors are intended to be used with PHYTEC KLCD-AC163. The tables below show the pin assignment of connectors X43 and X44.

TABLE 69: X43 Pin Assignment

Interface Pin #	Signal name	Signal Type	Signal Level	Description
1	NC	-	-	No connect
2	NC	-	-	No connect
3	VDD_3V3	PWR_O	3.3 V	LVDS1 3.3 V power rail
4	GND	-	0.0 V	Ground
5	X_LVDS1_CLK_N	LVDS_O	-	LVDS clock negative signal
6	X_LVDS1_CLK_P	LVDS_O	-	LVDS clock positive signal
7	VDD_3V3	PWR_O	3.3 V	LVDS1 3.3 V power rail
8	GND	-	0.0 V	Ground
9	X_LVDS1_D0_N	LVDS_O	-	LVDS data 0 negative signal
10	X_LVDS1_D0_P	LVDS_O	-	LVDS data 0 positive signal
11	X_LVDS1_D1_N	LVDS_O	-	LVDS data 1 negative signal
12	X_LVDS1_D1_P	LVDS_O	-	LVDS data 1 positive signal

Interface Pin #	Signal name	Signal Type	Signal Level	Description
13	X_LVDS1_D2_N	LVDS_O	-	LVDS data 2 negative signal
14	X_LVDS1_D2_P	LVDS_O	-	LVDS data 2 positive signal
15	X_LVDS1_D3_N	LVDS_O	-	LVDS data 3 negative signal
16	X_LVDS1_D3_P	LVDS_O	-	LVDS data 3 positive signal
17	VDD_5V0	PWR_O	5.0 V	LVDS1 5.0 V power rail
18	GND	-	0.0 V	Ground
19	NC	-	-	No connect
20	NC	-	-	No connect
21	NC	-	-	No connect
22	GND	-	0.0 V	Ground
23	NC	-	-	No connect
24	NC	-	-	No connect

Interface Pin #	Signal name	Signal Type	Signal Level	Description
25	NC	-	-	No connect
26	NC	-	-	No connect
27	X_I2C3_SCL_3V3	O	3.3 V	I2C3 serial clock
28	GND	-	0.0 V	Ground
29	X_I2C3_SDA_3V3	I/O	3.3 V	I2C3 serial data
30	NC	-	-	No connect
31	NC	-	-	No connect
32	NC	-	-	No connect

TABLE 70: X44 Pin Assignment

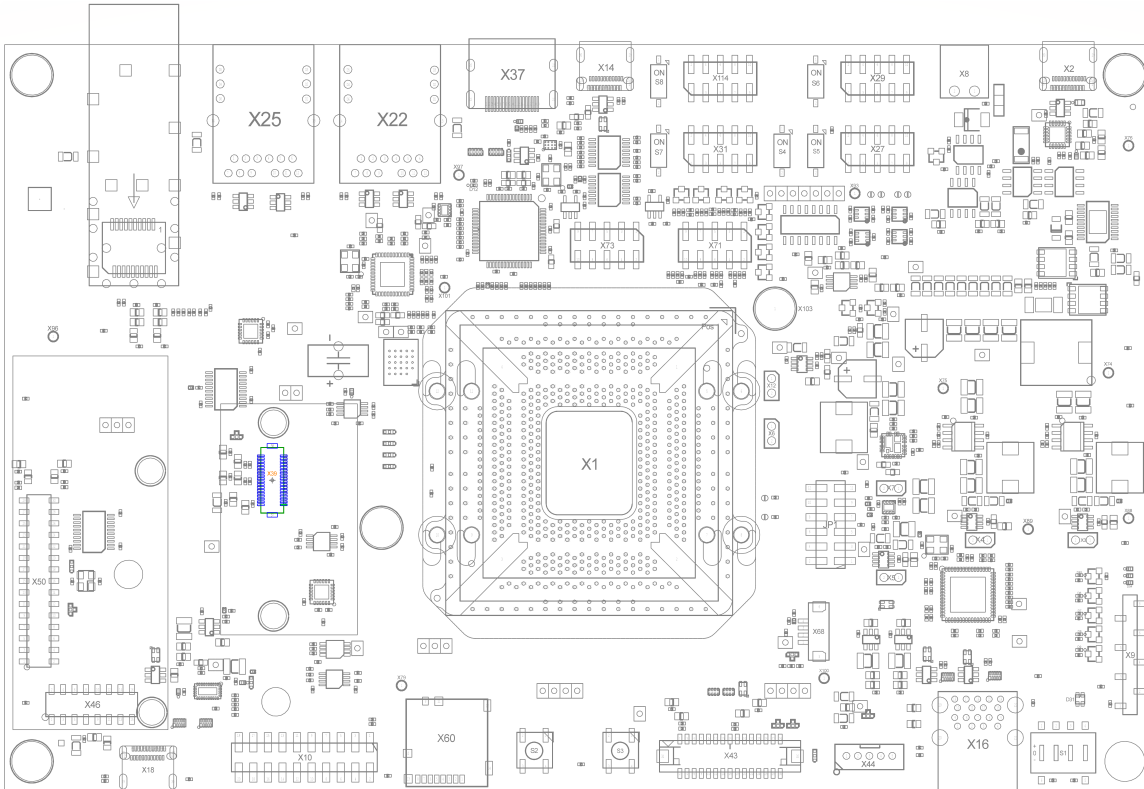
Interface Pin #	Signal name	Signal Type	Signal Level	Description
1	VDD_12V0	PWR_O	12.0 V	LVDS1 12.0 V power rail for backlight
2	X_PWM1_LVDS_DSI_3V3	O	3.3 V	LVDS1 backlight PWM, choice between 3.3 V, 0 V and shared PWM signal (default) via J29
3	GND	-	0.0 V	Ground
4	GND	-	0.0 V	Ground
5	X_LVDS1_BL_EN	O	3.3 V	LVDS1 backlight enable

25.3.16.1 LVDS Design Considerations

The differential impedance of LVDS0 lanes should be 100 Ohm and 50 Ohm to a Ground-Plane for all lanes. The lanes should be matched.

25.3.17 MIPI-DSI (X39)

FIGURE 27: MIPI-DSI (X39)



The Libra Development Board offers one MIPI-DSI display interface. MIPI-DSI has 4 channels, supporting one display with a resolution of up to 1920 x 1080 at 60Hz. The following table shows the pin assignment of connector X39. This feature is not available for all mountable FPSC SoMs.

TABLE 71: X39 Pin Assignment

Interface Pin #	Signal name	Signal Type	Signal Level	Description
1	GND	-	0.0 V	Ground
2	GND	-	0.0 V	Ground
3	X_MIPI_DSI1_D0_P	DSI_O	-	MIPI DSI data 0 positive signal
4	VDD_IN_MIPI_DSI	PWR_O	24.0 V	MIPI DSI power out rail, connected to the carrier board power in
5	X_MIPI_DSI1_D0_N	DSI_O	-	MIPI DSI data 0 negative signal
6	VDD_IN_MIPI_DSI	PWR_O	24.0 V	MIPI DSI power out rail, connected to the carrier board power in
7	GND	-	0.0 V	Ground
8	GND	-	0.0 V	Ground
9	X_MIPI_DSI1_D1_P	DSI_O	-	MIPI DSI data 1 positive signal
10	VDD_IN_MIPI_DSI	PWR_O	24.0 V	MIPI DSI power out rail, connected to the carrier board power in
11	X_MIPI_DSI1_D1_N	DSI_O	-	MIPI DSI data 1 negative signal
12	VDD_IN_MIPI_DSI	PWR_O	24.0 V	MIPI DSI power out rail, connected to the carrier board power in

Interface Pin #	Signal name	Signal Type	Signal Level	Description
13	GND	-	0.0 V	Ground
14	GND	-	0.0 V	Ground
15	X_MIPI_DSI1_CLK_P	DSI_O	-	MIPI DSI clock positive signal
16	VDD_5V0_MIPI_DSI	PWR_O	5.0 V	MIPI DSI 5.0 V power out rail
17	X_MIPI_DSI1_CLK_N	DSI_O	-	MIPI DSI clock negative signal
18	VDD_5V0_MIPI_DSI	PWR_O	5.0 V	MIPI DSI 5.0 V power out rail
19	GND	-	0.0 V	Ground
20	GND	-	0.0 V	Ground
21	X_MIPI_DSI1_D2_P	DSI_O	-	MIPI DSI data 2 positive signal
22	VDD_3V3_MIPI_DSI	PWR_O	3.3 V	MIPI DSI 3.3 V power out rail
23	X_MIPI_DSI1_D2_N	DSI_O	-	MIPI DSI data 2 negative signal
24	VDD_3V3_MIPI_DSI	PWR_O	3.3 V	MIPI DSI 3.3 V power out rail

Interface Pin #	Signal name	Signal Type	Signal Level	Description
25	GND	-	0.0 V	Ground
26	GND	-	0.0 V	Ground
27	X_MIPI_DSI1_D3_P	DSI_O	-	MIPI DSI data 3 positive signal
28	X_I2C4_SCL_3V3	O	3.3 V	I2C4 serial clock
29	X_MIPI_DSI1_D3_N	DSI_O	-	MIPI DSI data 3 negative signal
30	X_I2C4_SDA_3V3	I/O	3.3 V	I2C4 serial data
31	GND	-	0.0 V	Ground
32	GND	-	0.0 V	Ground
33	TP42	-	-	MIPI_DSI1_GPIO0 test point
34	X_PWM1_LVDS_DSI_3V3	O	3.3 V	MIPI DSI1 PWM, choice between 3.3 V, 0 V and shared PWM signal (default) via J31
35	TP43	-	-	MIPI_DSI1_GPIO1 test point
36	X_nRESET_OUT	O	3.3 V	Global reset output

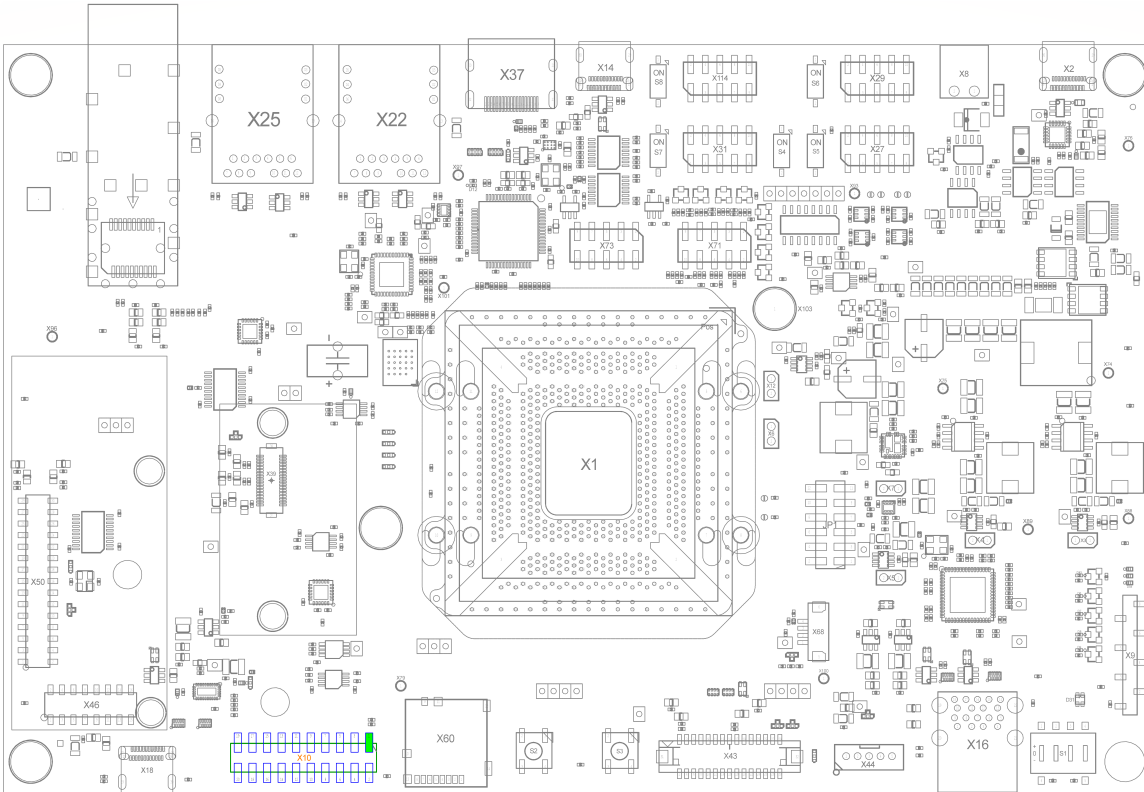
Interface Pin #	Signal name	Signal Type	Signal Level	Description
37	GND	-	0.0 V	Ground
38	GND	-	0.0 V	Ground

TABLE 72: X68 Fan Pinout

Interface Pin #	Signal Name	Signal Type	Signal Level	Description
1	X_FAN_PWR	PWR_O	5.0 V	FAN power rail, choice to use 12 V or VDD_IN via J19
2	GND	-	0.0 V	Ground
3	X_FAN_FB	I	1.8 V	FAN feedback signal (2 pulses per revolution)
4	X_PWM_FAN	OD_O_PU	5.0 V	Open drain PWM out with pull-up to VDD_5V0
5	Pad1	-	0.0 V	Connected to Ground
6	Pad2	-	0.0 V	Connected to Ground

25.3.19 JTAG (X10)

FIGURE 29: JTAG (X10)



The Libra Development Board provides a 2x10 2.54mm pin-header for JTAG connectivity. 1.8 V are available at the connector directly or with a 100R pull-up.

The JTAG connector X10 has the following pinout:

TABLE 73: X10 JTAG Connector Pinout

Interface Pin #	Signal Name	Signal Type	Signal Level	Description
1	Pull-up VDD_1V8	PWR_O	1.8 V	100 Ω pull-up to 1.8 V power rail
2	VDD_1V8	PWR_O	1.8 V	1.8 V power rail
3	X_JTAG_TRST	I	1.8 V	Reset in signal
4	GND	-	0.0 V	Ground
5	X_JTAG_TDI	I	1.8 V	JTAG TDI
6	GND	-	0.0 V	Ground
7	X_JTAG_TMS	I	1.8 V	JTAG TMS
8	GND	-	0.0 V	Ground
9	X_JTAG_TCK	I	1.8 V	JTAG TCK
10	GND	-	0.0 V	Ground
11	X_JTAG_RTCK	I	1.8 V	JTAG Return Clock, no connect
12	GND	-	0.0 V	Ground

Interface Pin #	Signal Name	Signal Type	Signal Level	Description
13	X_JTAG_TDO	O	1.8 V	JTAG TDO
14	GND	-	0.0 V	Ground
15	X_nRESET_IN	I	1.8 V	Reset in signal
16	GND	-	0.0 V	Ground
17	NC	-	-	No connect
18	GND	-	0.0 V	Ground
19	NC	-	-	No connect
20	GND	-	0.0 V	Ground

25.3.20 On-board Functionalities

25.3.20.1 Multicolor (RGB) LED (D31)

The Libra Development Board provides one multicolor (RGB) LED (D31). The LED is connected to an LED driver PCA9633TK controlled by the I2C3 bus. The location for D31 can be found in [LEDs](#).

25.3.20.2 Factory EEPROM (U57)

The Libra Development Board provides a 2 kbit EEPROM (ST M24C02-RMC6TG) for factory data. It is connected to the I2C3 bus. The EEPROM's write protection pin is connected to TP60. Write protection can be enabled by mounting R333 (10k) pull-up resistor. In this case, the EEPROM can be written if TP60 is tied to Ground only. The EEPROM I²C address can be fully customized by jumpers J21, 22, and 23. The default address is 0x51.

25.3.20.3 User EEPROM (U80)

The Libra Development Board provides a 2 kbit EEPROM (ST M24C02-RMC6TG) for general use. It is connected to the I2C3 bus. The EEPROM's write protection pin is connected to TP112. Write protection can be enabled by mounting R486 (10k) pull-up resistor. In this case, the EEPROM can be written if TP112 is tied to Ground only. The EEPROM I²C address can be fully customized by jumpers J21, 22, and 23. The default address is 0x52.

25.3.20.4 Quad SPI NOR (U62)

The Libra Development Board features a 512MBit Quad SPI NOR at U62.

25.3.20.5 ADC (X73)

The Libra Development Board features 8 analog to digital channels depending on the mounted phyFLEX SOM. The inputs are used to measure carrier board voltages and currents. Maximum input voltage is 1.8 V. All input signals are available at 2.54mm pin-header X73 with the following pinout:

TABLE 74: X73 ADC

Interface Pin #	Signal Name	Signal Type	Signal Level	Description
1	VDD_1V8	PWR_O	1.8 V	1.8 V power rail
2	GND	-	0.0 V	Ground
3	ADC_AIN0	I	0.0 - 1.8 V	Analog input channel 0 - used for VDD_SOM current
4	ADC_AIN1	I	0.0 - 1.8 V	Analog input channel 1 - used for VDD_SOM voltage
5	ADC_AIN2	I	0.0 - 1.8 V	Analog input channel 2 - used for VDD_5V0 current
6	ADC_AIN3	I	0.0 - 1.8 V	Analog input channel 3 - used for VDD_5V0 voltage
7	ADC_AIN4	I	0.0 - 1.8 V	Analog input channel 4 - used for VDD_3V3 current
8	ADC_AIN5	I	0.0 - 1.8 V	Analog input channel 5 - used for VDD_3V3 voltage
9	ADC_AIN6	I	0.0 - 1.8 V	Analog input channel 6 - used for VDD_1V8 current
10	ADC_AIN7	I	0.0 - 1.8 V	Analog input channel 7 - used for VDD_1V8 voltage

25.3.20.6 SPI ADC (X71)

The Libra Development Board comes with an SPI-ADC U61 (MCP3208-BI/SL) with 8 channels, which are connected to carrier board current and voltage measurement devices. This SPI-ADC serves as a comparison between itself and the on-board ADC, which is available depending on the mounted phyFLEX SOM. The SPI-ADCs maximum voltage is 5.0 V and the conversion method is SAR with a depth of 12 Bit. The SPI-ADC is connected to the SPI1 interface. The following table shows the pinout of pin-header X71 where all SPI-ADC input signals are available.

TABLE 75: X71 SPI-ADC

Interface Pin #	Signal Name	Signal Type	Signal Level	Description
1	VDD_5V0_REF	PWR_O	5.0 V	5.0 V reference voltage derived from precision voltage reference U78
2	GND	-	0.0 V	Ground
3	SPI_ADC_AIN0	I	0.0 - 5.0 V	Analog input channel 0 - used for VDD_SOM current
4	SPI_ADC_AIN1	I	0.0 - 5.0 V	Analog input channel 1 - used for VDD_SOM voltage
5	SPI_ADC_AIN2	I	0.0 - 5.0 V	Analog input channel 2 - used for VDD_5V0 current
6	SPI_ADC_AIN3	I	0.0 - 5.0 V	Analog input channel 3 - used for VDD_5V0 voltage
7	SPI_ADC_AIN4	I	0.0 - 5.0 V	Analog input channel 4 - used for VDD_3V3 current
8	SPI_ADC_AIN5	I	0.0 - 5.0 V	Analog input channel 5 - used for VDD_3V3 voltage
9	SPI_ADC_AIN6	I	0.0 - 5.0 V	Analog input channel 6 - used for VDD_1V8 current
10	SPI_ADC_AIN7	I	0.0 - 5.0 V	Analog input channel 7 - used for VDD_1V8 voltage

25.3.20.7 Temperature sensor (U56)

The Libra Development Board is equipped with a P3T1750DPZ I3C temperature sensor connected to I2C5. I2C address is 0x4F, I3C provisional ID is 0x9E.

25.3.20.8 TPM (U79)

The Libra Development Board features a Trusted Platform Module SLB9670. It is connected to SPI2 and offers TPM 2.0 functionality.

25.3.20.9 Peripheral current measurement (U5/U7/U9)

The Libra Development Board is equipped with current sensing devices which translate the momentary current load through a measurement resistor into a voltage value. This voltage value then can be interpreted by the phyFLEX SOM on-board ADC or the carrier board SPI-ADC or both at the same time. The current measurement ICs used are INA241A4QDDFRQ1 with a 0.004R 1% shunt resistor. The applicable gain factor is 100V/V. Which current measurement IC is connected to which ADC channel can be obtained from the section of the applicable ADC in this manual.

25.3.20.10 Global Board Reset (X_nRESET_OUT)

The X_nRESET_OUT signal (X_POR_B at phyFLEX FPSC SoM) is used to hold all devices with an external reset pin in the reset state. X_nRESET_OUT will be released after all board voltages are powered up and allows the phyFLEX FPSC SoM to boot. X_nRESET_OUT is brought out at several connectors.

X_nRESET_OUT Design Considerations

Note that there is a 10 kOhms pull-up resistor on the phyFLEX FPSC SoM VDD_IO voltage. It is recommended to use this signal as an open drain.

25.3.20.11 On-board Power Supplies

The Libra Development Board provides supply voltages on several connectors to power external devices. Be sure not to exceed the maximum permissible current that can be drawn from each power domain. In the table below, each source is listed with the location where a voltage connected to the source can be found:

TABLE 76: Onboard Power Supplies

Voltage Domain	Locations	Max. recommended additional current
VDD_IN	TP1, X39(VDD_IN_MIPI), X46(VDD_IN_AV), X117	Depends on used input power supply connected to the carrier board
VDD_12V0	TP3, X44(VDD_12V0_LVDS1), X117	TBD
VDD_SOM	TP4	TBD

Voltage Domain	Locations	Max. recommended additional current
VDD_5V0	TP6, X39(VDD_5V0_MIPI_DSI), X43(VDD_5V0_LVDS1), X50(VDD_5V0_AV), X117	TBD
VDD_3V3	TP7, X39(VDD_3V3_MIPI_DSI), X43(VDD_3V3_LVDS1), X50(VDD_3V3_AV), X52, X54, X114	TBD
VDD_3V3_OUT	X6	200 mA
VDD_1V8	TP8, X9, X10, X114	200 mA (derived from VDD_1V8_OUT, currents from both cannot exceed 200 mA cumulatively)
VDD_1V8_OUT	X7	200 mA

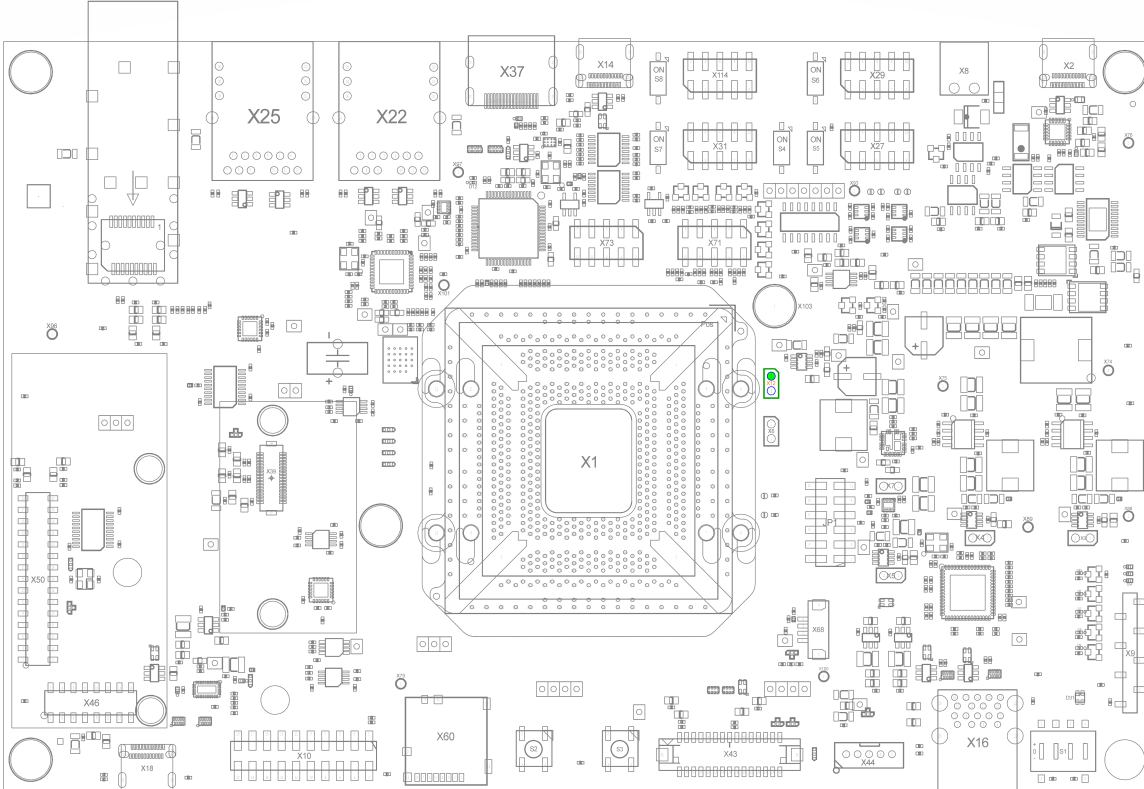
In addition to these currents, Libra Development Board delivers current for USB_VBUS of X16/X18 (3x 900 mA), phyCAM-M Interfaces (2x 1500 mA 3.3 V or 5 V depending on VCC_SELECT pin), HDMI connector (150 mA).

 **Warning**

Drawing current may result in heating of the voltage regulator components and might require additional heat sinking.

25.3.20.12 On-board Measurement of SoM Power Consumption

FIGURE 30: SoM Input Current Amp Header (X12)



The input current of the SoM supply rail VDD_SOM can be measured on board to determine the power consumption of the SOM. A current sense amplifier translates the supply current into a proportional voltage VOUT_CC_SOM, which can be measured at X12 (on PCB top side) and X12 (on PCB bottom side). The mounted amplifier features a gain of 100V/V. The SoM input current I_{SOM_IN} in Ampere is determined by inserting VOUT_CC_SOM into the following equation.

Subsequently, the SoM input power may be derived from I_{SOM_IN} and VOUT_CC_SOM using the following formula:

For example, measuring 400 mV at X12, the input current will be 1 A. With a SoM input voltage of 5.0 V, the input P_{SOM_IN} is 5 W.

25.3.21 Switches

The Libra Development Board has several switches and buttons for various uses. The locations for all switches can be found in [Switches and Buttons](#).

25.3.21.1 System Reset Button (S2)

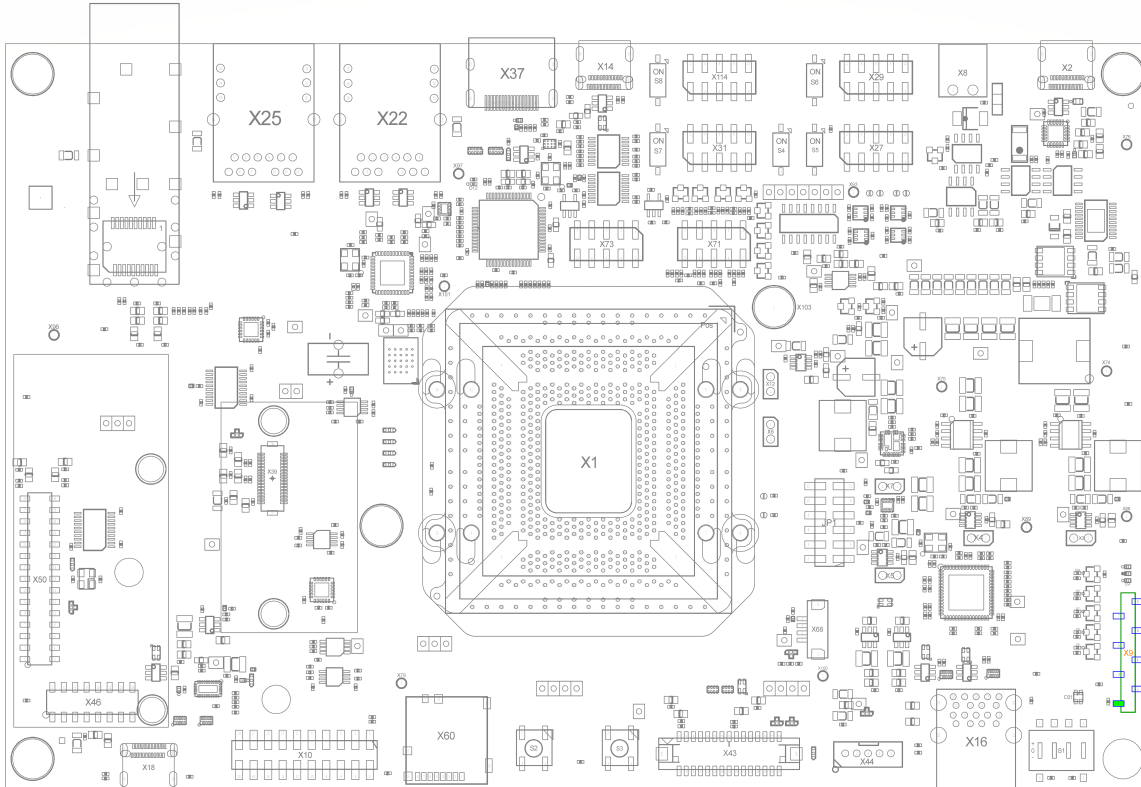
The Libra Development Board is equipped with a system reset button at S2. Pressing this button will assert reset through a voltage supervisor U11 that will pull the X_nRESET_IN pin (X1 Pin Y21) of the phyFLEX FPSC SoM low, causing the module to reset with a complete power cycle.

25.3.21.2 System ON/OFF Button (S3)

The Libra Development Board is equipped with an ON/OFF button at S3 and is connected to X_ONOFF of the phyFLEX FPSC SoM. For more information, refer to the applicable CPU's *Reference Manual*.

25.3.21.3 Boot Switch (S1)

FIGURE 31: Boot Header (X9)



The Libra Development Board features a tri-state boot switch with four individually switchable ports to select the phyFLEX FPSC SoM default bootsource. The Boot_Mode signals may also be accessed through pin header X9 or USB to UART/GPIO converter U15. Descriptions of the various boot modes can be found in [Boot Mode Selection](#). The available boot options differ depending on the mounted phyFLEX SoM. All available options are displayed in the table below. Default boot modes are marked **blue**, the phyFLEX SOM will boot default when no boot mode alteration is engaged:

TABLE 77: Boot Mode Legend

Boot Mode Designation	
1	High
0	Low
X	Don't care

Boot Switch Designation	
1	Pull-up
0	Pull-down
-	Middle setting, open

TABLE 78: phyFLEX-i.MX 8MP FPSC Boot Modes

Mounted SoM	Boot Target	Memory/Target Location	BOOT_MODE				S1 Switch Number			
			3	2	1	0	4	3	2	1
PFL-G-01 (phyFLEX-i.MX 8MP FPSC)	eMMC (SoM default)	SOM	0	0	1	0	-	-	-	-
	SD-Card	Carrier Board	0	0	1	1	-	-	-	1
	QSPI NOR	Carrier Board	0	1	1	0	-	1	-	-
	USB1 serial downloader	SOM	0	0	0	1	-	-	0	1
	Fuse boot	SOM	0	0	0	0	-	-	0	-
	JTAG mode	SOM	1	1	1	1	1	1	-	1

TABLE 79: phyFLEX-i.MX 95 FPSC Boot Modes

Mounted SoM	Boot Target	Memory/Target Location	BOOT_MODE				S1 Switch Number			
			3	2	1	0	4	3	2	1
PFL-G-02 (phyFLEX-i.MX 95 FPSC)	eMMC (SoM default)	SOM	1	0	1	0	-	-	-	-
	SD-Card	Carrier Board	1	0	1	1	-	-	-	1
	QSPI NOR	Carrier Board	1	1	0	0	-	1	0	-
	USB1 serial downloader	SOM	1	0	0	1	-	-	0	1
	Fuse boot	SOM	1	0	0	0	-	-	0	-

TABLE 80: phyFLEX-AM62L FPSC Boot Modes

Mounted SoM	Boot Target	Memory/Target Location	BOOT_MODE				S1 Switch Number			
			3	2	1	0	4	3	2	1
PFL-G-03 (phyFLEX-AM62L FPSC)	MMC0 eMMC FS (SOM default)	SOM	1	0	1	1	-	-	-	-
	USB0 Host MSC	SOM	0	1	1	1	0	1	-	-
	MMC0 eMMC FS	SOM	1	0	0	0	-	-	0	0
	FSS0 QSPI CS0	Carrier Board	1	0	0	1	-	-	0	-
	MMC1 4b UDA FS	SOM	1	0	1	1	-	-	-	-
	DEVBOOT	SOM	0	1	1	0	0	1	-	0
	FSS0 Serial NAND		1	1	0	0	-	1	0	0
	FSS0 xSPI SFDP		1	1	0	1	-	1	0	-
	EXT. HOST UART0		1	1	1	0	-	1	-	0
	EXT. HOST USB0 DFU		1	1	1	1	-	1	-	-

TABLE 81: phyFLEX-STM32MP2 FPSC Boot Modes

Mounted SoM	Boot Target	Memory/Target Location	BOOT_MODE				S1 Switch Number			
			3	2	1	0	4	3	2	1
PFL-G-04 (phyFLEX-STM32MP2 FPSC)	eMMC (SoM default)	SOM	0	0	1	0	-	-	-	-
	UART and USB	SOM	0	0	0	0	-	-	0	-
	SD-Card	Carrier Board	0	0	0	1	-	-	0	1
	Development	SOM	0	0	1	1	-	-	-	1
	QSPI NOR	Carrier Board	0	1	0	0	-	1	0	-

TABLE 82: phyFLEX-i.MX 93 FPSC Boot Modes

Mounted SoM	Boot Target	Memory/Target Location	BOOT_MODE				S1 Switch Number			
			3	2	1	0	4	3	2	1
PFL-G-05 (phyFLEX-i.MX 93 FPSC) A55 boot	eMMC (SoM default)	SOM	0	0	1	0	-	-	-	-
	USB1 serial downloader	SOM	0	0	0	1	0	-	0	1
	Fuse boot	SOM	X	0	0	0	-	-	0	-
	SD-Card	Carrier Board	0	0	1	1	0	-	-	1
	QSPI NOR	Carrier Board	0	1	0	0	0	1	0	-

Mounted SoM	Boot Target	Memory/Target Location	BOOT_MODE				S1 Switch Number			
			3	2	1	0	4	3	2	1
PFL-G-05 (phyFLEX-i.MX 93 FPSC) M33 boot	eMMC	SOM	1	0	1	0	1	-	-	-
	USB1 serial downloader	SOM	1	0	0	1	1	-	0	1
	Fuse boot	SOM	X	0	0	0	-	-	0	-
	SD-Card	Carrier Board	1	0	1	1	1	-	-	1
	QSPI NOR	Carrier Board	1	1	0	0	1	1	0	-

COMING SOON!

phyFLEX-AM62Px FPSC Boot Modes

TABLE 83: Boot Mode Configuration Header Pinout (X9)

Interface Pin #	Signal Name	Signal Type	Signal Level	Description
1	VDD_1V8	PWR_O	1.8 V	1.8 V power rail
2	X_BOOT_MODE0	I	1.8 V	Boot mode 0 configuration signal
3	X_BOOT_MODE1	I	1.8 V	Boot mode 1 configuration signal
4	X_BOOT_MODE2	I	1.8 V	Boot mode 2 configuration signal
5	X_BOOT_MODE3	I	1.8 V	Boot mode 3 configuration signal
6	X_nRESET_IN	I	1.8 V	Reset in signal
7	NC	-	-	No connect
8	GND	-	0.0 V	Ground

Boot Mode Design Considerations

Bootpin voltages should be valid when X_POR_B (X_nRESET_IN at Libra Development Board) is released.

26 Additional System-Level Hardware Information

26.1 I2C Connectivity

The I2C1 interface of the phyFLEX FPSC SoM is not connected to the Libra Development Board. The table below lists the connectors and pins with I2C connectivity and on-board devices. The I²C addresses are hexadecimal in 7-bit representation of the default Linux representation.

TABLE 84: I2C2 Connectivity

I2C2 Interface	Location and/or Address
STUSB4500QTR	U1 - 0x28
M.2 Key-M	X54
Factory EEPROM	U57 - 0x51
User EEPROM	U80 - 0x52
TCAL6416RTW	U58 - 0x21
phyCAM-M CSI2 VM-016	X34 - 0x18, 0x57
phyCAM-M CSI2 VM-017	X34 - 0x37, 0x57
phyCAM-M CSI2 VM-020	X34 - 0x18, 0x57
MIPI-DSI / PEB-AV-12	X39 - 0x10, 0x24, 0x2C, 0xE

TABLE 85: I2C3 Connectivity

I2C3 Interface	Location or Address
TUSB8042A	U21 - 0x44
phyCAM-M CSI1 VM-016	X32 - 0x10, 0x56
phyCAM-M CSI1 VM-017	X32 - 0x36, 0x56
phyCAM-M CSI1 VM-020	X32 - 0x10, 0x56
LVDS1 Connector	X43; connecting jumpers are not mounted by default
M.2 Key-E	X52

I2C3 Interface	Location or Address
PCA9533/01	U55 - 0x62
TCAL6416RTW	U72 - 0x21
HD3SS3220I	U66 - 0x47
PEB-AV-10 LVDS2	X50 - 0x18, 0x57, 0x5F
PEB-AV-13 LVDS2	X50 - 0x34

TABLE 86: I2C4 Connectivity

I2C4 Interface	Location or Address
SFP+	X113 - 0xA0, 0xA2

TABLE 87: I2C5 Connectivity

I2C5 Interface	Location or Address
P3T1750DPZ I2C	U56 - 0x4F
P3T1750DPZ I3C	U56 - 0x9E

To avoid conflicts when connecting external I2C devices to the Libra Development Board, the addresses of the onboard I2C devices must be considered. The table below lists the addresses already in use; the default address is printed in bold. The I²C addresses are hexadecimal in 7-bit representation, which is the default Linux representation.

TABLE 88: Reserved I2C Addresses

Bus	Connector	Prod. No.	Addresses
I2C3	phyCAM-M CSI1 Connector X32	VM-016-xxx-M	0x10 , 0x18
		VM-017-xxx-M	0x36 , 0x37
		VM-117-xxx-M	0x36 , 0x37
		VM-017-xxx-L	0x36 , 0x37, 0x18
		VZ-018	0x3D , 0x38
I2C4	phyCAM-M CSI1 Connector X34	VM-016-xxx-M	0x10 , 0x18
		VM-017-xxx-M	0x36 , 0x37

Bus	Connector	Prod. No.	Addresses
		VM-117-xxx-M	0x36 , 0x37
		VM-017-xxx-L	0x36 , 0x37, 0x18
		VZ-018	0x3D , 0x38

The Libra Development Board

27 Revision History

Date	Version #	Changes in this manual
01.12.2025	L-1087e.A0	Preliminary Manual Describes the phyFLEX-STM32MP2x FPSC SOM Version: 1633.0 Libra Development Board PCB Version: 1618.2
11.03.2026	L-1087e.A1	Corrected CAM info Updated Formatting

28 Contact Information

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